

OL2381

Highly integrated single-chip sub 1 GHz RF transceiver

Rev. 1 — 30 November 2011

Product data sheet

1. General description

A highly integrated single-chip transceiver solution, the OL2381 is ideally suited to telemetry applications operating in the ISM/SRD bands. The small form factor, low power consumption and wide supply voltage range make this device suitable for use in battery powered, handheld devices and their counter parts.

The device utilizes a fully integrated, programmable fractional-N PLL (including loop filter) to control the Local Oscillator (LO), thus supporting multi-channel operation and frequency hopping schemes. This feature also allows programmable frequency steps for crystal (XTAL) drift compensation.

The device can employ ASK, FSK or GFSK type modulation. The ASK modulation characteristics are fully programmable by varying the power amplifier output power in accordance with the TX data. The FSK modulation utilizes the fractional-N PLL capability to precisely modulate the LO frequency with the TX data (in loop modulation). Relaxed narrow band applications can utilize an on-chip GFSK type modulation to improve the spectral occupancy.

The device is based on a low IF direct conversion receiver architecture, with on-chip IF filtering and programmable channel bandwidth. After filtering and amplification the quadrature signals are digitized, demodulated and processed in the digital domain.

Baseband processing of the received signal comprises a demodulator, a data-slicer and clock recovery followed by a Manchester decoder. Automated signal signature recognition units are available to allow simple, fast and reliable data reception.

The device is controlled via a three-wire serial interface (SPI) with data input and output, data clock and interface enable. The interface can be configured to a full SPI interface with separate data and clock pins. Additional pins are available to access internal signals in real-time.

2. Features and benefits

- Highly integrated solution for the 315/434/868/915 MHz band
- Very few external components required
- Complies with ETSI EN300-220/FCC part 15 standards
- Near zero-IF RX architecture
- On-chip channel filtering with automatic calibration supported to provide stable cut-off frequencies and filter roll-off
- Multi-channel TX and RX operation by fully integrated fractional-N PLL with on-chip loop filter



- Automatic VCO sub-band selection and calibration to reduce PLL loop bandwidth variation
- Programmable ASK/FSK modulation with Manchester codec
- Programmable transmitter output power (–20 dBm to +10 dBm), stabilized with onboard PA regulator
- Digital RSSI with a configurable threshold
- Onboard Signal Signature Recognition Unit (SSRU) with Preamble Pattern Recognition (PPR)
- Configurable RX polling timer with 2 % absolute accuracy
- Level Sensitive Data (LSD) slicer with self-adjusting threshold
- Low power consumption (RX 16 mA, TX 13 mA at 6 dBm), with ultra Low 0.5 μ A standby current and configurable polling timer
- Single lithium cell operation (2.1 V). Operation up to 3.6 V fully supported
- 32-Pin HVQFN32 Pb-free package

3. Applications

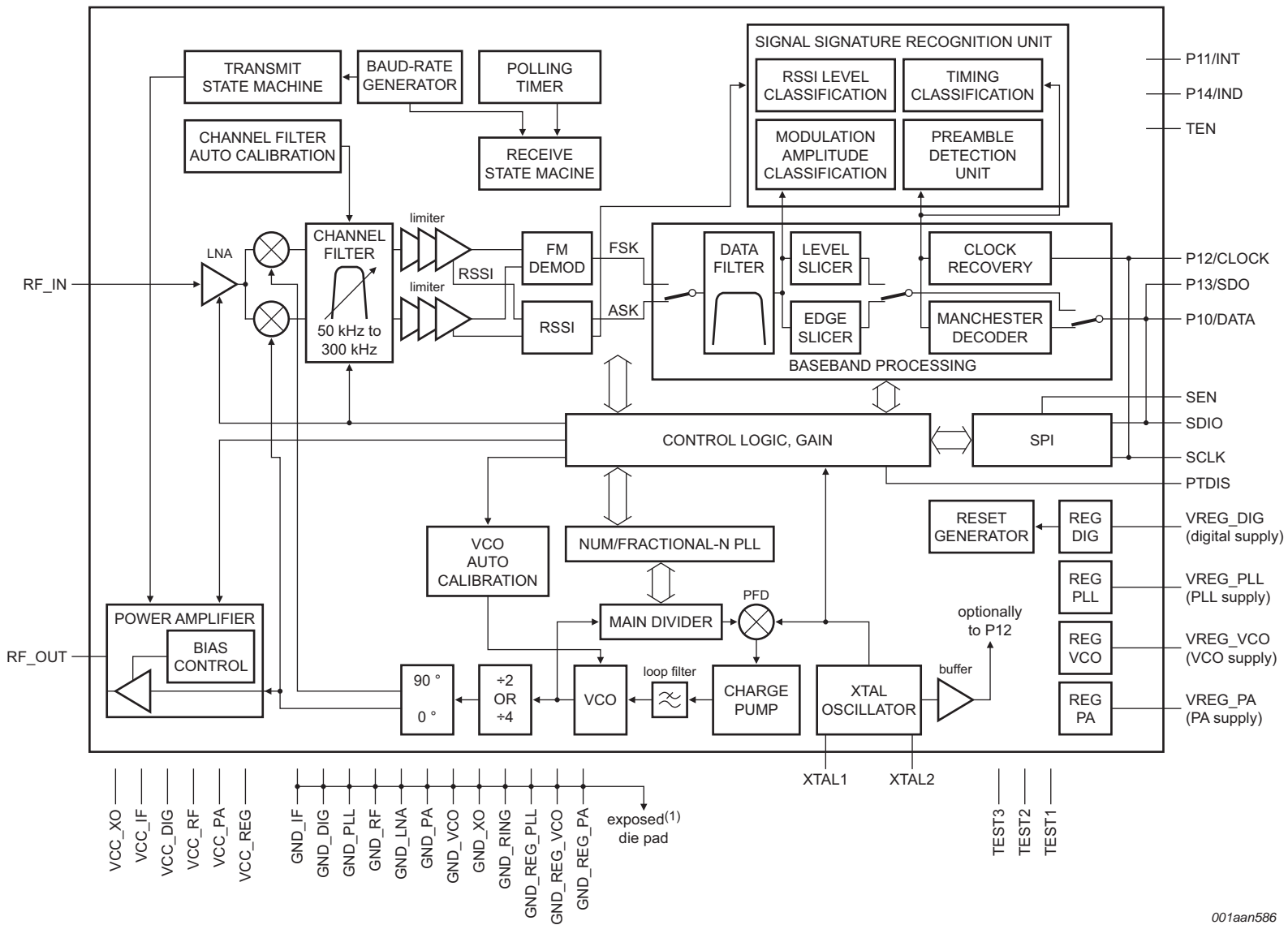
- Smart metering (wireless M-bus)
- Home and building security and automation (KNX-RF)
- Remote control devices
- After-market Remote Keyless Entry (RKE)
- Wireless medical applications
- Wireless sensor network

4. Ordering information

Table 1. Ordering information

Type number	Package		Version
	Name	Description	
OL2381AHN	HVQFN32	plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 × 5 × 0.85 mm	SOT617-3

5. Block diagram



001aan586

(1) All internal domain grounds including external GND pins 1, 8, 9, 16 and 32 are connected to the exposed die pad.

Fig 1. Block diagram

6. Pinning information

6.1 Pinning

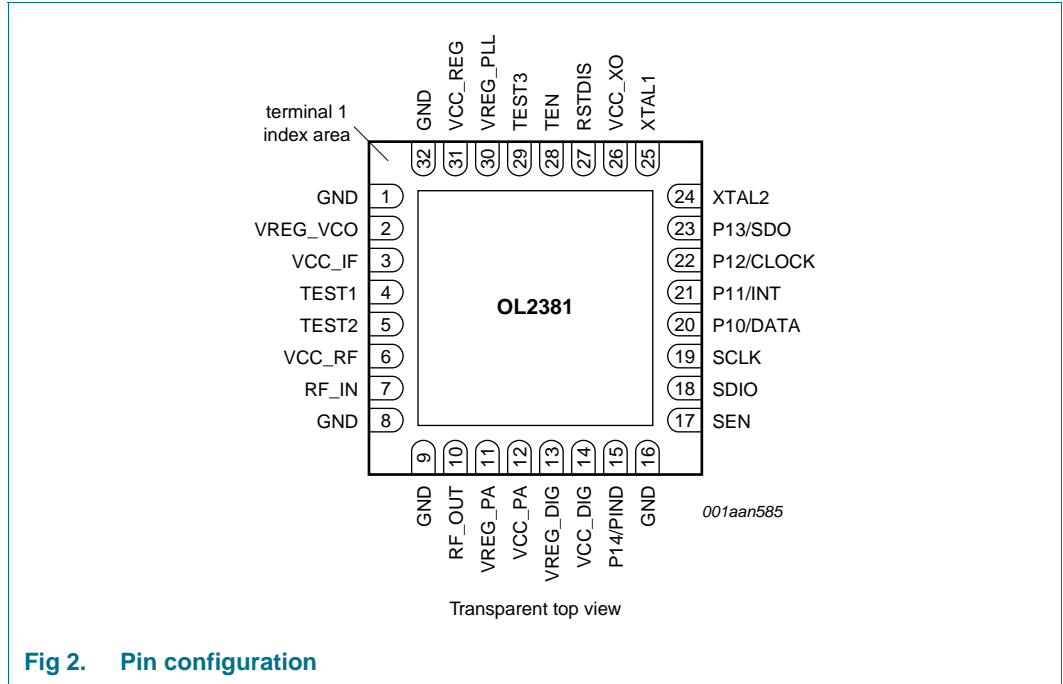


Fig 2. Pin configuration

6.2 Pin description

Table 2. Pin description

Symbol	Pin	Type	Reset state	Description
GND	1	-	-	ground; use exposed heatsink as ground reference
VREG_VCO	2	A	Z	VCO regulator output voltage to decoupling capacitor
VCC_IF	3	A	A	IF section power supply
TEST1	4	A	Z	RX test I output
TEST2	5	A	Z	RX test Q output
VCC_RF	6	A	A	LNA power supply
RF_IN	7	A	A	RX RF signal input
GND	8	-	-	ground; use exposed heatsink as ground reference
GND	9	-	-	ground; use exposed heatsink as ground reference
RF_OUT	10	A	Z	TX RF signal output
VREG_PA	11	A	Z	power amplifier regulator output voltage to decoupling capacitor
VCC_PA	12	A	A	power amplifier power supply
VREG_DIG	13	A	A	digital regulator output voltage to decoupling capacitor
VCC_DIG	14	A	A	digital module supply voltage
P14/PIND	15	DO	Z	digital output port with increased drive capability for PIN diode control

Table 2. Pin description ...continued

Symbol	Pin	Type	Reset state	Description
GND	16	-	-	ground; use exposed heatsink as ground reference
SEN	17	DI	DI	serial interface enable
SDIO	18	DIO	DI	serial interface input/output
SCLK	19	DIO	DI	serial interface clock
P10/DATA	20	DleO	Z	digital output port, TX data input, RX data output, data output of debug interface
P11/INT	21	DO	POR, interrupt output	digital output port, interrupt output, several status indicators, reference clock output, frame indicator of debug interface
P12/CLOCK	22	DO	1 MHz reference clock	digital output port, TX/reference clock out, RX data clock, clock of debug interface
P13/SDO	23	DO	Z	digital output port, status indicators, serial interface data output
XTAL2	24	A	A	crystal reference clock frequency input
XTAL1	25	A	A	crystal connection
VCC_XO	26	A	A	crystal oscillator supply voltage
RSTDIS	27	DI	DI	reset disable signal
TEN	28	DI	DI	test enable input
TEST3	29	A	Z	PLL test output
VREG_PLL	30	A	Z	PLL regulator output voltage to decoupling capacitor
VCC_REG	31	A	A	PLL, VCO regulators power supply
GND	32	-	-	ground; use exposed heatsink as ground reference
exposed die pad	-	A	GND	ground connection

- [1] A = analog.
 DI = digital input.
 DO = digital output with enable signal.
 DIO = digital input without enable signal and output with enable signal.
 DleO = digital input and output both with enable signal.

7. Functional description

7.1 General architecture description

The OL2381 transceiver is designed for use in both complex base-stations, when paired with powerful microcontrollers, and low component-count remote units with low pin-count microcontrollers. The IC features unique configuration possibilities via external pin-level configuration or SFR bit manipulation. Several automatic sequences are implemented to ease device operation, all of which can be manually influenced or overridden by control-bits.

7.1.1 Power management

The device contains a configurable power-on reset block. The device control registers are reset as the external voltage rises to ensure that the device state is in Standby mode. This is implemented by ensuring that all blocks are off except the SPI and the digital regulator. Note that the digital regulator is operating in clamp mode at this time.

7.1.2 XTAL oscillator

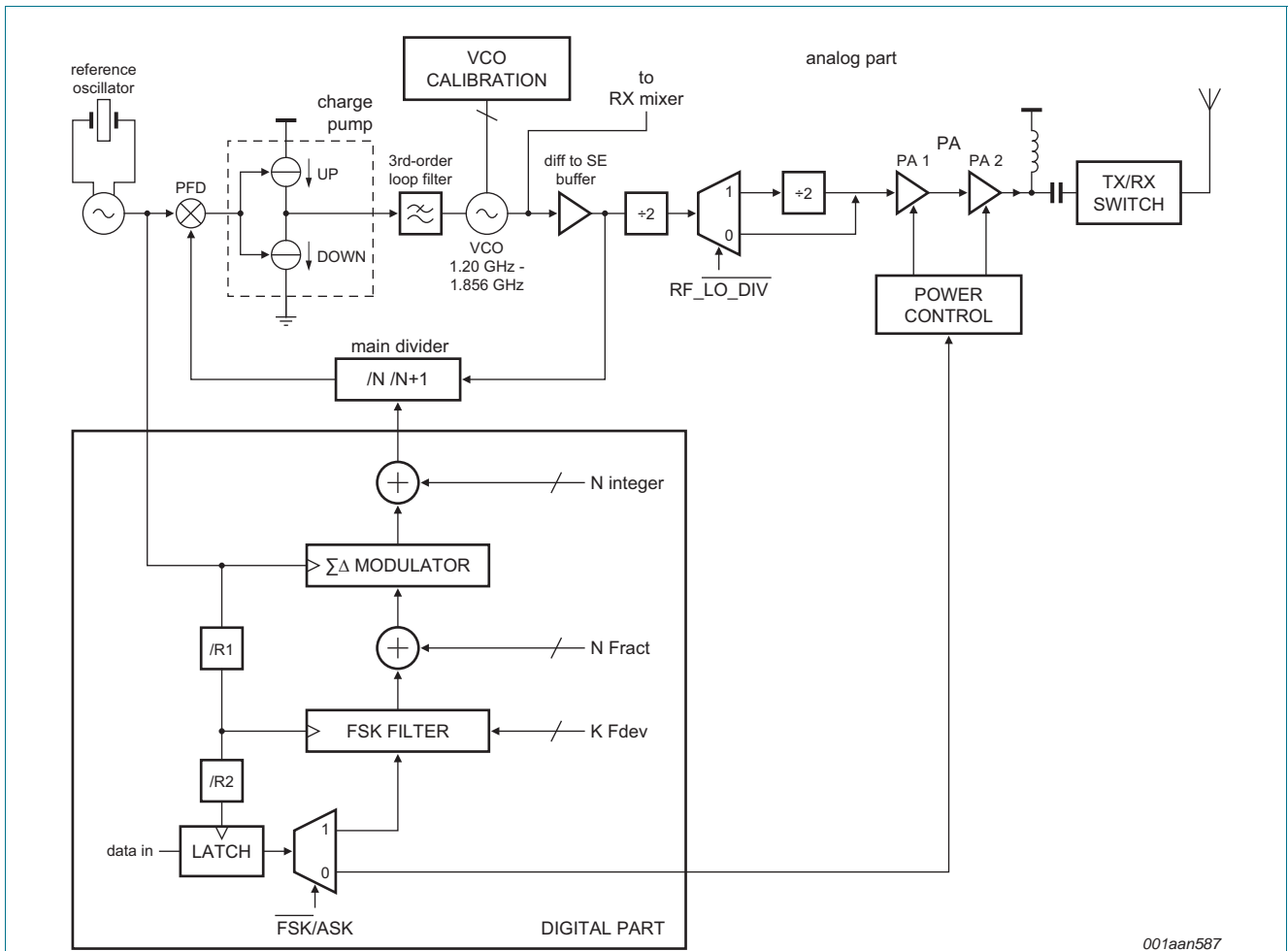
The main time-reference is derived from an amplitude-controlled XTAL oscillator. This 16 MHz reference is used as a reference clock for the PLL and as a timing reference for various analog calibration purposes.

7.1.3 Polling timer

Several base-station applications require a low-power polling timer for periodic device wakeup. This feature is essential to enable listening in pre-programmed time-windows when the OL2381 is used in RX mode applications. Internal configuration and trimming registers allow the setting of a wide range of different timer intervals while achieving an average timing accuracy of 2 %.

7.1.4 TX block

The TX section is able to operate within all ISM bands: 315 MHz, 434 MHz, 868 MHz and 916 MHz. The device provides a high degree of flexibility and is capable of ASK/FSK modulation, output power control and on-chip baud-rate generation with data rates up to 112 kchip/s. The device features multi-channel operation and enables carrier frequency adjustment and compensation of XTAL frequency offsets due to its high resolution fractional-N PLL architecture. The TX block features a high degree of integration, employing an on-chip VCO and PLL loop filter.



001aan587

Fig 3. TX block diagram

7.1.5 VCO calibration

On-chip calibration is available to reduce the VCO input voltage range and thus reduce the PLL loop bandwidth variation. The variation in system parameters such as locking time and LO phase noise can therefore be maintained within a tight window.

Calibration is performed by selecting the proper VCO sub-band according to the desired channel frequency. VCO sub-band selection and the PLL start-up sequence can be triggered by command and are supported by an automatic flow sequence. This flow can be overridden if required. Note that if the incorrect sub-band is chosen the VCO calibration is unable to tune to the desired frequency.

7.1.6 TX command

TX parameters (frequency, modulation, output power etc) can be predefined to enable fast and simple entry into TX mode (PA switched on).

7.1.7 RX block

The OL2381's RX path consists of a broadband resistive-feedback LNA, a mixer (mixing down the input signal to an IF of 300 kHz), a channel-filter, a limiter, an RSSI stage (AM demodulation) and a base-band signal processing block used for FM and AM data and clock recovery. The LNA, limiter and channel-filter gain settings can be configured via control bits. The channel filter bandwidth can also be adapted.

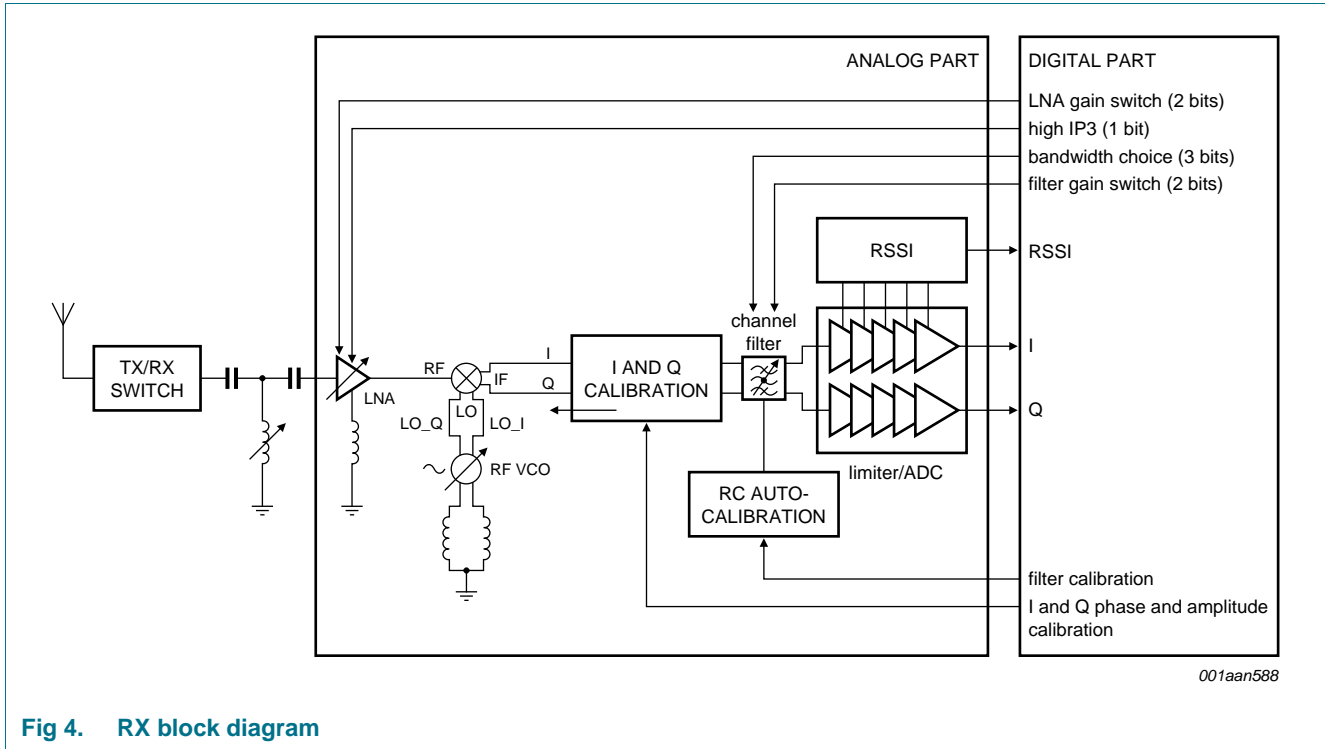


Fig 4. RX block diagram

7.1.8 Channel filter auto-calibration

Channel bandwidth accuracy requirements vary between applications. The modulation bandwidth changes with different bit rates. Bit rates can be 0.5 kbit/s to 112 kchip/s and the IF channel filter bandwidth must be set accordingly in the range 50 kHz to 300 kHz.

Channel bandwidth auto-calibration is implemented to maintain constant performance. This ensures stable cut-off frequencies and filter roll-off over process and temperature variations. This calibration is included in the RX command.

7.1.9 I/Q calibration

I/Q calibration can be implemented to improve the channel image rejection for certain applications. This calibration improves amplitude mismatch and phase quadrature between I and Q signals.

Both parameters can be trimmed by injecting an external RF signal operating in the image channel. The RSSI can then be used to determine the optimum settings to have the minimal remaining signal. This calibration is required for each frequency band.

The I/Q calibration settings are made available to -, and must be stored by, an external microcontroller.

7.1.10 Receive command

The predefined set of RX parameters (center frequency, modulation, etc.) enables Receive mode (receiver and LO buffers switched on) to be entered quickly after receiving the RX command. Several methods of signal signature recognition are implemented. These modes of semi-automatic signal processing can be pre-selected by the RX command.

7.1.11 Signal signature recognition unit

Several signal recognition units are implemented to provide fast and accurate signal detection. Signal signatures such as signal level (RSSI), modulation depth or baud-rate and coding can be automatically detected as wakeup criteria during the wakeup search phase.

7.1.12 Preamble detection

A configurable 1-bit to 32-bit pattern recognition unit can be implemented to aid power saving and avoid unintended wakeup due to ambient noise.

7.2 General operation

The OL2381 is a state machine-based transceiver to be used in conjunction with a microcontroller. Study this datasheet carefully to help choose the appropriate OL2381 configuration for a specific application. The interface to the microcontroller must be defined first, see [Section 7.3](#). Next, the correct basic settings must be identified. The operational frequency band must be chosen, all relevant registers must be programmed for TX and RX modes (exact setting of desired frequency, modulation, modulation depth, IF bandwidth, baseband filtering, etc). It is strongly recommended to study every aspect of this datasheet in detail and to verify correct device operation by measuring available debug-signals. The optimum operation and the highest device performance is achieved by fine-tuning and verification of all device settings. Use the automatic operating sequences after determining the optimum device configuration. Generally, the first operation is to bring the device from standby to power-up state, which is the precondition for any operation. This can be done manually, triggered by the external microcontroller, or automatically by the built-in polling timer. In this device mode, the XTAL oscillator is operational. SFR register bits (configuration data) can be changed. This mode can be left by issuing TX or RX commands. To save power and operating time the commands can be prepared by the 'prepare TX' or 'prepare RX' commands.

7.3 Interface description

7.3.1 Port connections

The minimum connection between a host controller and the OL2381 comprises three SPI lines: SDIO, SCLK and SEN. SPI communication and TX/RX data transfer can be achieved by multiplexing the SPI data and clock lines. The host controller's SPI must be set in slave mode after the RX/TX command is sent, the SCLK then shifts the out/in data via the host controller's SPI.

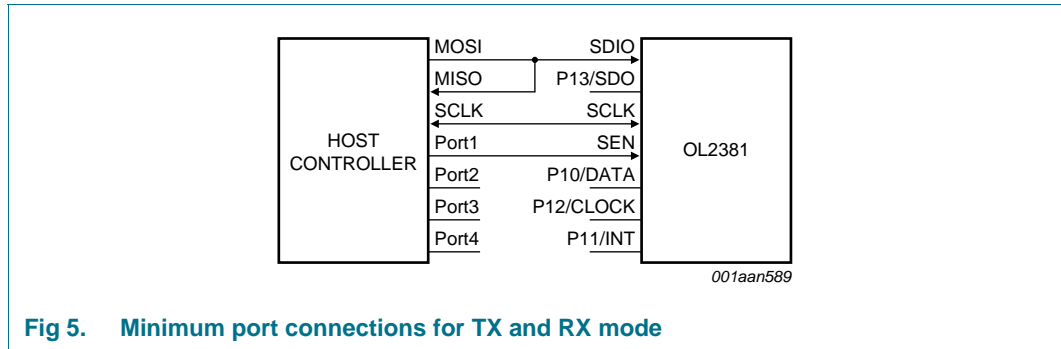


Fig 5. Minimum port connections for TX and RX mode

The device also supports full four-line SPI mode, the line SDIO serving as data input and P13/SDO as data output.

Alternatively, the device can be configured for separate data inputs and outputs. The lines SDIO, SCLK and, if selected, P13/SDO can be reserved for SPI command handling. In this case, TX and RX data is handled by the port pin P10/DATA, the clock is carried by port P12/CLOCK. The OL2381’s remaining ports can be used for additional status information.

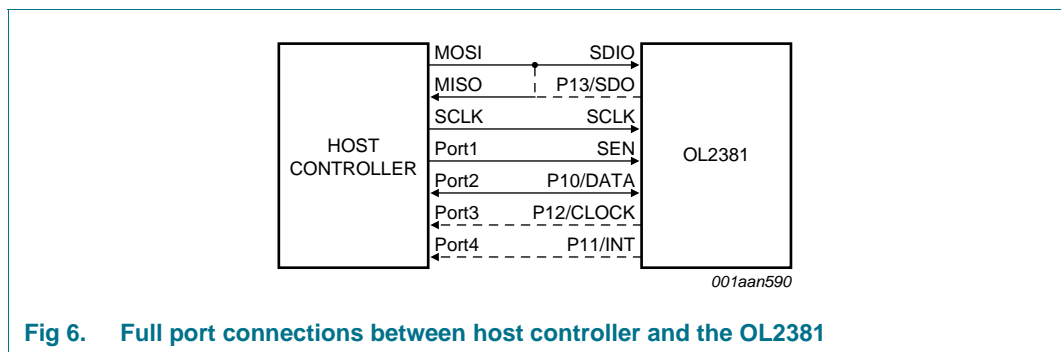


Fig 6. Full port connections between host controller and the OL2381

7.4 Special ports

7.4.1 TEN

The test enable input (pin TEN) must always be connected to GND. This pin is only required for a factory test and has no user-operable functionality.

7.4.2 TEST1, TEST2 and TEST3

Test pins for internal analog test-signals. In the application, these pins must be left open.

7.4.3 RSTDIS

The status of pin RSTDIS defines the polling timer state enable bit after power on. When the pin is LOW, the device is initialized with the polling timer enable bit set to 1.

7.5 General purpose ports

The device features five general purpose ports: P10 to P14, with selectable dedicated user functions; see [Section 7.8.3 “Reset and power mode register” on page 16](#). The port function is controlled by bits P1xCx. The width of these control bits for every port depends on the number of selectable signals.

All general purpose ports, except P11/INT and P12/CLOCK, are in 3-state after power-on reset. Port P11/INT is initialized as an output driving the active-LOW POR interrupt. Note that this interrupt is non-maskable.

Port P12/CLOCK is initialized to provide a 1 MHz reference clock as the default output.

7.5.1 P10/DATA

Priority of functions:

- Output signal of receiver debug interface
- RX data output, if bit SEP_RX_OUT is logic 1 and the receiver is activated

or

- TX data input when bit SEP_TX_LINES is logic 1 and the transmitter is activated

If register PORTCON2 bit SEP_TX_LINES is set and P12C[2:0] = 010b, the port delivers the TX clock as specified through register TXCON. This clock is activated after the TX command's ninth SCLK pulse and it runs until the power amplifier is turned off. This clock indicates the TX timing and informs the controller when the device samples the input data from the P10/DATA line.

If register PORTCON2 bit SEP_RX_OUT is set and if P12C[2:0] = 010b, the port delivers the RX clock associated with the data provided at P10/DATA. This clock is activated after the RX DATA command's ninth SCLK pulse. If the RX command is a PRDA, this clock is activated after successful preamble detection. In both cases the clock continues as long as the receiver state machine is in its DATA state. This clock is recovered from the RX signal timing and informs the controller when it can sample the data delivered at the P10/DATA line.

Note that in contrast to P10/DATA, where setting bit SEP_TX_LINES or bit SEP_RX_OUT overrules the normal port function, this is not the case for P12/CLOCK. The clock is only output if selected when P12C[2:0] = 010b.

Bit P10INV inverts output data, including RX data. If an inversion of TX data is desired, register TXCON's bit INV_TX_DATA must be used.

7.5.2 P11 and P12

P11 and P12 together with P10, form the serial interface when the receiver debug mode is activated; see [Section 7.41 "RX debug interface" on page 85](#).

7.5.3 P14

P14 can be used to control an external circuit, such as a TX/RX switch or an LNA.

7.6 Serial configuration interface description

7.6.1 General SPI information

The chip is configured via a three or 4 wire serial interface consisting of an 8-bit shift register and 80 × 8-bit registers holding the configuration data.

Data can be exchanged with multiple 8-bit frames (auto-incrementing) or in portions of 8 bits (1 byte), which provides an advantage when using a hardware SPI-interface. Data in the shift register is loaded into the addressed register on the last edge of SCLK within the last bit of the transferred byte.

7.6.2 SEN

A logic LOW applied to pin SEN disables the SPI interface. The internal state machine halts and every activity on pins SDIO and SCLK is ignored.

If the device is in Power-down mode, a positive edge on pin SEN activates the device. The crystal oscillator is always on, unless the device is in Power-down mode. The watchdog is cleared with a HIGH level on pin SEN; see [Section 7.11 “Watchdog” on page 25](#).

After the TX command, pin SEN has an additional function: At the falling edge of pin SEN the level on pin SDIO is latched and frozen.

7.6.3 SCLK

SCLK is the clock pin for the serial interface. Every edge of SCLK shifts data into or gets data from the SPI register-set. The second clock edge (SCLK) is used for data capturing. SDIO direction switching between input and output is accomplished with the first clock edge of the ninth bit. An additional clock edge is necessary at the start of a TX or RX command.

The clock polarity for an SPI command can be selected; see [Section 7.6.5](#).

If desired, pin SCLK can carry the baud-rate clock during a TX command and the recovered RX clock during a RX command.

7.6.4 SDIO

SDIO is the serial interface's bidirectional data input/output pin. Data in or data out operation is adapted automatically during SPI communication sequences.

If desired, pin SDIO can be used to input data if a TX command is executed or for RX data if a RX command is active.

7.6.5 General SFR access information

If SCLK is HIGH at the rising edge of SEN, the data is transferred with the rising edge of SCLK; see [Figure 7](#) and [Figure 8](#). If SCLK is LOW at the rising edge of SEN, the data is transferred at the falling edge of SCLK.

For continuity, all figures and examples in this data sheet assume SEN is LOW at the rising edge of SCLK, unless otherwise stated. The first edge of SCLK is referred to as the rising edge and the second as the falling edge.

7.7 Write and read access to SFR

7.7.1 Write access to SFR

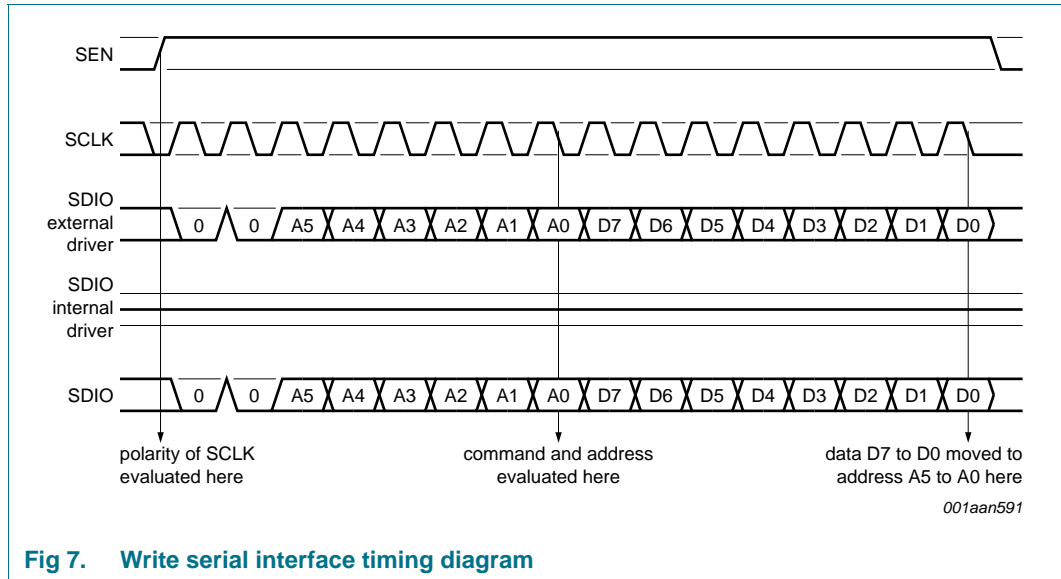


Fig 7. Write serial interface timing diagram

7.7.2 Read access to SFR

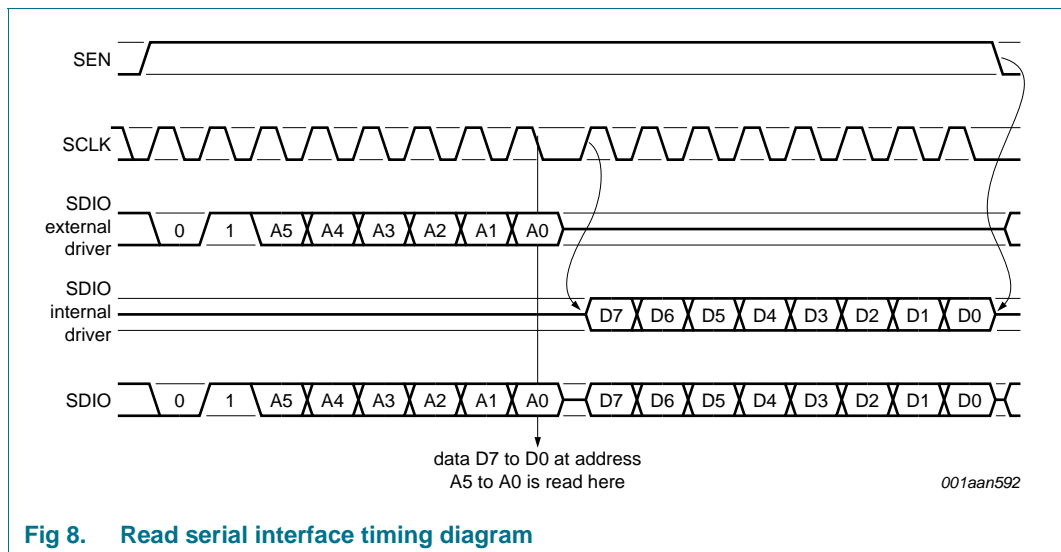


Fig 8. Read serial interface timing diagram

7.7.3 Separation of SDI and SDO line

A four-wire SPI interface can be implemented using pin SDIO for MOSI and pin P13/SDO for MISO. Timing and output control of pin SDO is the same as for the internal SDIO driver.

7.7.4 Read access to SFR with separate SDO line

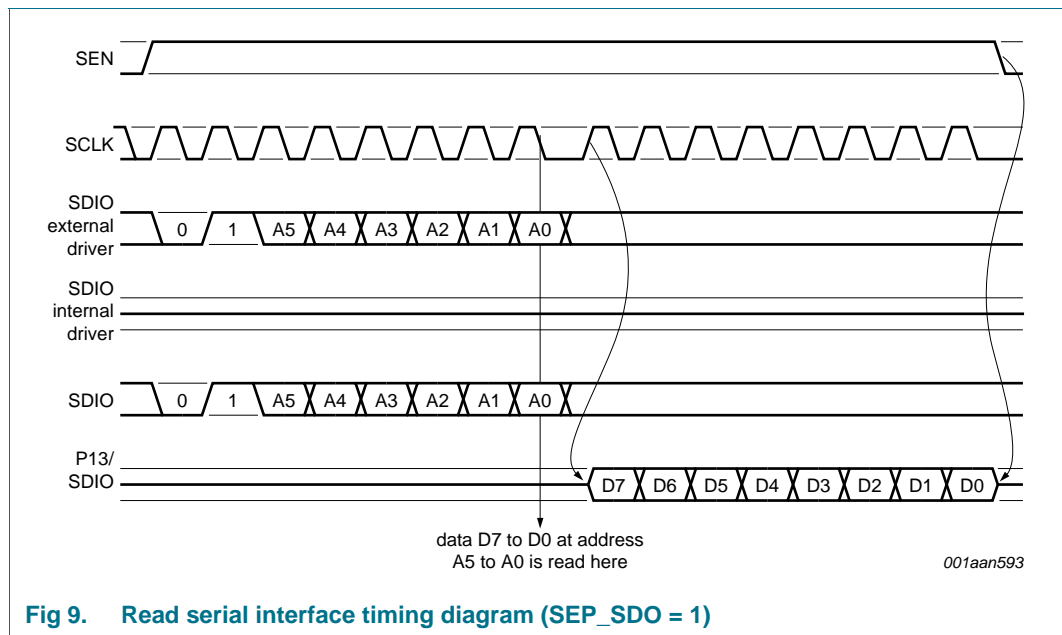


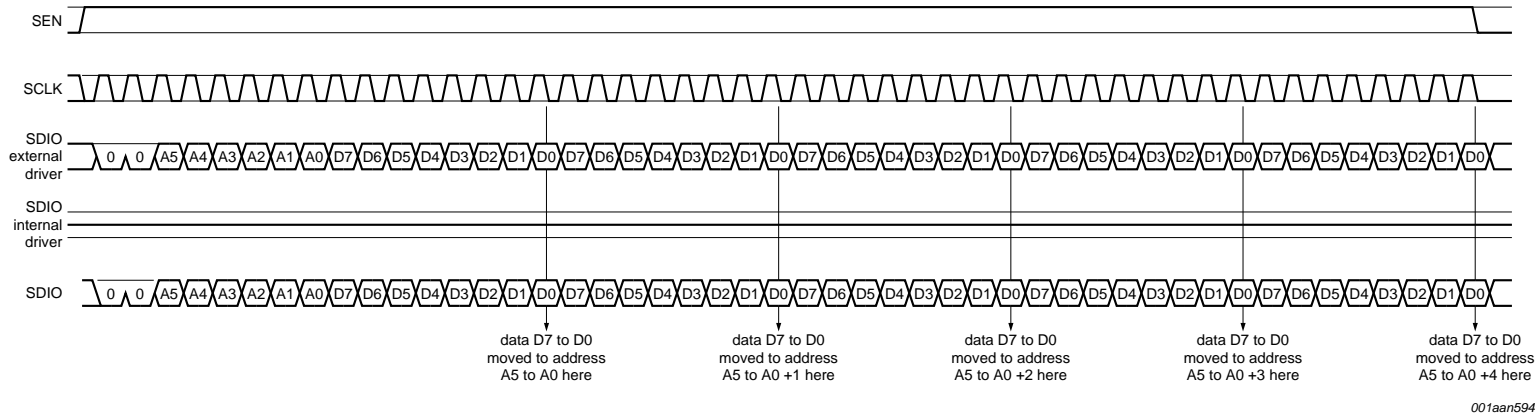
Fig 9. Read serial interface timing diagram (SEP_SDO = 1)

7.7.5 Read and write access to SFR with auto-increment function

If the SPI clock (SCLK) is still applied after the first 8 data bits are transferred, the auto-increment function automatically increments the address by one for the following 8 data bits. This enables data to be written to a continuous range of bytes without having to set the address for every single data-byte. The auto-increment function is terminated on the falling edge of SEN.

If the address reaches the end of the address range (3Fh) an additional increment causes the address to start at 00h again. This wrap around is accomplished in the current address bank. The auto-increment function has no influence on the bank selection.

7.7.6 Write access to SFR with auto-increment function

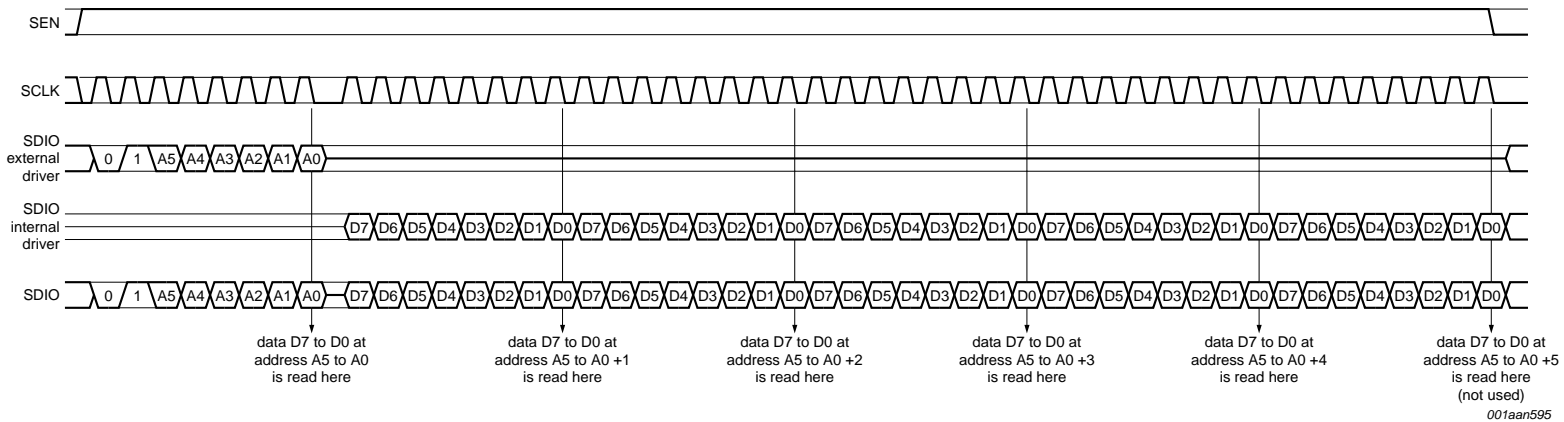


001aan594

Fig 10. Write serial interface auto-increment timing diagram

SEN must be forced LOW after registers are written to indicate end of write. [Figure 10](#) is an example showing 5 successive bytes stored.

7.7.7 Read access to SFR with auto-increment function



001aan595

Fig 11. Read serial interface auto-increment timing diagram (SEP_SDO = 0)

SEN must be forced LOW after registers are read to indicate end of read. [Figure 11](#) is an example showing 5 successive bytes read.

7.8 Device mode description

7.8.1 Automatic start-up procedures

The device features the following automatic start-up procedures for easy device handling and configuration:

- Power-on and crystal oscillator start-up
- PLL and VCO start-up including calibration
- Preparation for TX mode
- Preparation for RX mode
- VCO auto-calibration at every center frequency change

7.8.2 General description

The automatic start-up procedures are implemented to aid the quick and easy transition between operational states. Most procedures are controlled by changing bits in the PWRMODE register. Certain configurations can be directly entered by the TX or RX commands.

7.8.3 Reset and power mode register

The PWRMODE register acts as the device's 'main power on/off/standby switch'. Setting the RESET bit of this register brings the device into the reset condition equal to the power-on reset state. This power-down state is also reached automatically at first power-on (battery insertion). If this bit is set with a write command, the effect on all registers with a reset condition is a 'hard-reset'. If, with the same SPI write command, other bits are simultaneously written to the PWRMODE register, they are changed automatically to the power-on reset state; see [Section 8.2.1.10 "General power mode register PWRMODE" on page 100](#).

7.8.3.1 First power-on reset

The non-maskable interrupt flag IF_POR is set when the initial power-on reset takes place (battery insertion).

7.8.3.2 Power-down

Setting bit PD brings the device into low current consumption standby mode. All analog receiver and transmitter circuitry including the crystal oscillator are turned off and all dynamic digital activity is stopped. Only the SPI and the polling timer, if enabled, are active. Bit PD is also under automatic device control and is set under the following conditions:

- power-on reset or setting bit RESET (setting bit RESET overrides all others)
- the watchdog timer times out

7.8.3.3 Device mode states

Three important static device internal enable signals are decoded from DEV_MODE: PLEN, TXEN and RXEN.

- PLEN is set whenever the DEV_MODE is not logic 00
- RXEN is set only if DEV_MODE is logic 10
- TXEN is set only if DEV_MODE is logic 11

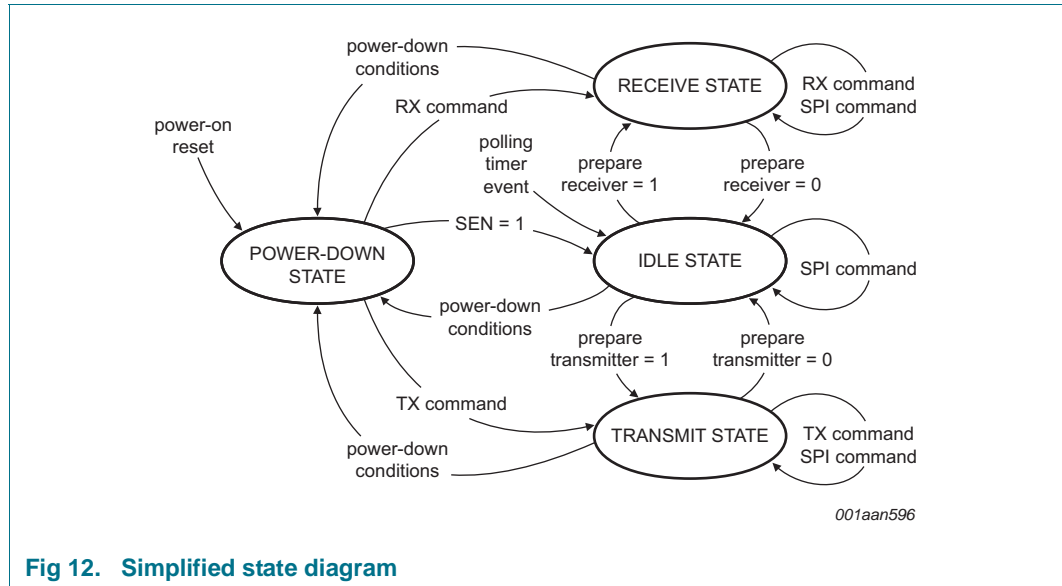


Fig 12. Simplified state diagram

An important implication of this is that a TX operation is immediately aborted if the active mode is switched to anything except TX mode, for example, switching the device into RX mode immediately shuts down the power amplifier without smoothly ramping down the RF power.

Conversely, entering TX mode immediately aborts any RX operation.

DEV_MODE bits can be either set directly by writing the PWRMODE register or by sending a RX or a TX command, where a RX command sets DEV_MODE to logic 10 and a TX command sets DEV_MODE to logic 11.

Setting bit RESET or setting bit PD (power-down) resets DEV_MODE to logic 00, where only the crystal oscillator is (potentially) enabled.

An alternative to setting the device mode can be to send a TX command and delay the '9th edge'. This sets the frequency and initiates the device as if in TX mode. The PA is then switched on at the TX command's 9th edge.

7.8.4 Flow description

The following actions are performed if the device leaves power-down state and enters active state. The internal control signals of these states are explained in more detail in later sections.

Power-down state indicator is cleared.

7.8.4.1 Digital regulator start-up

The digital voltage regulator is turned on whenever the device leaves the power-down state.

7.8.4.2 XTAL oscillator start-up

The crystal oscillator or the buffer for the external clock is turned on depending on the states of CLOCKCON register bits XODIS and EXT_CLK_BUF_EN.

Bit XO_RDY is logic 1 once the crystal oscillator has settled. The device waits for several clock periods until the clock output's frequency and duty cycle have fully settled to within the required specification. The end of this waiting period is indicated by bit REFCLK_RDY changing to logic 1. This enables the master clock gate at the root of the clock distribution tree and if applicable, the reference clock for the digital section is enabled. A polling timer recalibration is also initiated at this point.

7.8.4.3 PLL start-up

This sequence is controlled by the internal control signal PLEN. The voltage regulators for the PLL and VCO (REG_VCO_ON, REG_PLL_ON) are turned on.

Wait until the voltage regulators have settled. This sequence ends, if LO_PWR_RDY = 1.

7.8.4.4 Turn on VCO

The phase frequency detector (PFD_ON), prescaler (PRESC_ON), clock for the PLL (CLK_PLL_ON) and PLL lock detection are turned on with the next clock cycle.

7.8.4.5 Perform VCO calibration

This sequence is complete once the PLL is locked (LO_RDY is set). A manual VCO calibration immediately stops any TX or RX command.

7.8.4.6 Preparation for TX mode

This mechanism is invoked by issuing device mode logic 11 (prepare for TX) or by sending a TX command.

The voltage regulator for the power amplifier (bit REG_PA_ON) and the VCO clock divider for transmitter path (bit TXON) are enabled.

This sequence ends if the power amplifier's regulator started properly (brown-out detection not active).

7.8.4.7 Preparation for RX mode

This mechanism is invoked by issuing device mode logic 10 (prepare for RX) or by sending a RX command.

The bandgap reference circuit for the receiver section (bit RX_GAP_ON), VCO clock divider for the receiver section (bit PLL_LOCK), reference clock for the RX path (bit CLK_RXA_ON), and the analog section of receiver (bit RXA_ON) are enabled.

7.8.4.8 Perform channel filter calibration

The channel filter calibration is performed every time the device enters RX mode. This sequence ends if the channel filter calibration ends.

7.8.5 Changing device modes

Intermediate device modes may be required in an operation sequence e.g. start digital regulator and XTAL to initialize/change SFR contents or to re-trim the polling timer. This can be carried out by changing the corresponding registers. However, the direct

commands may be more useful if the only operation required is the entering of TX or RX mode. The corresponding sequences start automatically and operation enabled after all internal settling times are met.

7.8.6 Interrupts

The OL2381 can generate various interrupts which can be enabled by the IEN register and read from the IFLAG register; see [Section 8.2.1.11 “Interrupt enable register IEN” on page 101](#). The IFLAG register is always cleared after it is read. Certain pins can also be configured to present these interrupts; see [Section 7.3 “Interface description” on page 9](#).

7.9 Power supply and reset

Each main functional block is equipped with its own dedicated supply voltage pin. Therefore, several supply pins are available on the package and all must be connected. Note that all ground connections of these functional blocks are bonded to the exposed die pad of the package (metal plate underneath the die). Some blocks are supplied via dedicated integrated low-dropout voltage-regulators. Note that for all regulators the output voltage is available both internally and externally on a pin for connection of a decoupling capacitor. The following blocks have regulated supplies.

Table 3. Blocks with regulated supplies

Block	Regulator supply pin	Pin to decouple
PLL	VCC_REG	VREG_PLL
VCO	VCC_REG	VREG_VCO
PA	VCC_PA	VREG_PA
digital	VCC_DIG	VREG_DIG

7.9.1 Voltage regulators operation

All regulators are operated automatically by selecting the corresponding device modes. The device modes are set by DEV_MODE[1:0] in register PWRMODE; for details see [Section 7.8.3 “Reset and power mode register” on page 16](#).

The regulators can also be independently controlled by the control bits located inside the TEST registers. Individual operation of the voltage regulators can be necessary for debug or measurement purposes. The following paragraphs describe each individual regulator and its purpose.

7.9.2 Digital regulator

Before the device can be operated, the digital regulator must be switched on. In standby state (power-down state) the digital regulator is bypassed and supplies the digital section with a low supply voltage to guarantee data retention in the configuration registers. If the digital regulator is switched on, the voltage reaches its stabilized value of approximately 1.8 V. The digital regulator can be activated or deactivated by bit REG_DIG_DIS in TEST1 register. Clearing the bit enables the regulator, depending on the selected device mode. Setting the bit always disables the regulator.

7.9.3 PLL regulator

To start any PLL operation the PLL regulator must be switched on. This happens automatically with operation of bit REG_PLL_ON in the TEST2 register.

Remark: this bit only starts the PLL regulator, all PLL functional blocks are enabled individually by separate control-bits.

7.9.4 VCO regulator

For stability and immunity reasons the VCO is supplied via an independent voltage regulator. This regulator can be manually controlled via bit REG_VCO_ON in the TEST2 register.

Remark: this bit only starts the VCO regulator. VCO operation is enabled individually by a separate control-bit.

7.9.5 PA regulator

This regulator is enabled if PA operation is desired. This can be manually controlled by setting bit REG_PA_ON.

Remark: this bit only starts the PA regulator. TX operation must be enabled by setting the corresponding command on the SPI interface.

7.9.6 Device reset

A device reset occurs whenever the supply voltage is applied on the VCC pins (battery insertion). The device utilizes two power-on detection mechanisms, one digital and one analog. These reset circuits constantly monitor the supply voltage. Setting bit RESET in the PWRMODE register performs the same operation by software. This is equivalent to a power-on reset. If bit RESET is set via a command, it is cleared automatically when SPI signal SEN goes LOW after the next write register command.

7.10 Main control and timing blocks

7.10.1 Crystal oscillator

7.10.1.1 Circuit description

The crystal oscillator is the source of the reference clock for the PLL, the digital section and the mixed signal blocks in the receiver chain. The crystal oscillator circuit diagram is shown in [Figure 13](#).

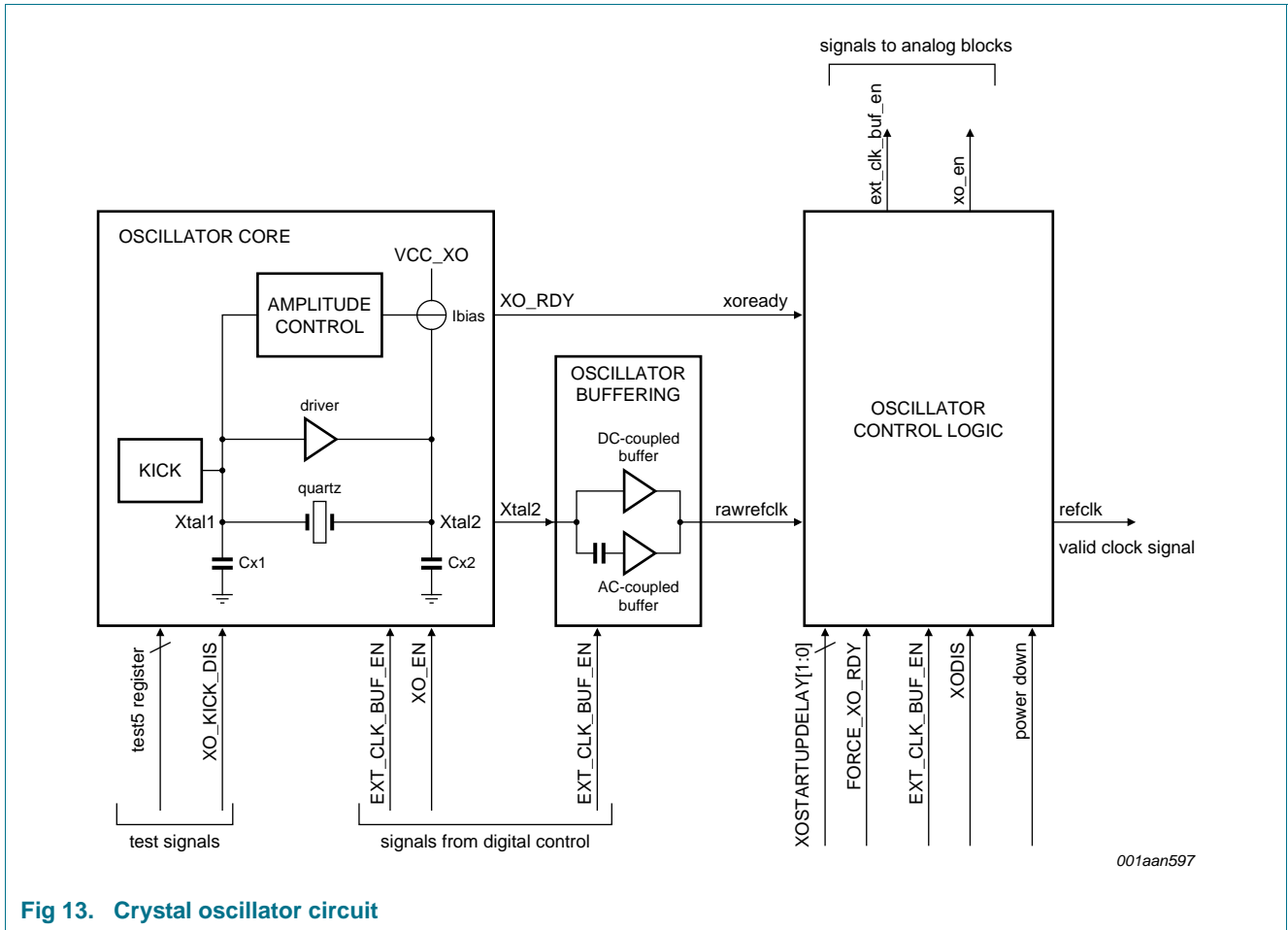


Fig 13. Crystal oscillator circuit

The crystal oscillator consists of three main blocks: the oscillator core, the oscillator buffer and the oscillator control logic.

The oscillator core is a low power quartz based Pierce oscillator. The oscillation frequency is defined by the quartz and the tuning capacitors CX1 and CX2. The driver’s low capacitance has negligible impact on the frequency value. The oscillator core is supplied by pin VCC_XO.

When the oscillation starts and the amplitude successfully detected, the amplitude control releases the signal XO_RDY to the oscillator control logic for validation. This signal indicates that the amplitude control loop has entered regulation mode and not that the oscillator has settled. An extra delay is still needed to ensure the frequency accuracy; see [Table 116 “XOSTARTUPDELAY bit functions” on page 124.](#)

After start-up, the amplitude control avoids clipping and excessive driving power in the crystal unit.

The oscillator control logic validates the oscillator signal and provide configuration facilities. The oscillator control logic is supplied by the digital regulator to the level VREG_DIG.

The oscillator buffer consists of two amplifiers connected in parallel: one low-noise AC-coupled amplifier for crystal operation and one high-input voltage DC-coupled amplifier for testing purposes only. The buffer plays the role of level-shifter for the signals in PLL and digital supply domains. The buffer circuitry is supplied by the PLL and digital regulators accordingly.

Alternatively, an external clock signal can be applied at pin XTAL2; see the external clock buffer description in [Section 7.10.2 “Oscillator control and control bits” on page 23](#). The applied signal must comply with the logic levels in the digital core (0 V for LOW and 1.8 V for HIGH). With the OL2381 properly configured, the DC-coupled amplifier replaces the low-noise AC-coupled amplifier. This provides the possibility to skip the internal oscillator's start-up sequence and also allows the customer to stop the clock sequence for test purposes.

Remark: The use of an external clock signal requires special care in the hardware configuration. The oscillator core circuitry connected to pin XTAL2 cannot withstand levels higher than 2.8 V. Therefore, the use of this test mode with supply voltages higher than 2.8 V requires a hardware modification for pin VCC_XO. The recommended solution is to connect pin VCC_XO to pin VREG_DIG. In that configuration the circuit's integrity is ensured but the digital noise needs to be considered.

The crystal oscillator is always active either in oscillator mode or in external clock buffer mode when the device is not in Power-down state.

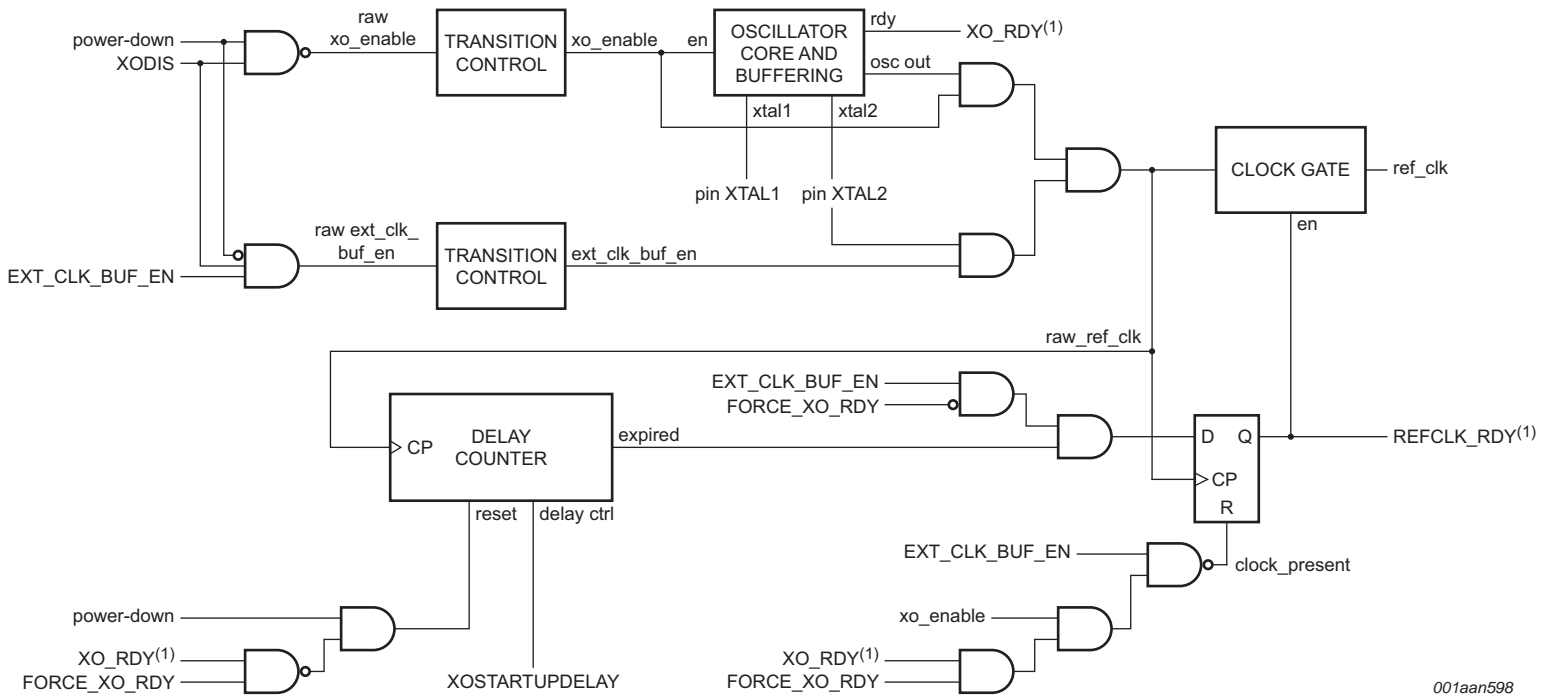


Fig 14. Diagram for crystal oscillator with clock selection circuitry

7.10.2 Oscillator control and control bits

The oscillator control logic is described in [Figure 14](#). Upper case signal names denote control bits in the OL2381's register set. Upper case signal names labeled '(1)' denote (internal and 'official') status signals. Lower case signal names denote internal signals.

The enable logic is visible at the top left corner for both modes: the crystal oscillator mode and the external clock buffer mode. The crystal oscillator is turned on when both, power-down and XODIS, are false. The transition control ensures that no glitches can be generated when turning the oscillator on and off. The external clock buffer is turned on when the device is not in power-down mode and both control bits, XODIS and EXT_CLK_BUF_EN are set; see [Section 8.2.1.15 "Clock connection register CLOCKCON" on page 103](#). As a consequence, putting the device in power-down mode disables all clock activity, and turning the crystal oscillator on has priority over turning the external clock buffer on.

If the crystal oscillator is turned on (`XO_ENABLE` becomes true) and a crystal is connected to the oscillator, the raw clock becomes available after the oscillation reaches a significant amplitude, which is then signaled with the internal `XO_RDY` status signal. This internal status signal can be routed to pin P12/CLOCK for observation. While the crystal oscillator is disabled, it is ensured that the clock from this clock source is held at the zero level.

If the external clock buffer is activated (bit `EXT_CLK_BUF_EN` is true) the signal connected to pin XTAL2 is taken as the clock source. While the external clock buffer is disabled, it is ensured that the clock from this clock source is held at the zero level.

Since only one clock source can deliver a clock at a given time they can be easily merged. The clock is only fed into the circuit when the clock gate is enabled. The following paragraphs explain the conditions for enabling this clock gate separately for each clock source.

When using the crystal oscillator, the delay counter, in [Figure 14](#), is held in reset state during Power-down mode or if both, the internal status signal `XO_RDY` and the expert control bit `FORCE_XO_RDY`, are false. If the oscillator signals `XO_RDY` after start-up (or if the `FORCE_XO_RDY` is set), the delay counter is released from reset, which lets it count the raw clock pulses from the oscillator. Note that counting will not occur if the oscillation amplitude is too low or if the clock pulses are too 'thin' (duty cycle near 0 % or near 100 %). Therefore it is ensured that the delay counting will not start before the raw clock has a usable shape. After a programmable count ([Table 116 on page 124](#)) is reached, the counter stops and signals the end of the delay.

The digital oscillator start-up delay can be controlled by bits `XO_STARTUPDELAY[1:0]` in register `EXPERT1`.

After the delay counter's end status reaches the `REFCLK_RDY` flip-flop, (shown at the lower right corner of [Figure 14](#)), it is sampled by the raw clock, now stabilized, and this declares the reference clock ready. This also enables the clock gate which passes the clock on to the circuit starting with the following clock pulse. The `REFCLK_RDY` status flip-flop is immediately reset when the raw clock is no longer present, which happens when the crystal oscillator is turned off or bit `XO_RDY` is false due to any reason which may have stopped the oscillation.

Note that special care is needed when non-recommended crystals are used. The use of non-recommended crystals and resonators may have a negative impact on the start-up behavior, on the frequency stability and on the PLL noise performance.

The oscillation amplitude is always large enough for recommended crystals so the amplitude control can properly detect that the start-up and noise generated by the AC-coupled buffering is appropriate for PLL operation.

If the crystal is replaced by a resonator with a low Q factor, the resulting amplitude may not be large enough for the `XO_RDY` status to be properly detected, although the generated clock may still be usable. To use the OL2381 under such conditions, the `XO_RDY` status must be overridden by using the expert control bit `FORCE_XO_RDY`. Note that the delay counting mechanism will not start counting before the raw clock reaches a certain quality.

If the external clock buffer is used, it is assumed that the clock source, which is connected to pin XTAL2, provides a stable clock with a duty cycle close to 50 % at the time when bit EXT_CLK_BUF_EN is set. Therefore the delay counter is not needed in this case. But even without the delay counter, the circuit provides a well-controlled startup sequence, which is enforced by the REFCLK_RDY flip-flop and the clock gate, so that no glitches are generated when the clock buffer is turned on or off. Note that not using the delay counter in this normal case requires the FORCE_XO_RDY expert control bit to be in the cleared state.

However, if bit FORCE_XO_RDY is set when using the external clock buffer, the delay mechanism is activated. This is how the delay counter is tested in the production test but it may also help to overcome start-up problems in the external clock source. The XO_RDY, REFCLK_RDY signals can be observed for oscillator testing via the test buffer. The resulting clock can be probed at pin CLOCK.

7.11 Watchdog

The device features a watchdog timer to recover from situations when activation is not desired. The watchdog timer runs with the reference clock and it is activated, if the device is not in Power-down mode.

The watchdog is cleared and temporarily stopped under the following circumstances:

- Pin SEN is HIGH
- A terminating wakeup search is executed, i.e. either a pessimistic wakeup search is activated (bit WUPSMODE = 0) or the timer for the wakeup search is activated during an optimistic wakeup search (bit WUPSMODE = 1 and bits WUPSTIMEOUT not equal to 0).
- A terminating preamble detection is executed, i.e. the timeout for the preamble must be activated (bit EN_PREADET_TIMEOUT = 1 and bits WUPSTIMEOUT not equal to 0).

Bit EN_PREADET_TIMEOUT can be found in register SIGMON1; see [Section 8.2.2.2 “Signal monitoring control register SIGMON1” on page 115](#). Bit WUPSMODE can be found in register SIGMON0; see [Section 8.2.2.1 “Signal monitoring register SIGMON0” on page 114](#). Bits WUPSTIMEOUT can be found in register WUPSTO; see [Section 8.2.2.4 “Register WUPSTO” on page 116](#).

The watchdog timeout can be adjusted according to [Equation 1](#).

$$\text{watchdogtimeout} = \frac{2^{15} + \text{WUPSTIMEOUT}}{\text{CLK}_{REF}} \quad (1)$$

where:

$\text{CLK}_{REF} = 16 \text{ MHz}$

watchdogtimeout = desired watchdog timeout

It is not possible to turn off the watchdog completely. The watchdog can be disabled for an arbitrary period only if pin SEN is set HIGH.

7.12 Polling and wakeup timer

The device features a low power oscillator, which can be used to generate wakeup events. A polling timer overflow always generates an interrupt request. Moreover, if selected, the device can be automatically released from the Power-down state and it can enter the RX state.

The low power oscillator has a nominal period of 40 μ s and a tolerance of $\pm 50\%$ over the entire temperature and supply voltage range and over process-dependent device spread.

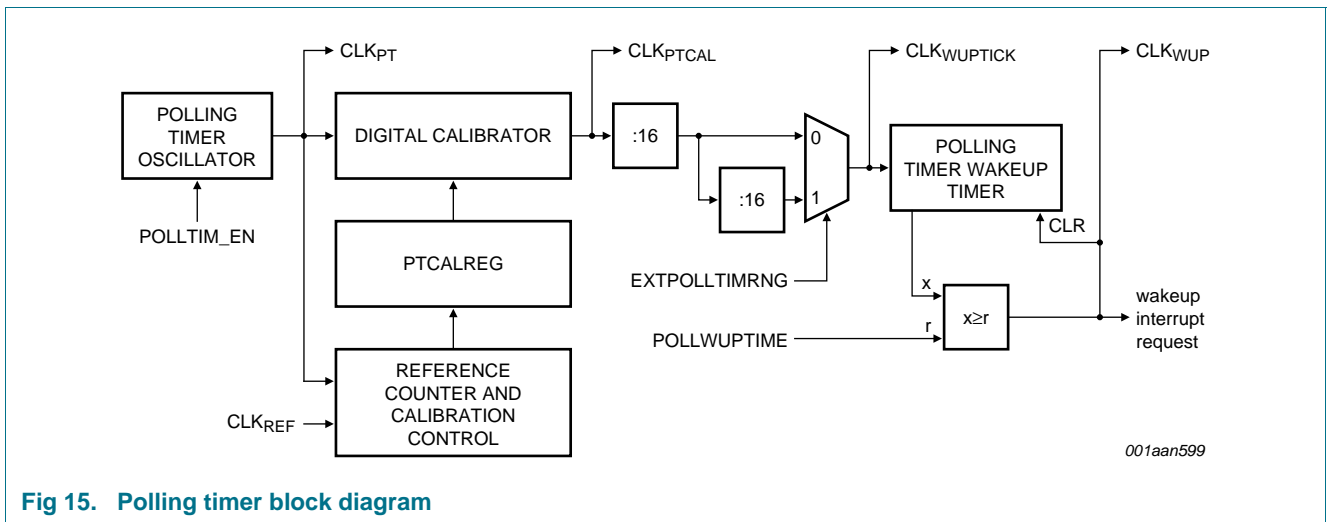


Fig 15. Polling timer block diagram

The polling timer employs a digital calibration with a modulo counter. The crystal oscillator clock **CLK_{REF}** is used as a reference clock for the calibration. The calibration procedure measures one period of the polling timer clock **CLK_{PT}** and determines the appropriate calibration value for the modulo counter. The output clock **CLK_{PTCAL}** has a nominal period of 62.5 μ s.

The polling timer can be turned on and off with bit **POLLTIM_EN** in the **PWRMODE** register. The state of this bit after a master reset is determined by the level on pin **RSTDIS**.

Note that due to the absence of the reference clock it is not possible to trim the polling timer directly after a master reset. The calibration register **PTCALREG** is set to its nominal value after a master reset.

After exiting Power-down mode, the polling timer calibration is triggered automatically if the crystal oscillator starts properly. It is also possible to trigger a manual calibration by setting bit **MANUALPTCAL**. Setting this bit generates a short pulse, which starts the calibration routine. Reading bit **MANUALPTCAL** always yields zero. The manual calibration is only executed if the polling timer and the crystal oscillator are running otherwise the request is ignored. Setting bit **MANUALPTCAL** at the same time as **POLLTIM_EN** is not supported. The calibration is only performed after the polling timer oscillator settles.

The value in the calibration register is consistent under all circumstances. This must also be the case if a running calibration is interrupted. Direct read or write access to register **PTCALREG** is not supported.

The polling timer wakeup time can be set with the 8-bit control register POLLWUPTIME. The wakeup time calculates to:

$$T_{WUP} = (POLLWUPTIME + 1) \times T_{WUPTICK} \quad (2)$$

The achievable resolution and wakeup times can be selected in two different ranges, a normal and an extended polling timer range according to the setting of bit EXT POLLTIMRNG in the CLOCKCON register.

It is possible to change the register POLLWUPTIME while the polling timer is running. If the new value is greater than the polling timer counter's current content, the running period is not interrupted and the newly set wakeup time is seamlessly adjusted. This mechanism allows the setting of a new wakeup time with respect to the last wakeup event. If the newly set value in register POLLWUPTIME is smaller than the polling timer counter's current content, the counter is reset immediately.

The digital calibration is implemented so that the accuracy of wakeup times greater than 10 ms is better than 1 %. This allows an overall timing error of less than 2 % for the given range.

7.12.1 Actions at polling timer wakeup

Register POLLACTION defines which action the device carries out after a polling timer event; see [Section 8.2.1.14 "Polling action register POLLACTION" on page 102](#).

POLL_MODE[1:0] defines the device's operating mode after a polling timer event.

RX_GAIN[1:0] means the same as the RX flags RE and RF (gain step/switch selection bits). The RX_CMD bit means the same as RX flag RC. It allows a choice between a WUPS (0) and a PRDA command (1). RX_FREQ[1:0] means the same as RX flags RA and RB (frequency selection).

The last bit in the POLLACTION register, SET_RX_FLAGS, defines whether the RX flag register's current content is used for the automatically initiated RX command (if 0) or whether the RX flags RA, RB, RC, RE and RF flags are overwritten with the contents of the RX_FREQ, RX_CMD and RX_GAIN bit settings of this register, respectively, before the command is actually launched (if 1). If the flags are overwritten, RX flag RD is set to logic 1 to make the sub-command either a WUPS or a PRDA command; see [Section 7.32.2 "Receive command" on page 55](#) for more information.

7.13 RX and TX baud-rate generator

The baud-rate generator generates the nominal, unsynchronized chip clock according to [Equation 3](#).

$$baudrate = \frac{16\text{MHz}}{2^{PRESC}} \times \frac{2^{11} + MAINSC}{2^{12}} \times \frac{1}{128} \quad (3)$$

where PRESC is an exponent in the range from 0 to 7, and $2^{11} + MAINSC$ is the mantissa in the range 2048 to 4095. The resulting baud-rate clock can jitter by one prescaler clock cycle CLK_{PSC} .

The mainscaler MAINSCL lower bits can be found in register TIMING0.

The MAINSCH and the PRESC bits can be found in register TIMING1; see [Section 8.2.1.5 “Timing register TIMING1” on page 95](#).

The divide-by-128 divider is used as a ‘clock’ for several other blocks to measure the sub-timing within one chip interval.

This baud-rate generator is used as the time reference for a synchronized TX operation and as a time reference for the clock-recovery in RX mode.

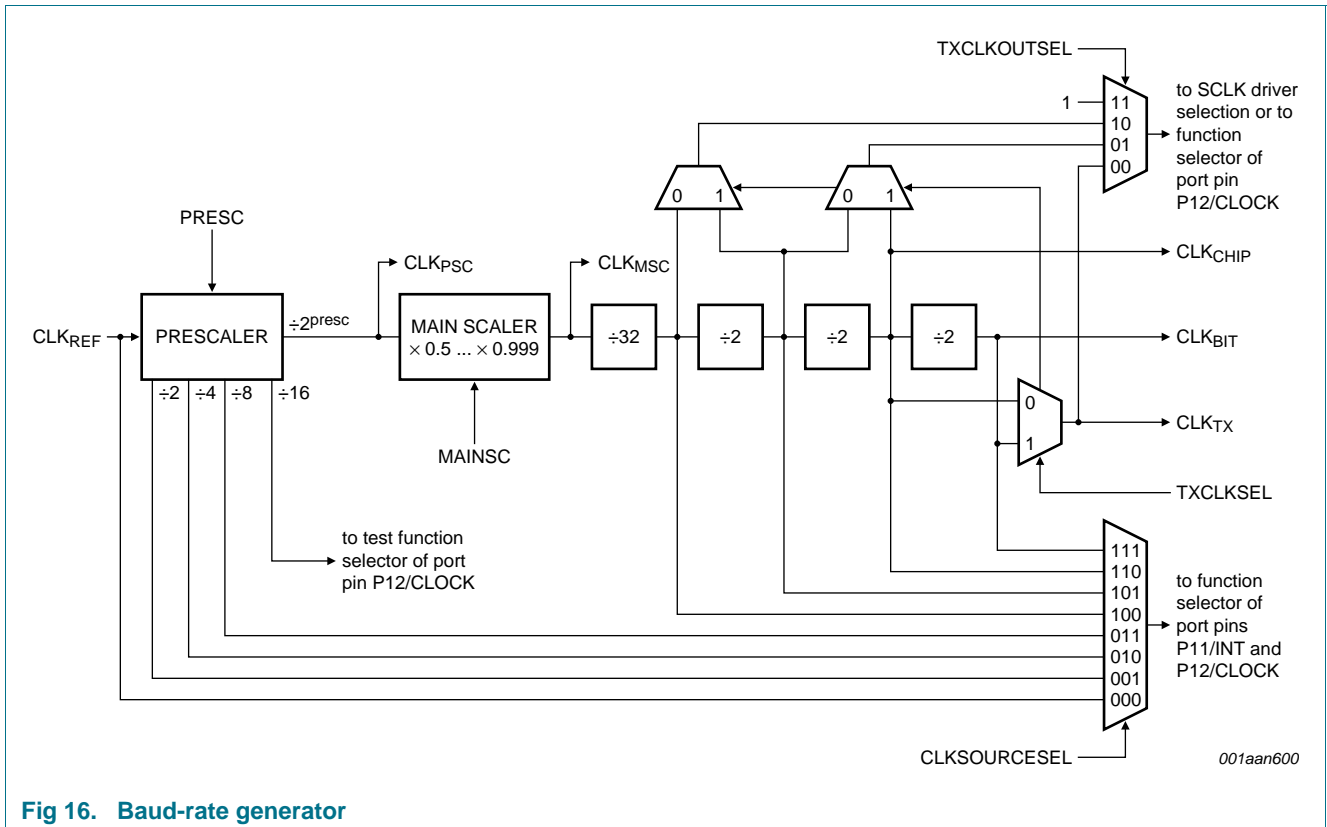


Fig 16. Baud-rate generator

Calculation of clock in TX mode is shown in [Equation 4](#).

$$CLK_{TX} = \frac{CLK_{REF}}{2^{PRESC}} \times \frac{2^{11} + MAINSC}{2^{12}} \times \frac{1}{128} \times \frac{1}{2^{TXCLKSEL}} \tag{4}$$

where $CLK_{REF} = 16$ MHz.

Bit TXCLKSEL can be selected whether the chip clock CLK_{CHIP} or the bit clock CLK_{BIT} is used as the TX clock. If automatic Manchester generation is required, the bit clock must be selected.

Bits CLKSOURCESEL are in register CLOCKCON; see [Section 8.2.1.15 “Clock connection register CLOCKCON” on page 103](#).

Bit TXCLKSEL is in register TXCON; see [Section 8.2.1.23 “Transmitter control register TXCON” on page 107](#).

7.13.1 Clock recovery for RX mode

The clock-recovery for RX mode is dependent on the baud rate accuracy. If the absolute correct baud rate cannot be selected, choose the next available integer value. The clock recovery is able to cope with a 1 % tolerance to be able to operate correctly with standard XTAL cutting and temperature inaccuracies. The clock recovery is implemented as a digital phase control loop with a fixed operating frequency determined by the baud-rate generator setting. The baud-rate generator's mainscaler clock acts as the reference clock for the clock-recovery PLL (128 times the actual chip clock). The clock recovery PLL is programmable with regards to its settling speed. The settling of the clock-recovery speed can be set to reach its final state within 3, 7, 15 or 31 chips. If the clock-recovery is locked to the bit-stream the actual possible phase-error is proportional to the selected settling speed setting. Highest settling speed (settling within 3 chips) produces the smallest actual phase error due to fast regulation; slowest speed (settling within 31 chips), allows for the largest phase error due to the slowest regulation time constant; see [Table 103 "CLOCK_RECOV_TC bit functions" on page 118](#).

Note that the decoding of NRZ signals with long constant bit-periods is directly influenced by the accuracy of the selected baud rate. Proper coding can significantly improve sensitivity and the BER of NRZ decoding.

7.14 Phase-locked loop

A complete on-chip PLL is available to provide an RF carrier in both RX and TX modes. The PLL is a 4th-order fractional-N PLL. The PLL analog section is described in [Section 7.14.1](#) and the PLL digital section is described in [Section 7.14.7](#).

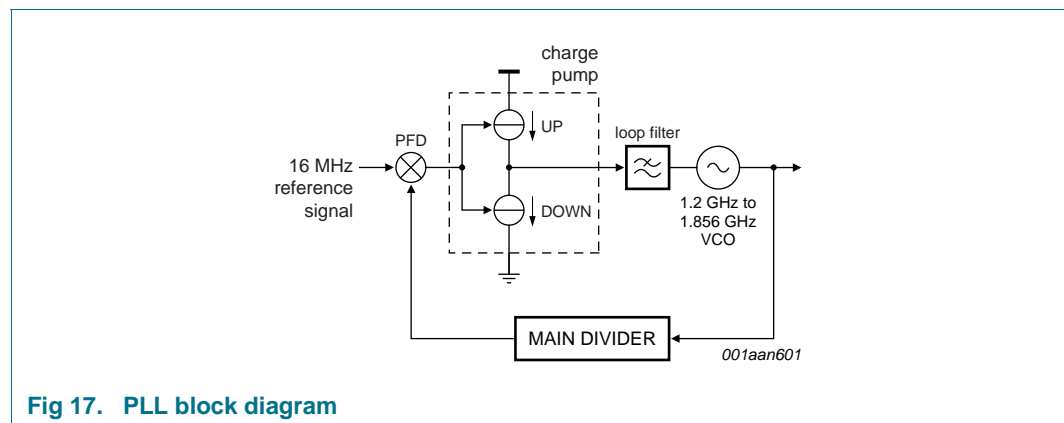


Fig 17. PLL block diagram

7.14.1 PLL building blocks

All PLL building blocks except bit VCO_BAND in register LOCON and the charge pump reference current (PLL_ICP[4:0]) settings are automatically configured and operated by selecting the corresponding device modes. The following paragraphs describe the function of the internal control signals. These control signals can be influenced, if desired, by operating control bits located in the EXPERTn and TESTn registers.

7.14.2 PLL and VCO regulators

To operate the whole PLL, both regulators must be switched on; see [Section 7.9.3 "PLL regulator" on page 19](#).

7.14.3 General PLL operation

The following blocks are enabled after switching on the regulators so that the entire PLL is operational: VCO (VCO_ON), phase-detector (PFD_ON), prescaler (PRESC_ON) and reference clock buffer (CLK_PLL_ON), depending on the selected mode of operation (RX or TX mode, selected via device mode or command); eventually RX_ON must be also set. If this bit is set to logic 1, the RX LO dividers are activated.

7.14.4 Charge pump

This block delivers the charge to the loop filter. The polarity and amount of charge are proportional to the phase error reported by the phase detector.

The peak current of this charge pump is automatically adjusted. It can be overridden by PLL_ICP[4:0] in register EXPERT0; see [Section 8.2.4.1 "Register EXPERT0" on page 124](#). The charge pump peak current is a function of the icp control bits: $icp[0] * 15 \mu A + icp[1] * 30 \mu A + icp[2] * 60 \mu A + icp[3] * 120 \mu A + icp[4] * 240 \mu A$.

This means that a value from 15 μA up to 465 μA can be selected. The purpose of this programmability is to compensate for gain variation in other blocks, especially RF VCO, and to keep a constant PLL loop bandwidth. The recommend value is to set PLL_ICP to 2.

7.14.5 RF VCO

The very low phase-noise on-chip RF oscillator is based on an LC oscillator.

A capacitor bank is integrated to center the resonant frequency of the LC tank on the desired RF frequency. The VCO auto-calibration routine automatically trims the VCO to the correct sub-band. Whenever a different frequency setting is used for TX or RX operation, the VCO auto-calibration is carried out automatically. Automatic trimming can be blocked by setting bit SKIP_VCO_CAL in the LOCON register except during the PLL start-up; see [Section 8.2.1.3 "Local oscillator control register LOCON" on page 95](#). The trimming (sub-band selection) can be manually modified by control bits VCO_SUBBAND[5:0] in register VCOCON; see [Section 8.2.1.2 "VCO control register VCOCON" on page 94](#). Frequency sub-band setting 0 corresponds to the maximum frequency, and 3Fh to the minimum frequency.

Note that this RF VCO is running at twice (868 MHz and 928 MHz bands) or four times (313 MHz and 434 MHz bands) the chosen frequency bands.

Setting bit VCO_BAND selects the VCO's appropriate operating mode. This bit must be set to logic 1 at RF frequency bands below 400 MHz, or set to logic 0 for all other bands.

7.14.6 PLL loop bandwidth setting

It is recommended that the PLL loop bandwidth is set to just above 150 kHz (–3 dB closed loop bandwidth) as this gives the best trade off between noise behavior and locking time. The loop bandwidth can be set by PLL_ICP[4:0] to the recommended value ICP = 2.

7.14.7 Delta-sigma modulator for fractional-N synthesis

The operating frequency is set by the content of frequency control registers FC0 to FC3, which each have a width of 20 bits. The 'active' frequency control register is selected directly by the TX or RX command; see [Section 8.2.1.1 "Frequency control registers" on page 93](#).

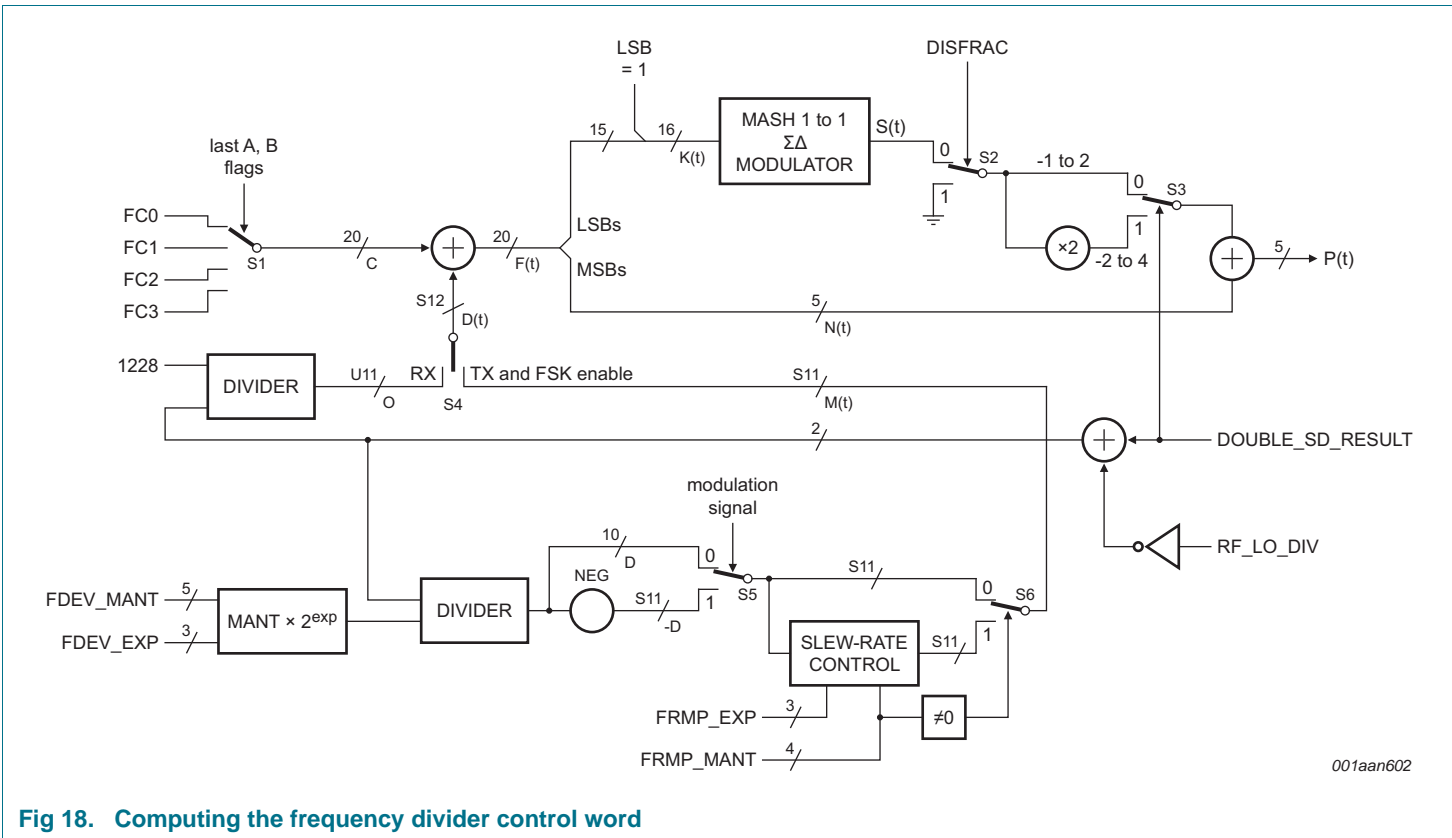


Fig 18. Computing the frequency divider control word

7.14.7.1 PLL operating frequency f0

In [Figure 18](#), the integer (Nt) is forwarded directly to the adder which produces the relevant control word (Pt) for the PLL. The remaining fractional values cannot be handled by the frequency divider directly and are therefore converted into a pseudo-random sequence of integers. This conversion is implemented by the sigma delta modulator. It produces numbers in the range from -1 to +2, whose average over time equals the given fractional part.

The spectral purity of the resulting RF signal is highly dependent on the randomness of the sequence generated by the fractional part. If this contained short repetitive patterns unwanted spurious signals may occur in the RF spectrum. To guarantee the produced sequences are always of maximal length, we append a constant 1-bit to the given fractional part, which resolves the issue. The weight of this 16th bit is $1 / 216 = 1 / 65536$, which is very low. It creates a tiny frequency offset which can be taken into account when calculating the center frequency control value FCx for a given center frequency.

When the fractional part approaches 0 or 1 the low frequency noise components in the pseudo-random sequence become more dominant and can no longer be sufficiently suppressed by the PLL's transfer function. The visible effect is an increase of the phase noise in the RF output near the carrier. To counteract this effect, the OL2381 uses bit DOUBLE_SD_RESULT (Double Sigma Delta Result). If this bit is set, the fractional contribution to the PLL control word is doubled. So when the frequency control value F(t) is increased linearly, each RF output frequency is produced twice; once with a fractional value that is closer to zero or one (between 0 and 1 / 4 or between 3 / 4 and 1) and a second time with a fractional value which is closer to the mid-value 1 / 2 (between 1 / 4 and 3 / 4). The latter value produces a good pseudo-random sequence.

The frequency control value's fractional part is processed differently depending on bit DOUBLE_SD_RESULT, and the center frequency changes accordingly. Therefore the formulae, which convert between a given Frequency Control (FC) value and the RF center frequency, change with the state of bit DOUBLE_SD_RESULT.

In normal mode the expression is straightforward as shown in [Equation 5](#).

$$f_{RF} = f_{ref} \times \left(64 + 2 \times \frac{2 \times FCx + I}{65536} \right) \times \frac{1}{2 + 2 \times RF_LO_DIV} \quad (5)$$

- The expression's left side shows the reference frequency. The output frequency varies proportionally with the reference.
- The parenthesized expression (64 + 2 × ...) is the characteristics of the PLL frequency divider.
- The right term in the parenthesized expression accounts for the number interpretation of C and F(t) and the constant 1 LSB, which is added to guarantee maximum length sequences from the sigma-delta modulator
- The fraction at the right is the output division ratio, which is either 1 / 2 or 1 / 4, depending on the setting of bit RF_LO_DIV.

After simplifying the expression further we get the results shown in [Equation 6](#).

$$f_{RF} = f_{ref} \times \left(32 + \frac{2 \times FCx + I}{65536} \right) \times \frac{1}{1 + RF_LO_DIV} \quad (6)$$

For the inverse we solve the above expression for FCx and then we round the result to the nearest integer number as shown in [Equation 7](#).

$$FCx = \text{round} \left\{ \left\{ \frac{f_{RF}}{f_{ref}} \times (1 + RF_LO_DIV) - 32 \right\} \times 32768 - 0.5 \right\} \quad (7)$$

Using the floor function this becomes as shown in [Equation 8](#).

$$FCx = \left\lfloor \left\{ \frac{f_{RF}}{f_{ref}} \times (1 + RF_LO_DIV) - 32 \right\} \times 32768 \right\rfloor \quad (8)$$

Remark: [Equation 8](#) is an important equation.

If bit DOUBLE_SD_RESULT is set, the integer part and the fractional part of the center frequency setting must be considered separately. In this case the expression for the output frequency is shown in [Equation 9](#).

$$f_{RF} = f_{ref} \times \left\{ 64 + 2 \times \left(FCx[19:15] + 2 \times \frac{2 \times FCx[14:0] + I}{65536} \right) \right\} \times \frac{I}{2 + 2 \times RF_LO_DIV} \quad (9)$$

In the inner parenthesized expression the integer part is taken as is, where the term which contains the fractional part has an additional factor of 2. After canceling certain factors of 2 we get result shown in [Equation 10](#).

$$f_{RF} = f_{ref} \times \left\{ 32 + FCx[19:15] + \frac{2 \times FCx[14:0] + I}{32768} \right\} \times \frac{I}{I + RF_LO_DIV} \quad (10)$$

The inverse of this function is problematic, because the function for the output frequency is not monotonous. But we know that each output frequency is produced exactly twice and we know also that we want the solution where the average of the sigma-delta output S(t) is closest to 1 / 2. Let us convert [Equation 10](#) such that the integer part of the frequency control value has no factor and the term containing the fractional part of the frequency control value becomes isolated on one side of the equation as shown in [Equation 11](#).

$$\frac{f_{RF}}{f_{ref}} \times (I + RF_LO_DIV) - 32 - FCx[19:15] = \frac{2 \times FCx[14:0] + I}{32768} = 2 \times fract \quad (11)$$

Now we ask for the integer part for which the fractional part becomes a value in the range from 0.25 to 0.75, which is equivalent to twice the fractional part, and lies between 0.5 and 1.5 as shown in [Equation 12](#) and [Equation 13](#).

$$\frac{f_{RF}}{f_{ref}} \times (I + RF_LO_DIV) - 32 - FCx[19:15] \geq 0.5 \quad (12)$$

$$\frac{f_{RF}}{f_{ref}} \times (I + RF_LO_DIV) - 32 - FCx[19:15] < 1.5 \quad (13)$$

Now we can isolate the integer part from both inequalities so that the right sides are the same as shown in [Equation 14](#) and [Equation 15](#).

$$FCx[19:15] \leq \frac{f_{RF}}{f_{ref}} \times (I + RF_LO_DIV) - 32 - 0.5 \quad (14)$$

$$FCx[19:15] + 1 > \frac{f_{RF}}{f_{ref}} \times (I + RF_LO_DIV) - 32 - 0.5 \quad (15)$$

These inequalities can be combined into a single expression to calculate the integer control value for the PLL as shown in [Equation 16](#).

$$FCx[19:15] = \left\lfloor \frac{f_{RF}}{f_{ref}} \times (I + RF_LO_DIV) - 32.5 \right\rfloor \quad (16)$$

Remark: [Equation 16](#) is an important equation.

The integer part which we have just found can be entered in [Equation 10](#) and then we can solve for the fractional part. We get the result for the settings after rounding it to the nearest integer number shown in [Equation 17](#).

$$FCx[14:0] = \text{round} \left\{ \left\{ \frac{f_{RF}}{f_{ref}} \times (1 + RF_LO_DIV) - 32 - FCx[19:15] \right\} \times 16384 - 0.5 \right\} \quad (17)$$

When using the floor function this becomes as shown in [Equation 18](#).

$$FCx[14:0] = \left\lfloor \left\{ \frac{f_{RF}}{f_{ref}} \times (1 + RF_LO_DIV) - 32 - FCx[19:15] \right\} \times 16384 \right\rfloor \quad (18)$$

Remark: [Equation 18](#) is an important equation.

From [Equation 5](#) and [Equation 10](#) we can also see which frequency resolution can be achieved in which mode. If bit DOUBLE_SD_RESULT is set to logic 0, we have [Equation 19](#).

$$f_{RF, res(0)} = f_{ref} \times 2 \times \frac{2}{65536} \times \frac{1}{2 + 2 \times RF_LO_DIV} = \frac{f_{ref}}{32768} \times \frac{1}{1 + RF_LO_DIV} \quad (19)$$

If bit DOUBLE_SD_RESULT is set to logic 1, the resolution becomes as shown in [Equation 20](#).

$$f_{RF, res(1)} = f_{ref} \times 2 \times \frac{2}{65536} \times \frac{1}{2 + 2 \times RF_LO_DIV} = \frac{f_{ref}}{16384} \times \frac{1}{1 + RF_LO_DIV} \quad (20)$$

Taking bit DOUBLE_SD_RESULT into the formula, [Equation 19](#) and [Equation 20](#) can be combined into

$$f_{RF, res} = \frac{f_{ref}}{32768} \times \frac{1 + DOUBLE_SD_RESULT}{1 + RF_LO_DIV} \quad (21)$$

Remark: [Equation 21](#) is an important equation.

7.14.8 RX frequency offset

Because the OL2381 receiver implements a superheterodyne architecture with an intermediate frequency of 300 kHz, the local oscillator is automatically tuned to 300 kHz above the wanted RX center frequency in RX mode. This RX frequency offset is independent of the RF_LO_DIV and DOUBLE_SD_RESULT settings.

This is accomplished by adding an offset value O to the center frequency setting C; see [Figure 18 “Computing the frequency divider control word” on page 31](#). This offset value is automatically adjusted so that it matches the LO frequency resolution, which changes with the settings of bits RF_LO_DIV and DOUBLE_SD_RESULT.

[Table 70 “RX frequency offset” on page 107](#) shows that the resulting RX frequency offset is independent of the RF_LO_DIV and DOUBLE_SD_RESULT settings. It is always 195 Hz below the nominal IF of 300 kHz, which is accurate enough in all cases.

7.14.9 PLL lock detection

A lock detection circuit is implemented to support the shortest PLL power-on time. The lock-detection circuit monitors the phase and frequency differences of the PLL and the reference clock. If the phase-difference of the two clock signals is settled within a defined window, an internal LOCK_DETECT signal is triggered. After a specified time, set by bit LOCK_DET_TIME[1:0] in register EXPERT1, status bit LO_RDY is set in register DEVSTATUS. Since the lock detect circuit consumes additional power, it is only enabled during the PLL's start-up phase and whenever a different sub-band setting is applied. The lock detect circuit can be manually controlled by bit LOCK_DET_ON in register LOCON; see [Section 8.2.1.3 "Local oscillator control register LOCON" on page 95](#).

7.15 VCO auto-calibration

VCO calibration is performed every time the VCO's center frequency is changed. The following internal sequences are started:

1. Start VCO calibration and turn on PLL lock detection. The output of the lock detection must be gated LOW when the calibration is running.
2. With the next clock cycle: turn on phase frequency detector (bit PFD_ON), prescaler (bit PRESC_ON), clock for PLL (bit CLK_PLL_ON) and PLL lock detection.
3. Perform VCO calibration (select best possible sub-band for desired frequency setting).
4. Check PLL lock detection plus lock detect time.

7.16 TX operation

7.16.1 TX mode

7.16.1.1 Preparation for TX mode

TX mode is initiated by setting the device mode bits DEV_MODE[1:0] to 11b or by sending a TX command. The necessary VCO, PLL and PA start-up is accomplished by the internal state machine. Completion of the start-up sequence is indicated by bit TX_RDY in the special function register DEVSTATUS.

7.16.2 TX command

The power amplifier is activated on the first active edge of the TX command's ninth bit. Therefore, the active edge for the power amplifier start-up differs from the active edge of the remaining SPI communication. This must be considered for the data set-up time of the transmitted bit.

Predefined configurations can be chosen for the TX sequence. The configuration bits are described in [Table 4](#).

Table 4. TX command bits

TA	TB	TC	TD	TE	TF
TX frequency selection bits		data and power amplifier synchronization bit	power amplifier control bit	Manchester generation bit	amplitude selection bit

Table 5. TX command packet

D0	D1	D2	D3	D4	D5	D6	D7
1	1	TA	TB	TC	TD	TE	TF

Table 6. Control of TX data (bits TC, TE)^[1]

TC	TE	Effect
0	0	TX data is unsynchronized (only synchronized to CLK _{REF})
1	0	TX data is synchronized with the baud-rate clock (CLK _{TX})
X	1	TX data is synchronized and XORed with the baud-rate clock (CLK _{TX}), hence Manchester generation is applied

[1] If bit TE = 1, the value of bit TC is ignored and data is always synchronized with the baud-rate clock. However, bit TC has an effect if bit TD = 1. Therefore, bit TC must be properly set even if TE = 1.

Table 7. Power amplifier control and synchronization (bits TC, TD)

TC	TD	Effect
X	0	power amplifier stays on after falling edge of SEN
0	1	power amplifier turns off on the falling edge of SEN (PA off-ramping supported)
1	1	power amplifier turns off synchronously with the baud-rate clock (CLK _{TX}) after the falling edge of SEN (PA off-ramping supported)

Table 8. Summary of combined TC, TD and TE bits

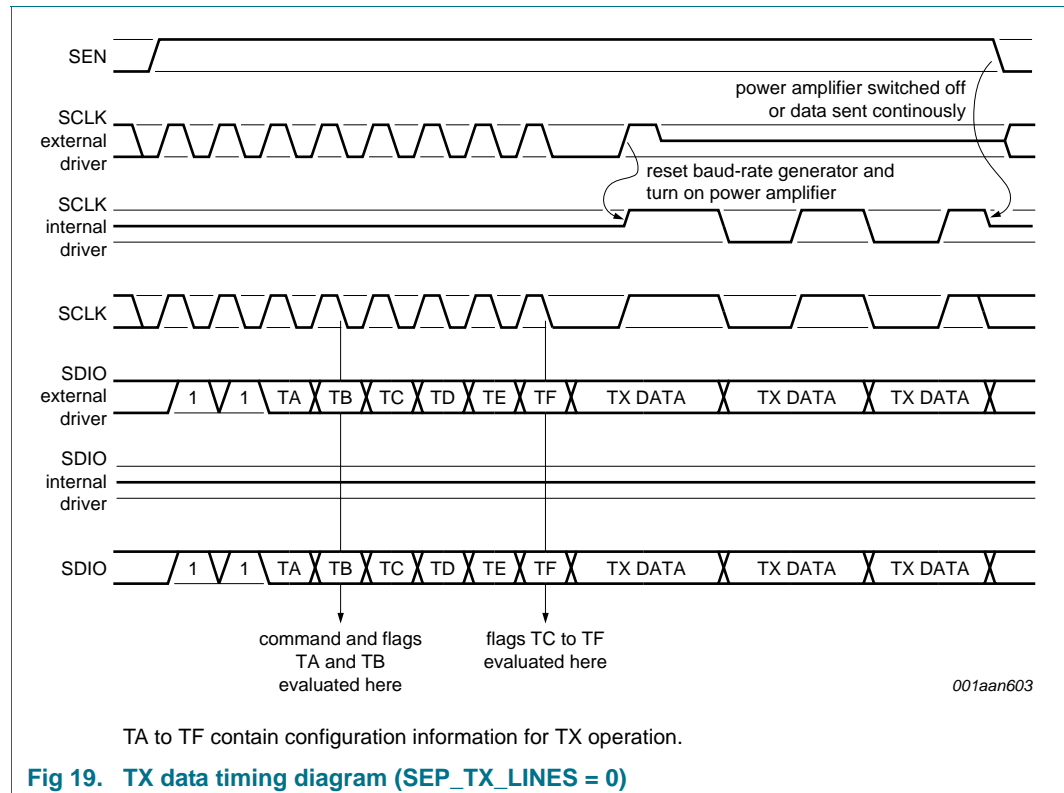
TC	TD	TE	Function
0	0	0	unsynchronized TX data and PA stays on
0	0	1	Manchester coded data and PA stays on
0	1	0	unsynchronized TX data and falling edge of SEN turns off PA
0	1	1	Manchester coded data and falling edge of SEN turns off PA
1	0	0	synchronized TX data and PA stays on.
1	0	1	Manchester coded data and PA stays on
1	1	0	Synchronized TX data and PA turns off synchronously (CLK _{TX}) after the falling edge of SEN
1	1	1	Manchester coded data and PA turns off synchronously (CLK _{TX}) after the falling edge of SEN

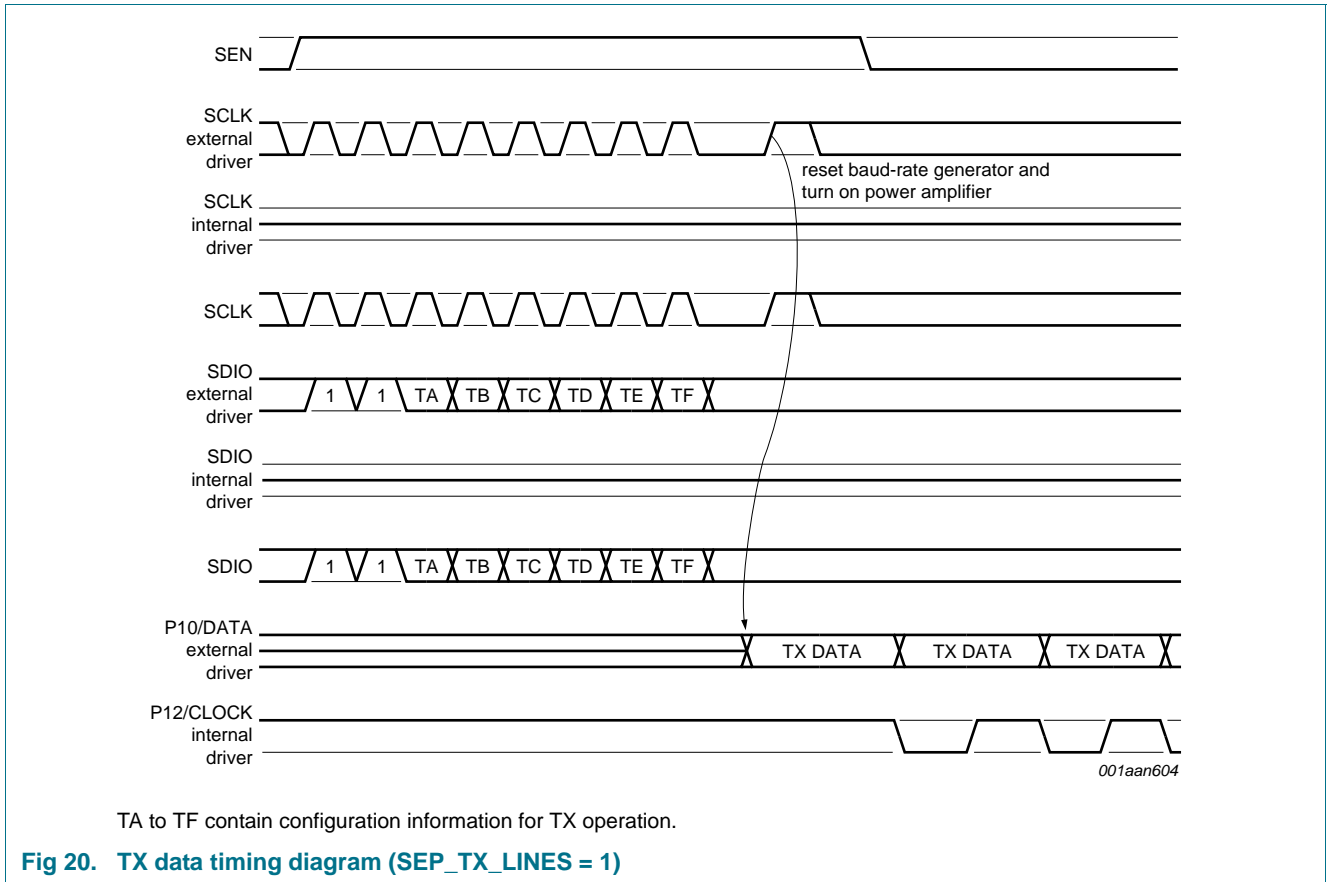
Table 9. Amplitude selection (bit TF)

Bit TF	Effect
0	modulation and amplitude/power settings are applied according to register ACON0
1	modulation and amplitude/power settings are applied according to register ACON1

Table 10. Frequency band selection (bits TA, TB)

Bit TA	Bit TB	Selected frequency band
0	0	FC0L, FC0M, FC0H
0	1	FC1L, FC1M, FC1H
1	0	FC2L, FC2M, FC2H
1	1	FC3L, FC3M, FC3H





7.16.3 Example of synchronized data transmission

Table 11. Phase 1: data transmission

D0	D1	D2	D3	D4	D5	D6	D7
1	1	0	0	1	0	1	0
-	-	selection of frequency configuration register FC0		synchronizat ion of TX data with positive edge of TX clock CLK _{TX}	PA stays on after falling edge of SEN, TX data is stored and continuously sent	Manchester code generation is selected	Modulation and amplitude/power settings of ACON0 are applied

Table 12. Phase 2: end data transmission

D0	D1	D2	D3	D4	D5	D6	D7
1	1	0	0	1	1	1	0
-	-	selection of frequency configuration register FC0		synchronizat ion of TX data with positive edge of TX clock CLK _{TX}	PA turned off in synchronizat ion with TX clock CLK _{TX} after falling edge of SEN	Manchester code generation is selected	Modulation and amplitude/power settings of ACON0 are applied

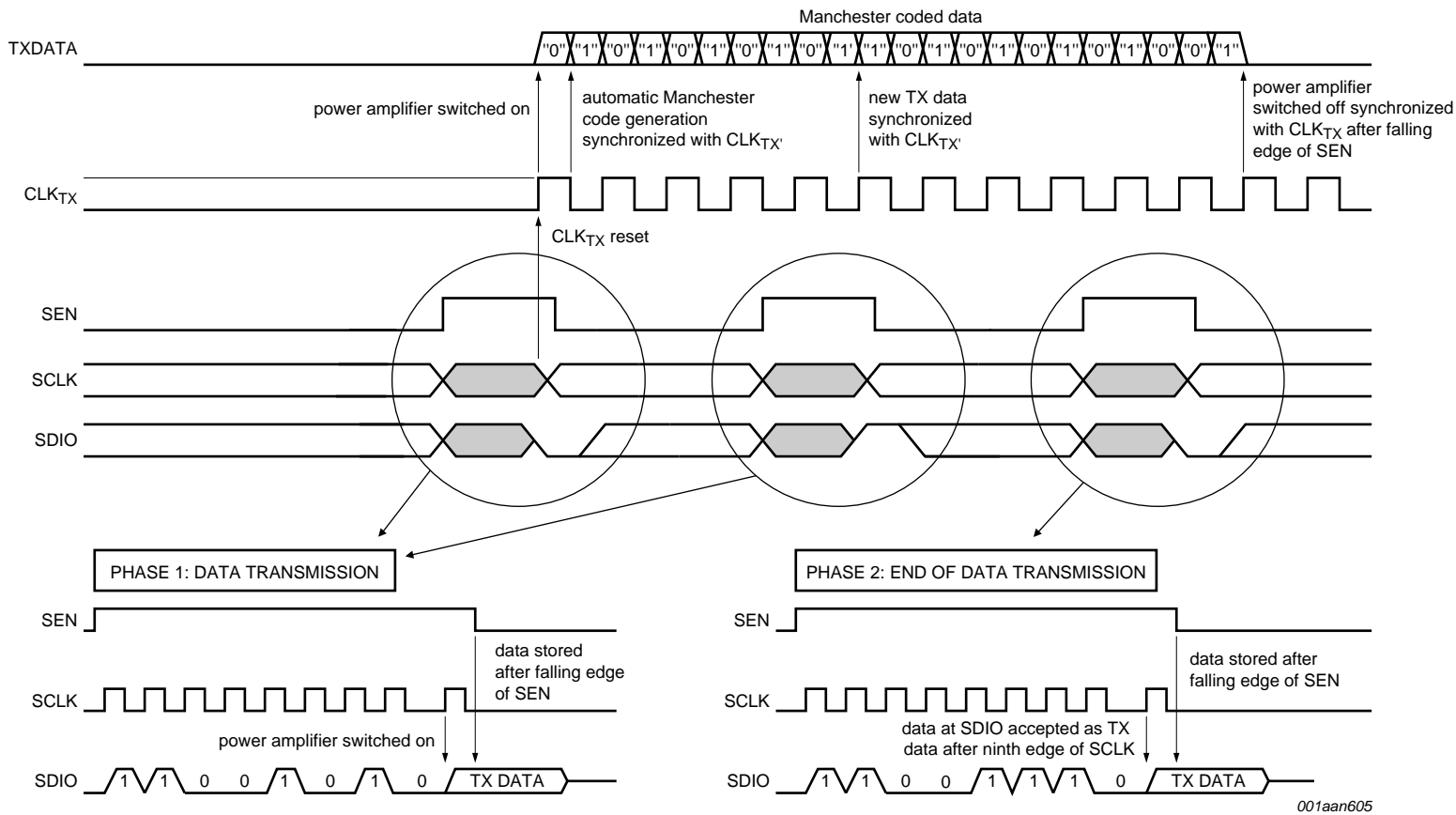


Fig 21. TX data example

7.16.4 Clock output selection for the TX command

The clock output at port pins SCLK or P12/CLOCK respectively, can be selected with the special function bits TXCLKOUTSEL[1:0]. With this mechanism it is possible to provide a faster clock than the actual TX clock CLK_{TX}.

If no clock is selected, TXCLKOUTSEL = 11b and the device behaves as follows; see [Section 8.2.1.23 "Transmitter control register TXCON" on page 107](#):

- SEP_TX_LINES = 0: the output driver of SCLK is never activated

- SEP_TX_LINES = 1: the line P12/CLOCK drives a constant HIGH level; see [Section 8.2.1.9 “Port control register PORTCON2” on page 99](#)

7.17 Power amplifier

The power amplifier is driven from the PLL synthesizer and operates in single-ended mode.

The power amplifier consists of six binary-weighted output stages which are connected in parallel and are operated according to the amplifier control register settings ACON0, ACON1 and ACON2; see [Section 8.2.1.19 “Register ACON0” on page 105](#). Though the PA’s supply voltage is configurable to 3 different voltage settings, it is advised to use only the PAM 0 setting for the majority of applications.

The device features several control bits controlling the output amplitude and ASK modulation characteristics of the power amplifier. The control registers ACON0 to ACON2 control the power amplifier stage for either amplitude fine tuning or ASK modulation. Bit ASK0 located in register ACON0 and bit ASK1 located in register ACON1 determine ASK or FSK operation.

The lower 5 bits of control registers ACON0, ACON1 and ACON2 allow the setting of two different high levels (AMH0 and AMH1) and one low level (AML) respectively, which define the modulation depth during amplitude modulation of the UHF carrier. Which two available AMHx registers is used is selected by TX command flag bit TF. Amplitude modulation is achieved by switching between the selected high and low levels in accordance with the internal signal AMOUT, which is derived from the TX data stream.

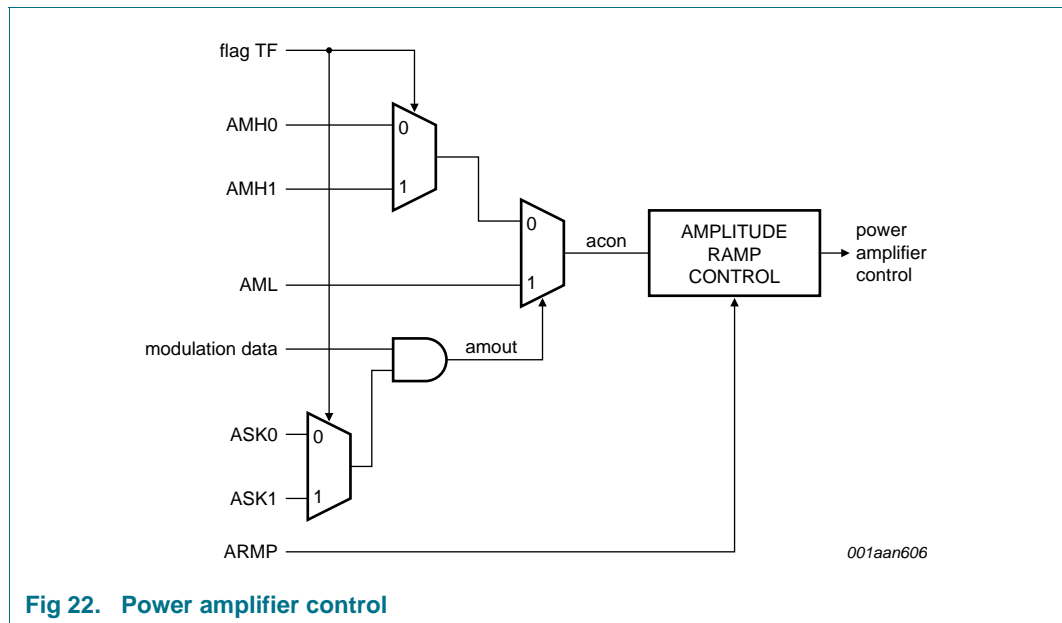


Fig 22. Power amplifier control

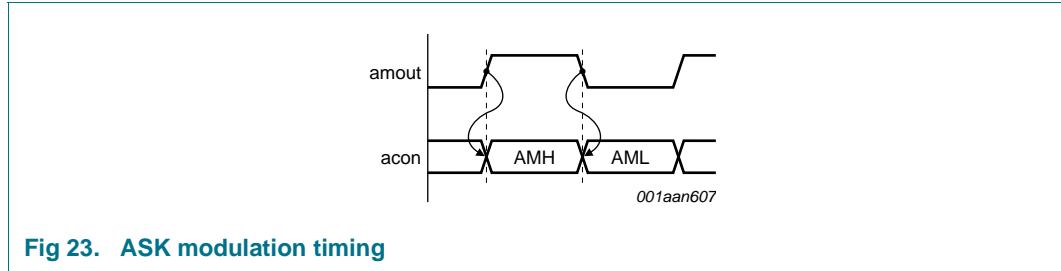


Fig 23. ASK modulation timing

7.18 Soft ASK, ramp control

To achieve a more narrow spectral occupation of the ASK signal, Gaussian ASK-like modulation is implemented. The time-constant defined in the ARMP register defines the ASK signal's up and down ramping time-constant; see [Section 8.2.1.22 "Register ARMP" on page 106](#). This feature is also used for switching on the carrier in FSK applications to achieve best possible electromagnetic radiation values.

Register ARMP sets the number of 16 MHz clock cycles to be used to ramp the ASK amplitude from the lower AML value to the higher AMH value and vice versa. The number of clocks is calculated as $ARMP = ARMP_MANT[4:0] \times 2^{ARMP_EXP}$.

If ARMP_MANT[4:0] is zero, no amplitude ramping is done.

Inverse function:

$$ARMP_EXP = \max\left\{0, \left\lceil \log_2\left(\frac{ARMP}{15.75}\right) \right\rceil\right\} \tag{22}$$

$$ARMP_MANT = \left\lfloor 0.5 + \frac{ARMP}{2^{ARMP_EXP}} \right\rfloor \tag{23}$$

Where ARMP = number of 16 MHz clocks for desired amplitude ramp.

For power-on/power-off ramping, the value is changed between zero and the current AMH or AML value.

The ramp's total duration is shown in [Equation 24](#).

$$ARMP \times \frac{(\lfloor AMH - AML \rfloor - 1)}{f_{ref}} \tag{24}$$

7.19 Power mode control

The PA supply voltage is configurable to three different voltage settings to achieve the best possible power resolution for low power, medium power and high power applications. The PA regulator's actual stabilized voltage can be selected by the PAM[1:0] bits located in the TXCON register; see [Section 8.2.1.23 "Transmitter control register TXCON" on page 107](#). The only recommended PAM setting is PAM 0 (D1 = 0, D0 = 0), with Class E matching. Additional information can be found in the Application note.

7.20 PLL frequency deviation (FSK)

7.20.1 Frequency modulation

FSK and GFSK-type modulation is accomplished by adding a time-varying sequence to the center frequency control value. This variation in the total frequency control value is slow enough to pass the PLL's transfer function and the resulting RF is modulated in frequency; see [Section 7.14.3 "General PLL operation" on page 30](#) for a detailed description of operation.

The FSK path starts by computing the frequency deviation value D from the given FDEV_EXP[2:0] and FDEV_MANT[4:0] values; see [Equation 25](#).

$$D = \left\lfloor 2^{\text{FDEV_EXP}} \times \text{FDEV_MANT} \times \frac{1}{2} \times \frac{1 + \text{RF_LO_DIV}}{1 + \text{DOUBLE_SD_RESULT}} \right\rfloor \quad (25)$$

The RF_LO_DIV and DOUBLE_SD_RESULT bits are included in this expression to compensate for the influence of these bits on the frequency resolution. If the argument of the floor function is an integer, which is the case for all but 72 of the 1024 possible setting combinations, then the result of the floor function equals its argument. In these cases the resulting frequency deviation is independent from the RF_LO_DIV and DOUBLE_SD_RESULT bits.

$$f_{dev} = 2^{\text{FDEV_EXP}} \times \text{FDEV_MANT} \times \frac{1}{2} \times \frac{1 + \text{RLD}}{1 + \text{DSR}} \times \frac{f_{ref}}{32768} \times \frac{1 + \text{DSR}}{1 + \text{RLD}} \quad (26)$$

Note that in [Equation 26](#), DSR and RLD are bits DOUBLE_SD_RESULT and RF_LO_DIV respectively. After canceling out the dependency from these bits we get the following simple result.

$$f_{dev} = \frac{2^{\text{FDEV_EXP}} \times \text{FDEV_MANT}}{65536} \times f_{ref} \quad (27)$$

If the argument of the floor function is not an integer, the result is multiplied with the current frequency resolution, which is equivalent to rounding the result from [Equation 27](#) down to the next available frequency step.

Frequency deviation is calculated as shown in [Equation 28](#) and [Equation 29](#).

$$\text{FDEV_MANT} = \min \left\{ 31, \left\lfloor 0.5 + \left(\frac{\text{FDEV}}{2^{\text{FDEV_EXP}}} \right) \right\rfloor \right\} \quad (28)$$

$$\text{FDEV_EXP} = \min \left\{ 7, \max \left(\left\lfloor \frac{1 + \text{DOUBLE_SD_RESULT}}{1 + \text{RF_LO_DIV}} \right\rfloor, \left\lfloor \log_2 \left(\frac{\text{FDEV}}{15.75} \right) \right\rfloor \right) \right\} \quad (29)$$

Where:

$$\text{FDEV} = 65536 \times f_{dev} / f_{ref}$$

f_{dev} = desired frequency deviation

f_{ref} = reference frequency (16 MHz)

The modulation signal controls the RF output such that a logic 0 produces +D (the high frequency, $f_{RF} = f_{center} + f_{dev}$) and logic 1 selects -D (the low frequency, $f_{RF} = f_{center} - f_{dev}$). If FRMP_MANT is logic 0, the resulting squarewave shaped sequence is the modulating sequence M(t).

7.20.2 Soft FSK

A GFSK-type modulation scheme is implemented to achieve a narrower signal bandwidth of the FSK spectrum. The GFSK shape is modeled by a linear interpolation approach. The FSK frequency shifting is done linearly between $F_{RF} - F_{DEV}$ and $F_{RF} + F_{DEV}$. The linear ramp is implemented by stepping the frequency control value between +D and -D at a step rate (sr), using a step increment (si). Both variables are controlled by FRMP_EXP[2:0] and FRMP_MANT[3:0] according to the expressions in [Equation 30](#) and [Equation 31](#).

$$sr = \frac{f_{ref}}{2^{\min(0, FRMP_EXP-4)} \times FRMP_MANT} \text{ increment/s} \quad (30)$$

$$si = 2^{\min(0, 4-FRMP_EXP)} \text{ steps} \quad (31)$$

When FRMP_EXP[2:0] = 4, the scaling factor for the step rate is 1 and so is the step increment si. When FRMP_EXP[2:0] is greater than 4, the step rate is decreased in powers of two and the step increment is kept at 1. Likewise, when FRMP_EXP[2:0] is less than 4, the step increment is increased in powers of two and the step rate scaling factor is kept at 1. These two dependencies taken together result in a continuous scaling of the ramp's slew rate.

When we multiply these two expressions together, we get the ramp's slew rate in steps per second shown in [Equation 32](#).

$$\text{slew rate} = f_{ref} \times \frac{2^{\min(0, 4-FRMP_EXP)}}{2^{\min(0, FRMP_EXP-4)} \times FRMP_MANT} \text{ steps/s} \quad (32)$$

$$\text{slew rate} = f_{ref} \times \frac{2^{\min(0, 4-FRMP_EXT)-\min(0, FRMP_EXP-4)}}{FRMP_MANT} \text{ steps/s} \quad (33)$$

To find what the soft FSK ramp's slew rate is in terms of Hz/s, we have to multiply the expression in [Equation 33](#) with the frequency resolution shown in [Equation 34](#) and [Equation 35](#).

$$\text{slew rate} = f_{ref} \times \frac{2^{4-FRMP_EXT}}{FRMP_MANT} \times \frac{f_{ref}}{32768} \times \frac{1 + DOUBLE_SD_RESULT}{1 + RF_LO_DIV} \quad (34)$$

$$\text{slew rate} = \frac{(f_{ref})^2}{2048 \times FRMP_MANT \times 2^{FRMP_EXP}} \times \frac{1 + DOUBLE_SD_RESULT}{1 + RF_LO_DIV} \quad (35)$$

If we want to get the FRMP settings from a given slew rate, we need the inverse function.

$$FRMP_MANT \times 2^{FRMP_EXP} = \frac{(f_{ref})^2}{2048 \times \text{slew rate}} \times \frac{1 + DOUBLE_SD_RESULT}{1 + RF_LO_DIV} \quad (36)$$

Soft FSK parameters are calculated as shown below:

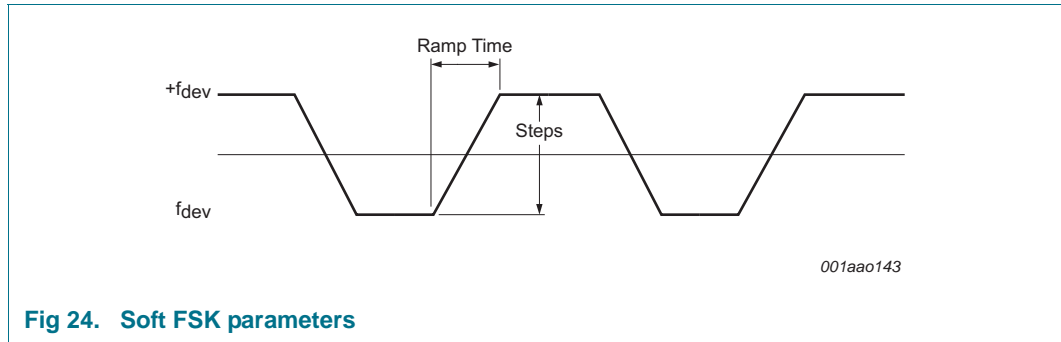


Fig 24. Soft FSK parameters

Given:

f_{ref} = reference frequency (crystal frequency: 16 MHz).

f_{dev} = frequency deviation.

RampTime = wanted time for ramping, to reduce occupied bandwidth.

Search:

FRMP_EXP and FRMP_MANT, in order to program register FRMP.

Calculation:

1. Calculate the frequency resolution: $f_{RF, res} = \frac{f_{ref}}{32768} \times \frac{1 + \text{DOUBLE_SD_RESULT}}{1 + \text{RF_LO_DIV}}$.

DOUBLE_SD_RESULT and RF_LO_DIV can be logic 0 or logic 1 and are described elsewhere in this datasheet.

2. Calculate the frequency steps; see Figure 24: $Steps = \frac{2 \times f_{dev}}{f_{RF, res}}$.

3. Calculate the slew rate: $Slew\ rate = \frac{Steps}{RampTime}$.

4. Calculate the FRMP_EXP and FRMP_MANT:

$$FRMP_EXP = \min\left\{7, \max\left(0, \left\lceil \log_2 \left[\frac{f_{ref} \times 16}{SlewRate \times 7.75} \right] \right\rceil\right)\right\}$$

$$FRMP_MANT = \min\left\{15, \left\lceil 0.5 + \frac{f_{ref} \times 16}{SlewRate \times 2^{FRMP_EXP}} \right\rceil\right\}$$

7.21 Oscillator and divider settings

Different oscillator divider and PLL divider settings can be selected to enable operation at all ISM bands. The configuration information is located in the LOCON register; see [Section 8.2.1.3 "Local oscillator control register LOCON" on page 95](#).

Bit RF_LO_DIV controls the local oscillator's output frequency divider. If this bit is logic 0, the divider divides the VCO frequency by 2 so that the LO produces RF frequencies above 500 MHz; if the bit is logic 1, the divider divides by 4 producing frequencies below 500 MHz.

7.22 Modulation data generation

Depending on the setting of bit SEP_TX_LINES in register PORTCON2, either pin SDIO or pin P10/DATA act as the data input; see [Section 8.2.1.9 “Port control register PORTCON2” on page 99](#). Input data is synchronized to the reference clock CLK_{REF}. This flip-flop serves also as storage for the input data. Input data is sampled under the following conditions.

- Bit SEP_TX_LINES = logic 0: input data sampling starts with the ninth bit of the TX command and stops when the command ends, hence SEN goes LOW. The last input state is stored.
- Bit SEP_TX_LINES = logic 1: input data sampling starts with the ninth bit of the TX command which turns on the power amplifier and stops when the power amplifier is turned off again. Intermediate SPI read, write or TX commands which do not alter the power amplifier's state do not influence data sampling.

The sampled input data is either provided transparently, synchronized to the baud rate or Manchester coded, depending on the current TX flags TC and TE. Baud-rate synchronization and Manchester code generation runs with the TX clock CLK_{TX}. Data is updated with every positive clock edge of CLK_{TX} and, if Manchester coding is selected, it is inverted with the negative clock edge of CLK_{TX}.

The data stream can be optionally inverted by setting bit INV_TX_DATA. This inversion is located after the storage elements. If the stored data is constant, it is possible to alter modulation data by an SPI write access to bit INV_TX_DATA; see [Section 8.2.1.23 “Transmitter control register TXCON” on page 107](#).

7.23 TX operating mode

7.23.1 Power-down

In this mode the device consumes little current and the registers do not change. All transmitter, receiver, clock generator, and amplifier blocks are switched off.

When the power-down state is left (by the rising edge of SEN) the PD bit is cleared.

7.23.2 Idle mode

In this mode the device is powered up. The crystal oscillator or the external clock buffer is enabled and after crystal oscillator stabilization (if selected) the device is supplied with the reference clock.

7.23.3 Active mode

Active mode is entered when the device mode bits are set to anything other than logic 00. The digital regulator and XTAL are always activated. If active mode logic 01 is chosen, the VCO and the PLL are also started. If SPI state is entered, communication between a microcontroller and the registers is enabled via the SPI interface. The active state can be left by programming a register indicating another state or by setting SEN LOW for more than 4 ms.

7.23.3.1 PLL active TX mode

The TX mode is entered on reception of a valid TX command, providing the PLL is settled. Depending on the TX command's content, TX mode exits either directly when SEN is set LOW, or when synchronized with the last data bit's edge when SEN is set LOW or directly on the SPI register setting. The power amplifier is turned on at the ninth bit's first active edge of the TX command. Therefore, the active edge for the power amplifier start-up differs from the active edge of the remaining SPI communication. This must be considered for the data set-up time of the transmitted bit. Any SPI clock following the ninth bit is ignored by the SPI interface. If during a TX sequence a POR or power fail condition occurs, the XTAL active mode is entered. More information can be found in [Section 7.16.2 "TX command" on page 35](#).

7.23.4 Baud-rate generation

The baud rate for the TX data is generated by the baud-rate generator. This baud-rate generator is used for TX and RX operation at the same time; see [Section 7.13 "RX and TX baud-rate generator" on page 27](#) for a detailed explanation.

7.23.5 TX mode clock selection

Depending on the setting of bit TXCLKSEL in register TXCON, different clock sources can be selected; see [Section 8.2.1.23 "Transmitter control register TXCON" on page 107](#). TXCLKSEL = logic 1 selects the baud-rate generator's bit clock. TXCLKSEL = logic 0 selects the chip clock. If Manchester modulation is required, the bit clock is selected. Bit INV_TX_DATA in register TXCON is used to invert the TX data stream.

7.24 RX operation

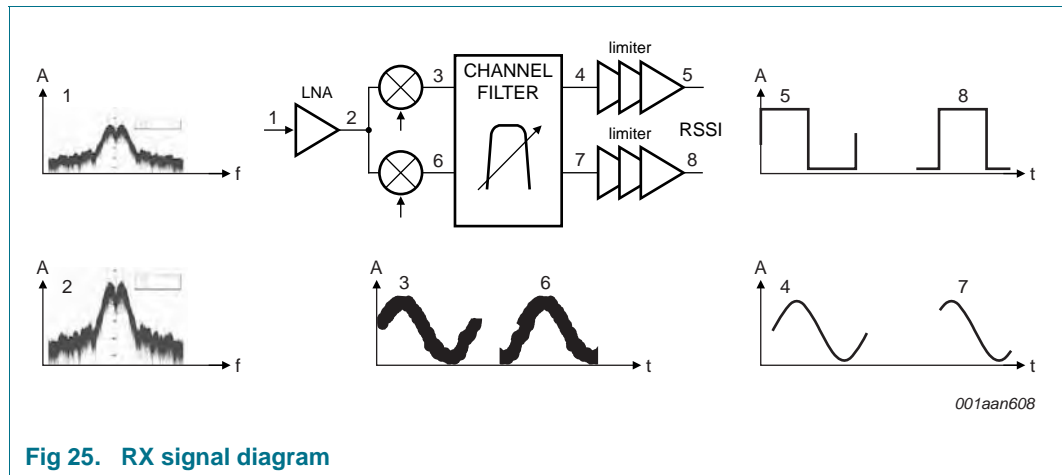


Fig 25. RX signal diagram

[Figure 25](#) visualizes internal signal shapes inside the RX block. Signal 1 represents the signal input spectrum, sketched in the frequency domain. The frequency spectrum is centered to the desired RX frequency. Signal 2 represents the amplified spectrum of the input signal (signal 1). Signal 2 is mixed with the LO frequency (must be set to 300 kHz above the RX frequency) down from the RX input frequency with the I and the Q mixer to the IF (300 kHz). Signal 3 and signal 6 represent the IF signals of the I and the Q channel (90 ° phase difference) in the time domain. Signals 4 and 7 represent the I and Q signals after the channel filter. Signals 5 and 8 are the amplified and limited I and Q signals at the output of the limiter. It is possible to switch some of these internal analog signals to pins

TEST1, TEST2 via bits ANA_TEST_SEL[2:0] in register TEST1. The digital IQ signals of the limiter output, and other digital baseband signals can be accessed via the alternative port functions of P11C and P12C with the appropriate setting of bits DIG_TEST_SEL[2:0] in register TEST0; see [Table 121 “Register TEST0 - \(address 35h\) bit description” on page 126](#) for more details.

7.24.1 General operation

The RX block consists of a fully analog front-end including an analog channel filter. The mixer and channel filter demodulates only one sideband to the IF. The LO frequency (RF VCO frequency) must be set 300 kHz above the expected frequency of the RX signal. The receiver mixes down the RX signal's lower side-band. The LNA gain settings and the channel filter are adjustable to achieve a high dynamic operating range. Field strength detection, automatic gain selection and AM demodulation are implemented via the RSSI information. The RSSI is derived from a limiter. Automatic gain selection is explained in [Section 7.28](#).

Data demodulation is performed in the digital part of the RX chain. The circuit is capable of demodulating ASK and FSK signals. FSK demodulation is applied directly with the analog IF signal from the channel filter. This signal is directly fed into the digital FM demodulator where it is processed further. ASK demodulation employs the RSSI signal which is decoded in the digital part and then further processed. The Data slicer and clock recovery mechanisms regenerate the bit stream for both, ASK and FSK signals.

The OL2381 is able to cope with a 1 % data rate tolerance enabling it to operate correctly with standard XTAL cutting and temperature inaccuracies.

7.25 LNA

The feed from the single-ended antenna is converted to a differential signal at the input of the mixer. The intrinsic voltage gain (from input pin RX to the unloaded LNA) is adjustable to typically 4 dB, 17 dB, 23 dB or 25.5 dB. Two gain settings can be programmed to meet the dynamic range requirements of the receiver chain. In parallel to the LNA gain, the channel filter gain can also be adjusted. The selection of the appropriate gain setting (Hi-gain or Lo-gain) is executed automatically by the gain control loop. The individual gain setting is programmed by the control bits located in the RXGAIN register; see [Section 7.28](#).

7.26 Mixer

The mixer is effectively an active I/Q mixer. It mixes down the amplified signal from the LNA to the 300 kHz IF frequency.

7.27 Channel filter

Channel filter gain and bandwidth can be selected independently with control bits. A well-defined filter bandwidth is achieved using auto-calibration features. The filter bandwidth can be configured by setting bits CF_BW[2:0] in register RXBW. The different adjustable bandwidth settings of the IF channel filter can be found in [Table 75 on page 108](#). The best noise performance is achieved by setting the channel filter's bandwidth as close as possible to the bandwidth occupied by the modulated RX signal.

7.27.1 Channel filter auto-calibration

The channel filter auto-calibration is implemented to achieve a well-centered filter roll-off characteristic in the filter pass-band. This feature can compensate for process and temperature dependent parameter mismatches. Filter auto-calibration is performed automatically before every RX operation.

The calibration can be blocked by setting bit `SKIP_CF_RC_CAL`, and can be forced at any time by setting bit `FORCE_CF_RC_CAL` both in register `TEST4`.

Channel filter calibration status information can be accessed by reading the `CFRCCAL` register. All `CFRCCAL` register bits are read-only.

After starting channel filter calibration, bit `CF_RC_CAL_RUNNING` in register `CFRCCAL` can be probed. This bit is set to logic 1 when the RC calibration algorithm is running.

`CF_RC_CAL_RES[3:0]` indicate the channel RC calibration result. These bits are applied directly to the internal RC components of the channel filter.

Channel filter auto-calibration can be manually overridden by special register `TEST4`. Control bits `CF_RC_ADJUSTCAL[1:0]` allow the accuracy of the channel filter auto-calibration routine to be cross-checked.

Setting bit `SKIP_CF_RC_CAL` by-passes the on-chip RC-calibration. Setting bit `FORCE_CF_RC_CAL` triggers an RC auto-calibration. The corresponding RC calibration values set in `CF_RC_CAL_RES[3:0]` in register `CFRCCAL` after auto-calibration, have to be entered in `MAN_CF_RC_CALVAL[3:0]` in register `TEST4`.

The `CF_RC_ADJUSTCAL[1:0]` control bits can be used to evaluate the on-chip channel filter RC calibration block accuracy. The R part of the RC reference is trimmed by changing the value of these two bits. By knowing the adjusted R variation we can verify that the output of the `CF_RC_CAL_RES[3:0]` control bits is changing accordingly. This enables the complete RC measurement mechanism to be validated.

7.27.2 Channel I/Q calibration

An I/Q calibration is implemented to achieve a high image frequency rejection. This calibration is intended to be used once during production of the final application PCB as part of an end-of-line test. It requires an external signal at the image frequency of the desired RX frequency to be applied to pin RX. The I/Q calibration routine automatically calculates the best I/Q trimming configuration for the optimum image rejection of >50 dBc. This result must be read and stored by the external microcontroller. The calibration value is valid for the whole frequency band over all supply voltages and temperatures.

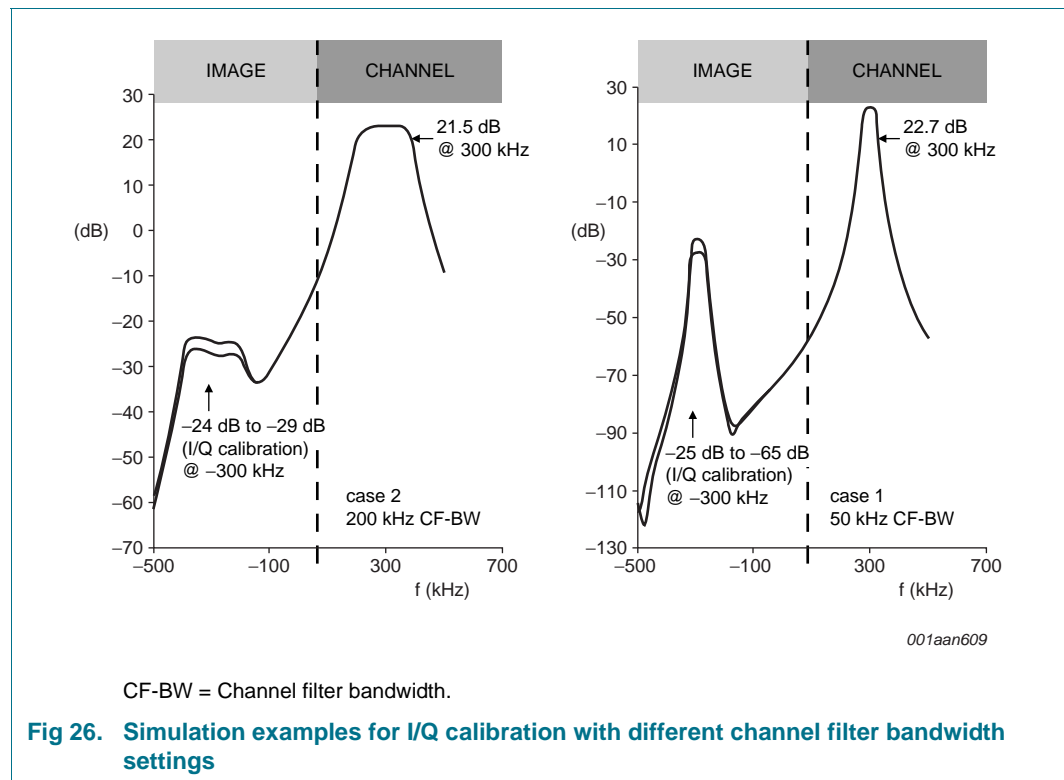
Perform the I/Q calibration as follows:

Apply a signal at the RX image frequency. The signal level must be chosen so that the RSSI is still able to measure the damped image; for example, an input of -40 dBm gives an image at -90 dBm, which is still a sufficient RSSI operating margin.

The I/Q calibration is enabled by setting bit `START_CF_IQ_CAL` in register `CFIQCAL`. Status bit `CF_IQ_CAL_RUNNING` indicates an active calibration cycle. All possible I/Q offset combinations are run sequentially at every combination an RSSI measurement is performed. The combination with the minimum RSSI reading is stored in

CF_IQ_CALVAL[6:0]. This information must be stored by the external microcontroller. Initialize this register with the stored values each time. Set CF_IQ_CALVAL[6:0] to logic 0 if no IQ calibration is required.

Figure 26 shows the effect of a simulated I/Q calibration. With this calibration an image rejection of 50 dB is achievable.



7.28 LNA and channel filter gain settings

Table 13 gives the intrinsic voltage gain of the LNA circuit. LNA voltage gain is programmable and this table indicates the incremental I_{CC} steps impacting RX front-end current consumption.

Table 13. Channel filter gain settings

Channel filter gain 1	Channel filter gain 0	Voltage gain (dB)
0	0	-2
0	1	17
1	0	22
1	1	27

Table 14. RX gain control

LNA gain 1	LNA gain 0	Gain (dB)	LNA input stage typical current (mA)
0	0	4 ⁽¹⁾	0.55

Table 14. RX gain control ...continued

LNA gain 1	LNA gain 0	Gain (dB)	LNA input stage typical current (mA)
0	1	17	0.55
1	0	23	1.1
1	1	25.5	1.65

[1] LNA low gain stage.

Voltage gain induced by an impedance transformation network (from antenna to input pin RX) needs to be added to the values in Table 13 (such as 6 dB extra gain in case of ideal 50 Ω to 200 Ω impedance transformation) to compute the overall RX front-end voltage gain.

The RX analog chain voltage gain (before limiter) can be performed by adding these values to those of the channel filter given in Table 13.

Figure 27 and Figure 28 show the field-strength as a function of gain switching.

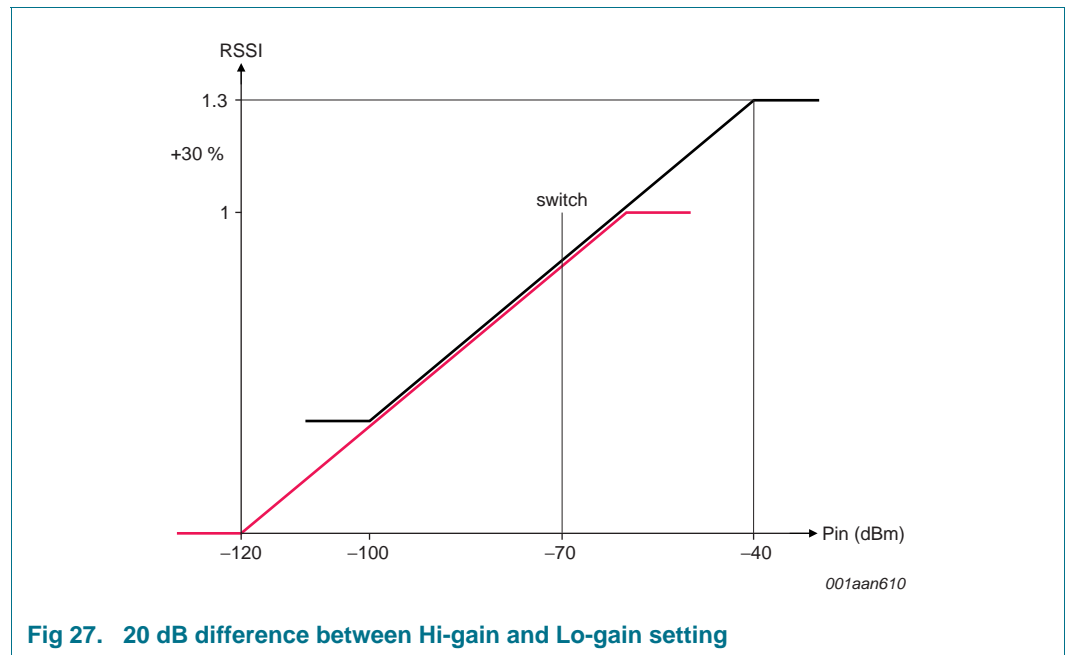


Fig 27. 20 dB difference between Hi-gain and Lo-gain setting

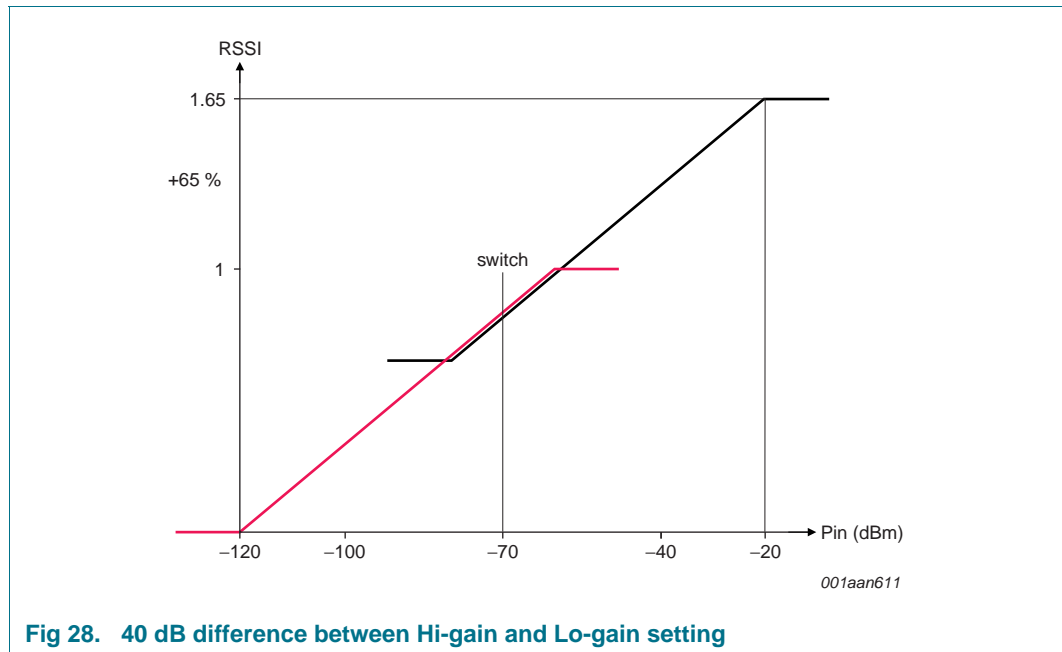


Fig 28. 40 dB difference between Hi-gain and Lo-gain setting

7.29 Limiter

The function of the limiter is to amplify or limit the input signal so that the output voltage of the last stage of the limiter is always constant. This applies to both very small signals at the sensitivity limit and very large input signals. The limiter block consists of 5 gain stages for each channel (I and Q). The limiter output signal of the last stage can be seen as a rail-to-rail square signal. Two limiter chains are implemented. One chain limits the I-signal, the other is used to limit the Q-signal. These square wave signals are used for FM demodulation in the baseband signal processing section. Therefore the limiter can be interpreted as a one-bit ADC directly connected to the digital section. The analog output signal levels of the individual limiter stages are used in conjunction with the RSSI block to measure the RX signal strength on a logarithmic scale.

7.30 Limiter block filter cut-off frequency

The following cut-off frequencies are selected after allowing for the IF frequency of 300 kHz, and a maximum bandwidth of 300 kHz:

- high-pass cut-off frequency < 100 kHz
- low-pass cut-off frequency > 500 kHz

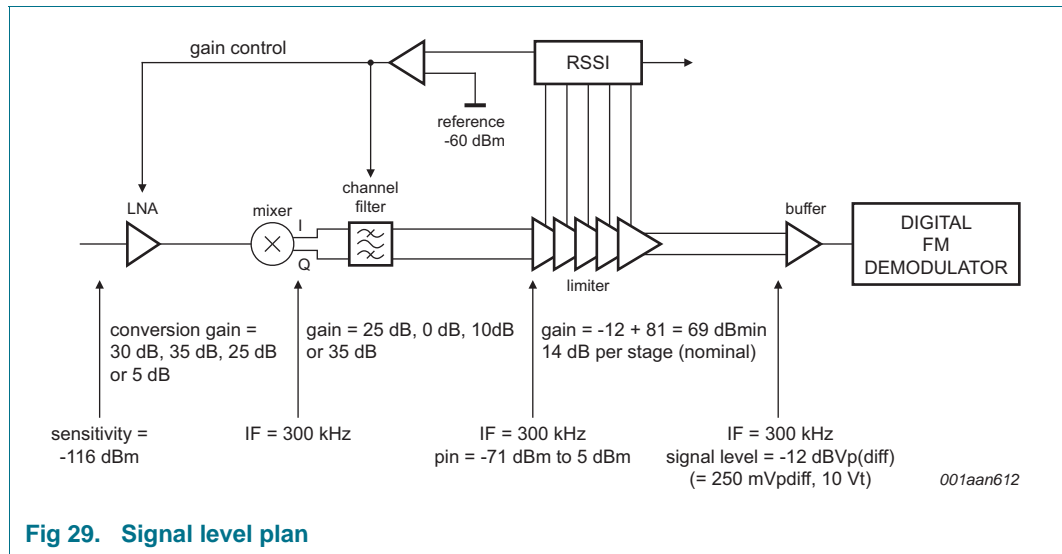


Fig 29. Signal level plan

7.31 RSSI

The RSSI function is implemented by adding tail currents used in the individual limiter stages. This does not apply to levels higher than the compression point. In this case the gain of the LNA and channel filter is reduced to increase the linearity and the dynamic range of the RSSI.

Remark: As the RSSI is proportional to the input voltage level having a frequency of 300 kHz, it must be filtered to ensure a stable result as the input voltage. The RSSI frequency is 600 kHz due to the nature of the RSSI detector principle.

7.31.1 Dynamic range and operation

The RSSI's dynamic operation is required for ASK demodulation and carrier detection. An overall dynamic range of 130 dB is required, -120 dBm minimum sensitivity up to +10 dBm maximum signal strength. The front-end gain can be switched. An overlap of the dynamic ranges of 20 dB is recommended to guarantee continuous ASK demodulation. This results in a single range of 70 dB. The RSSI value can be used to reduce the power output of a TX operation. The RSSI value can be included in the handshaking information with appropriate TX power settings applied.

7.31.2 Resolution

The resolution is set to ±2 dB in all conditions. A 6-bit converter is implemented to allow for process and temperature variations.

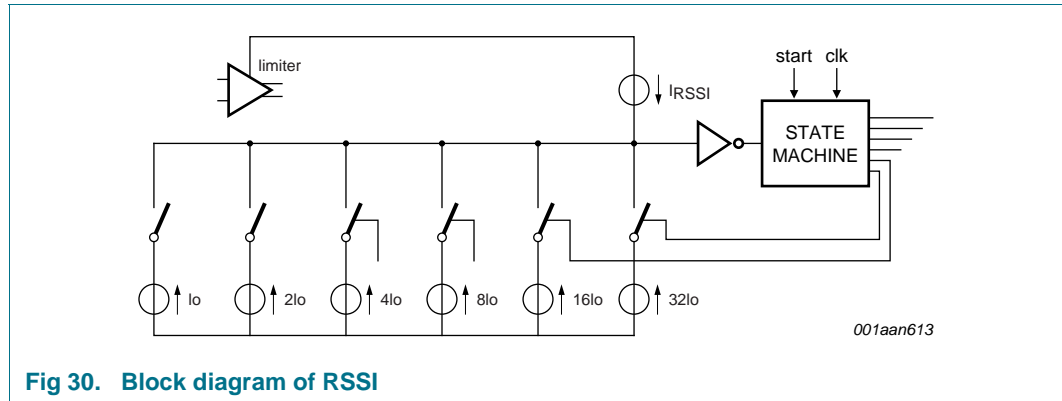


Fig 30. Block diagram of RSSI

7.31.2.1 RSSI low-pass filtering

The filter integration time-constant of the analog RSSI signal can be adapted to achieve a more stable digital RSSI reading (RSSI raw value) as an input to the digital filtering and interpolation. The RC-type analog filter is used in addition to the digital filters implemented in the baseband digital signal processing unit. This first order low-pass filter is applied directly to the summed output of the limiter tail-currents. The limiter gain bandwidth characteristics are not affected.

7.31.2.2 RSSI digital filtering

The raw RSSI value is fed to a digital filtering and interpolation circuit. The output of the digital circuit is the digitized RSSI value. The digital RSSI filter cut-off frequency can be selected by bits RSSI_FILTER_FC[3:0] in register RXBW.

The first-order low-pass filter previously mentioned cut-off frequency can be calculated according to the Equation 37.

$$f_c = \frac{f_{ref}}{2\pi \times 2^{5+RSSI_FILTER_FC}} \tag{37}$$

Where f_{ref} is the reference frequency and RSSI_FILTER_FC[3:0] is a 4 bit value in register RXBW; see Section 8.2.1.25 “Channel filter bandwidth and RSSI filter settings register RXBW” on page 108.

7.31.2.3 Low-level signal detection

The RSSI is used to detect the start of a communication sequence. Carriers at a sensitivity level as low as -110 dBm are detected properly.

7.31.3 RSSI gain control

The automatic front-end gain selection switching threshold is controlled by the RSSI’s output signal. This principle decreases the gain of the front-end and, if necessary, the channel filter when the input level is significantly greater than the reference sensitivity level. This gain switching increases the linearity of the overall chain and the robustness for large signal behavior and also increases the RSSI’s dynamic range.

Register HIGAINLIM contains control word HI_GAIN_LIMIT[7:0]; see Section 8.2.1.27 “Register HIGAINLIM” on page 109. At power-up the front-end gain is always set to the value of RX_HI_GAIN[4:0] in register RXGAIN, so that the RSSI operates in its most sensitive mode; see Section 8.2.1.24 “Receiver gain control register RXGAIN” on page

[108](#). If the gain switching is enabled during wakeup-search, the gain is reduced to the RX_LO_GAIN[3:0] setting provided the RSSI threshold set by HI_GAIN_LIMIT[7:0] is exceeded. The RSSI reading is performed automatically during the wakeup-search detection.

Remark: If the input signal level is above the switching threshold and the gain-switching is initiated, two bits are lost due to the switching event. The length of the wakeup and the preamble must be chosen accordingly to guarantee safe operation. The minimum length of preamble must be 8 bits; the bit time of two bits is necessary to start the receiver and to perform the necessary RSSI measurement. Two bits may be lost due to RSSI switching, and a minimum of 4 bits are required to detect the preamble correctly and to synchronize the clock recovery. This is true only when using the edge slicer, more time may be required when using the level-sensitive slicer.

The result of the RSSI conversion can be retrieved in status register RSSILEVEL; see [Section 8.2.2.12 “Register RSSILEVEL” on page 122](#).

A compensation value can be set in the GAINSTEP register to achieve a continuous RSSI reading when the front-end gain is changed; see [Section 8.2.1.26 “Register GAINSTEP” on page 109](#). RSSI_GAIN_STEP_ADJ[6:0] in register GAINSTEP represents the difference between the gain values set in RX_HI_GAIN[4:0] and RX_LO_GAIN[3:0] for the corresponding RSSI read value. The RSSI_GAIN_STEP_ADJ[6:0] value is added to the RSSI conversion result when RX_LO_GAIN[3:0] is activated. This yields an RSSI overall dynamic range of more than 120 dB.

7.32 Receive mode

7.32.1 Preparation for RX mode

The device initiates RX mode upon the correct setting of DEV_MODE[1:0] in register PWRMODE. This, in turn, sets internal enable bits PLEN and RXEN.

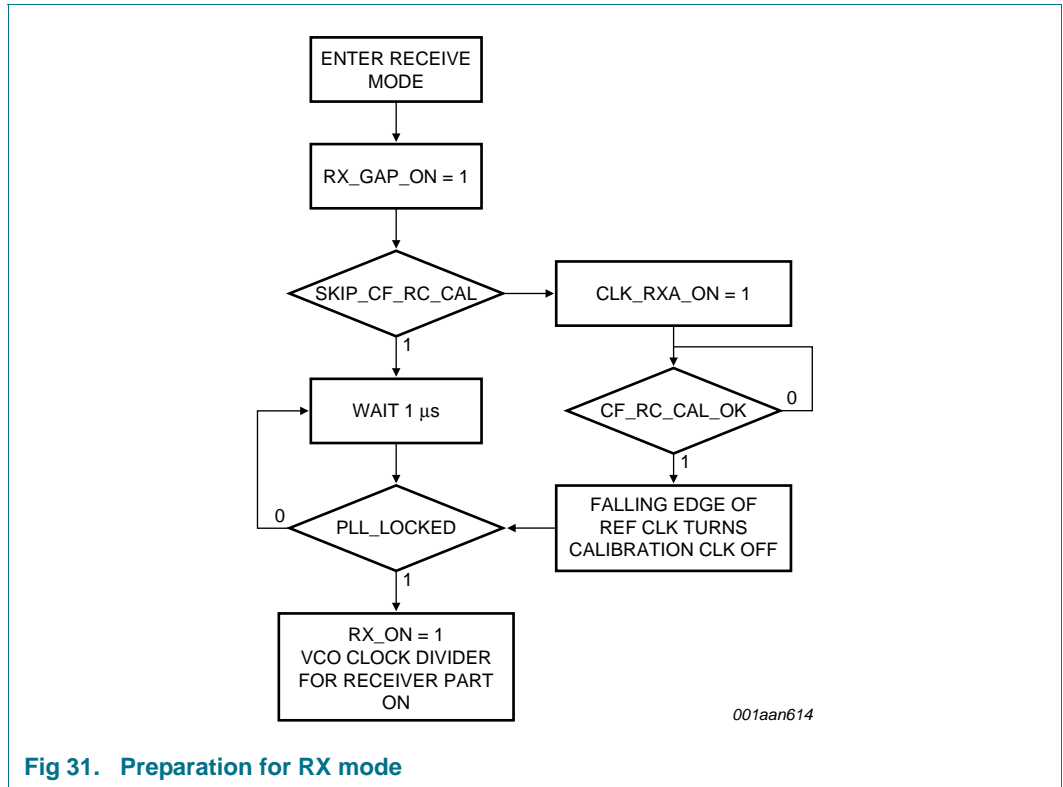


Fig 31. Preparation for RX mode

1. Turn on the bandgap reference circuit for the receiver section (bit RX_GAP_ON) and the clock for the channel filter RC calibration (CLK_RXA_ON) with the negative edge of the reference clock. The latter is done only if the channel filter RC calibration is not skipped (bit SKIP_CF_RC_CAL). Then wait 1 μs until the bandgap stabilizes.
2. If the channel filter RC calibration is enabled, start it and then wait until it ends. Then turn off the clock for the RC calibration at the next falling edge of the reference clock.
3. Wait until the PLL control-state machine reaches the state PLL_LOCKED and then turn the receiver on (bit RX_ON), which also turns on the VCO clock divider in the receiver section.

This sequence ends with the channel filter RC calibration, if enabled. When this ends, the receiver is turned on.

7.32.2 Receive command

The device features a RX command comparable to the TX command. The command includes the six command bits RA, RB, RC, RD, RE and RF:

- RA, RB: RX frequency selection bits
- RC, RD: sub-command bits
- RE, RF: gain step/switch selection bits

Table 15. Receive command packet

D0	D1	D2	D3	D4	D5	D6	D7
1	0	RA	RB	RC	RD	RE	RF

Table 16. Frequency selection (bits RA, RB)

Bit RA	Bit RB	Selected frequency band
0	0	FC0L, FC0M, FC0H
0	1	FC1L, FC1M, FC1H
1	0	FC2L, FC2M, FC2H
1	1	FC3L, FC3M, FC3H

Remark: In RX mode a frequency offset of +300 kHz is automatically added to the resulting center frequency to account for the necessary LO frequency offset. If this is the first RX command after a TX operation or whenever these flags change from one RX command to another, an LO sub-band calibration (VCO calibration) is initiated.

Table 17. Sub-command selection bits RC, RD

Bit RC	Bit RD	Selected RX sub-command
0	0	CONT (continue)
0	1	WUPS (wakeup search)
1	0	PRDA (preamble detection followed by data reception)
1	1	DATA (data reception without preamble detection)

With a CONT RX command, the microcontroller can continue with any previously initiated WUPS, DATA or PRDA command. If the frequency selection bits RA and RB are the same as in the previous RX command and if the flags RE and RF are both logic 0, then, with the next rising edge of SCLK, only the RX clock and the RX data lines are switched to the SPI SCLK and D(I)O pins, respectively. This provides the microcontroller with the possibility to interlace SPI Read and Write commands with RX data, provided that the SPI communication rate is much faster than the data reception rate. If no RX operation is in progress, no initiation occurs, and the CONT RX command only switches the SPI lines with the next SPI clock edge, and delivers the internal RX result. The RX result can be the recovered chip clock and the transparent slicer signal or just a constant level, depending on the current RX output configuration and depending on the RX state.

A WUPS RX command initiates a wakeup search operation. This command's restart characteristics enable it to interrupt any RX operation. During this command the RXDCON0 configuration is applied as the dynamic configuration for the slicer and signal classification and detection; the RX clock and data result can be observed with the SPI lines producing a constant HIGH on the clock line and a constant LOW on the data line in digitized mode. This output (not the wakeup search operation itself) can be interrupted with Read and Write commands and can be continued with a CONT RX command. The WUPS command ends after either a WAKEUP_FOUND or a WAKEUP_NOT_FOUND decision. In both cases the status of the detection method is sampled. When the WUPS command ends, the WUPS_FOLLOWUP configuration dictates how the device operates; see [Table 20 "RX operating mode transitions" on page 61](#).

A PRDA RX command initiates a preamble detection. This command's restart characteristics enable it to interrupt any other RX operation. During this command the RXDCON1 configuration is applied as the dynamic configuration for the slicer and signal classification and detection method; the RX clock and data result can be observed with the SPI lines producing a constant HIGH on the clock line and a constant HIGH on the data line during preamble detection in digitized mode. This output (not the preamble

detection operation itself) can be interrupted with Read and Write commands and can be continued with a CONT RX command. When the correct preamble is detected, the receiver switches automatically into data reception mode. This switch does not influence the signal processing section of the receiver, which means that there is a seamless transition from the preamble detection mode to the data reception mode. What changes with the switch is the dynamic part of the configuration and the state of the signal detection and classification means. The dynamic configuration for the signal detection and classification method is switched to the RXDCON2 set and the detection methods are restarted.

If the preamble detection ends with a PREAMBLE_NOT_FOUND status (after running into a timeout), the PREA_FOLLOWUP configuration automatically decides if and how the receiver operates; see [Table 20 “RX operating mode transitions” on page 61](#). Regardless of the outcome of the preamble detection phase (found or timeout) the status of the detection method is sampled when the preamble detection ends.

If the digitized RX output format is selected for the RX clock and data, both are held constant while the preamble detection is in progress. When the preamble is detected, the RX clock starts and the associated RX data bits are delivered with each RX clock pulse. In transparent mode the output signals are always available.

A DATA RX command initiates the reception of frame data and skipping the preamble detection phase. This command always uses the RXDCON2 set as the dynamic configuration for the slicer and the signal detection and classification methods. After initializing the slicer it behaves similar to the PRDA command after successful preamble detection.

Both the PRDA command in data reception mode and the DATA command do not end automatically on any selectable criteria. They can be terminated with either a TX command or another restarting RX command, or by turning the receiver off.

Table 18. Gain switch selection (bits RE, RF)

Bit RE	Bit RF	Selected gain step/switch configuration
0	0	keep RX gain as is
0	1	gain switch (WUPS sub-command only), same as logic 00 for other sub-commands
1	0	use low gain settings
1	1	use high gain settings

The combination logic 01 (gain switch) is only applicable with the wakeup search (WUPS) RX command. If this is chosen, the wakeup search starts with the high gain settings. If the received RF signal strength is always below the limit given by the HI_GAIN_LIMIT settings, then the low gain settings are used throughout the whole wakeup search. But if the RF amplitude exceeds this limit, the receiver automatically switches to the low gain settings and continues with the wakeup search. Note that the wakeup search timer is not influenced by the gain switch.

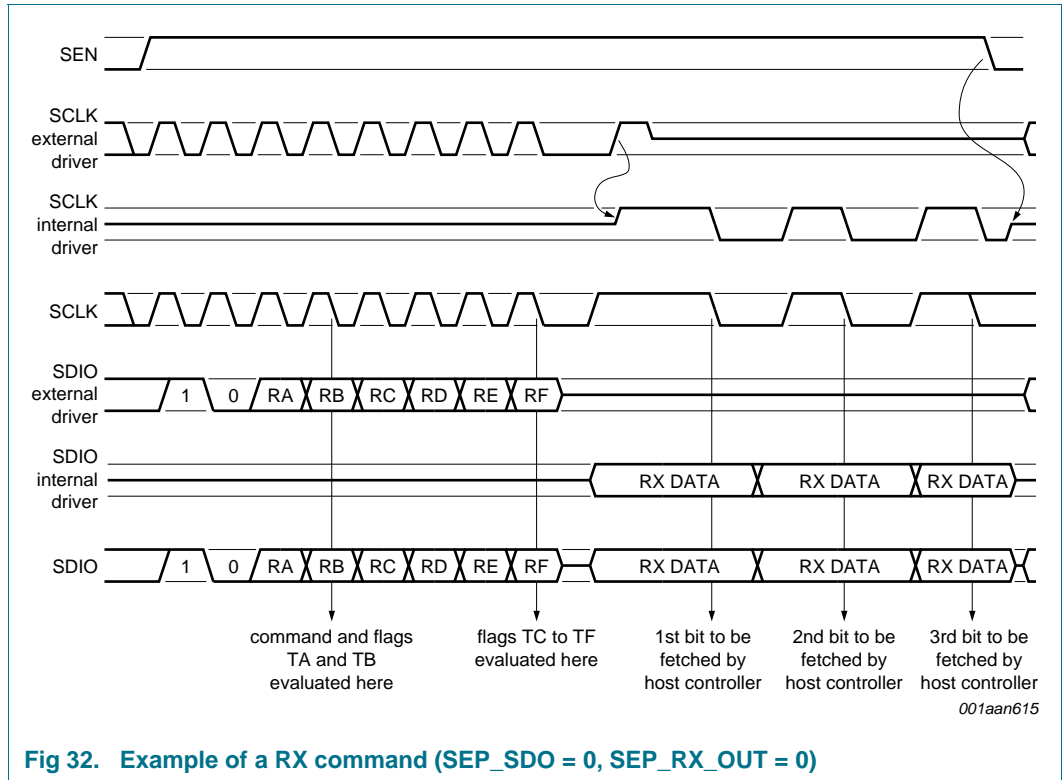


Fig 32. Example of a RX command (SEP_SDO = 0, SEP_RX_OUT = 0)

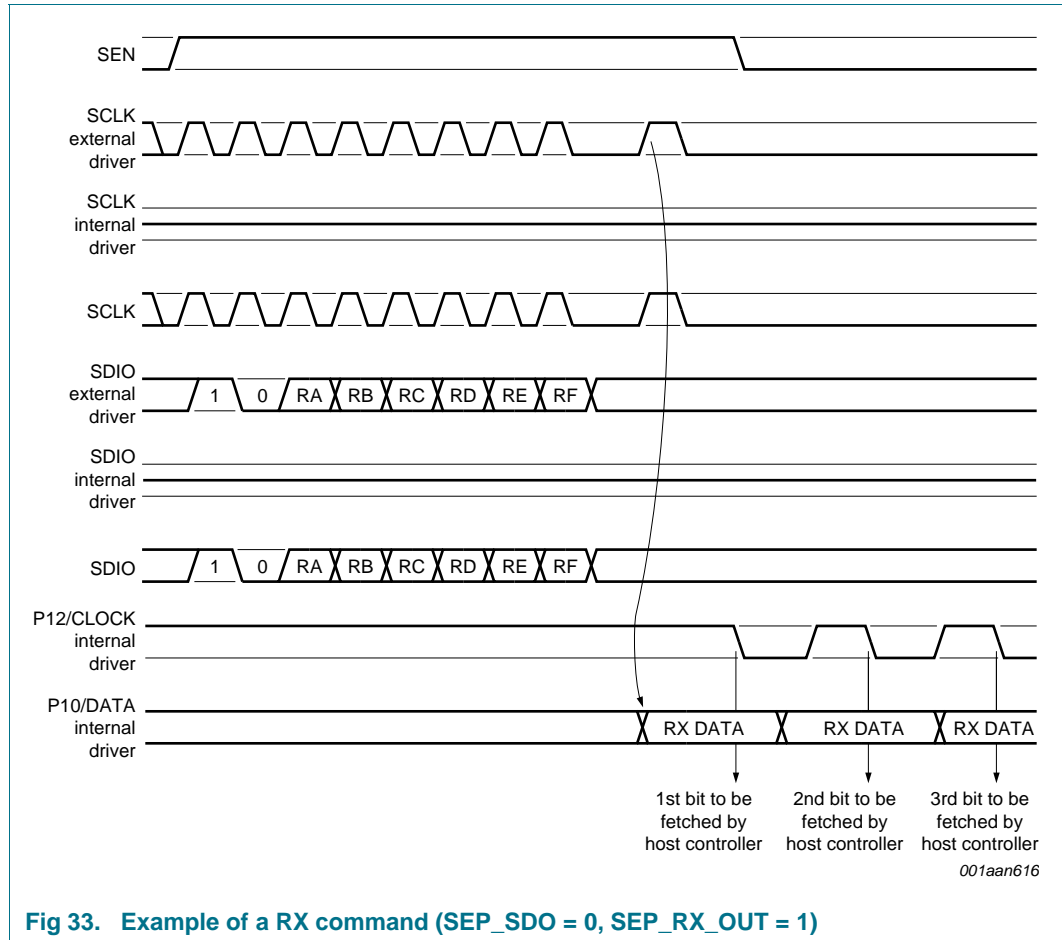


Fig 33. Example of a RX command (SEP_SDO = 0, SEP_RX_OUT = 1)

From a sequence and timing point of view the RX command behaves as follows:

The DEV_MODE is set to logic 10 (RX mode) on the falling edge of the SPI clock after receiving the 4th bit (flag bit RB) of the command. The new frequency setting is applied according to the flag bits RA and RB, which is shared with the TX command. The LO is initialized at this frequency and the receiver remains switched on even if the RX command is aborted. A 4-bit command can be used to turn the receiver on and to switch the LO frequency. A new calibration of the VCO sub-band, provided it is enabled, and a new PLL lock-in occurs under the following conditions.

- upon receipt of the first RX command after a TX operation
- the first RX command after powering up the device
- the frequency settings are changed with respect to a previous RX command

The next relevant action occurs upon receiving the 8th bit (flag bit RF) of the command on the SPI clock's falling edge. This latches the remaining flags (RC to RF) into the RX flag register. Please note that the receiver state machine is still not influenced after receiving the full command byte. This gives the microcontroller the chance to wait until the analog section of the receiver settles fully before executing the command from a sequence point of view.

The command is initiated on the next rising edge of the SPI clock. In the case of a WUPS, a PRDA or a DATA RX command, this brings the receiver state machine to the respective starting point of the sub-command. If a CONT RX command is issued, the receiver state machine is not influenced. The SPI clock's rising edge also switches the RX clock onto the SCLK line after a programmable delay (CLK2SCLK_DELAY[4:0]) and the RX data output is immediately switched onto the SD(I)O line. This delay takes effect when switching the SPI line SCLK with a TX or RX command into the mode, where it changes its direction to output. In this mode it delivers the TX or RX clock, respectively. The delay starts with the next positive edge of the reference clock following the 9th edge of SCLK (activation edge). After the delay the output driver of SCLK is activated.

The delay value is $(\text{CLK2SCLK_DELAY} + 1) / f_{\text{ref}}$, where CLK2SCLK_DELAY[4:0] can be set to a value in the range 0 to 15. So if the 9th edge of SCLK occurs just before the positive edge of the reference clock and if CLK2SCLK_DELAY[4:0] is set to logic 0, the minimum delay is 1 reference clock cycle (62.5 ns at 16 MHz). If the 9th edge of SCLK occurs just after the positive edge of the reference clock and if CLK2SCLK_DELAY[4:0] is set to 15, the maximum delay is 17 reference clock cycles (1062.5 ns at 16 MHz); see [Section 8.2.1.3 "Local oscillator control register LOCON" on page 95](#).

If digitized RX output mode is configured, the clock output delivers a constant HIGH state during wakeup search and during preamble detection. The output starts toggling during data reception according to the recovered RX clock. The data output behaves in a similar way to digitized mode, the only difference is that it is in LOW state during wakeup search operations.

If transparent RX output is configured (see register RXCON), the clock and data output always delivers the recovered chip clock and the deglitched slicer output, respectively.

7.32.2.1 Dynamic receiver configuration

It is not always appropriate to have a fixed setting for all aspects of the receiver configuration for a given protocol. This is illustrated in the following two examples:

- If the transmitter sends its frames continuously without RF interruption, then it makes sense to initialize the slicer at the start of the wakeup search but to skip the slicer initialization at the start of the preamble detection in order to save time.
- If Manchester encoded data is to be received then the modulation amplitude detection must be configured to allow single signal gaps which occur at data bit transitions (01 or 10). But if the wakeup pattern is a constant Manchester encoded 000... or 111... pattern, allowing no signal gaps increases discrimination precision.

To be able to manage these scenarios whilst minimizing the loading of the external microcontroller, a so-called dynamic device configuration can be implemented. This dynamic device configuration is controlled with the following control bytes.

Table 19. RXDCON registers

Register	Nomenclature
RXDCON0	wakeup search settings
RXDCON1	preamble-detection settings
RXDCON2	data reception settings

The relevant register is automatically selected depending on whether the receiver is in wakeup search mode, preamble detection mode or in data reception mode. The settings of SLICERINITSEL[1:0] and INIT_ACQ_BITS[1:0] make two individual alternative configuration sets available because only one slicer initialization is necessary for the combined preamble detection and data reception operation.

It is possible to chain all these device modes together, employing individual device configuration settings automatically. This is especially useful when the first command is initiated from a polling timer event where the receiver can work in parallel to the wakeup of the microcontroller.

Table 20. RX operating mode transitions

First operation	After wakeup search				After preamble detection			
	polling timer		command		polling timer		command	
Initiated by	polling timer		command		polling timer		command	
Success(+)/fail(-)	+	-	+	-	+	-	+	-
Power-down	-	[1]	-	[1]	-	[1]	-	[1]
Stop	[1][2]	[1][2]	[1]	[1]	-	[1][2]	-	[1]
DATA	[1][2]	-	[1]	-	[1][2]	-	[1]	-
PRDA	[1]	-	[1]	-	-	-	-	-
Bit (field) name	WUPS_FU _TS	WUPS_FU _TF	WUPS_FU _CS	WUPS_FU _CF	-	PREA_FU _TF	-	PREA_FU _CF
follow-up configuration name	WUPS_FOLLOWUP				PREA_FOLLOWUP			

[1] A possible operating mode transition.

[2] A non-maskable interrupt is generated.

Table 20 can be used to determine the configuration of the RXFOLLOWUP register; see Section 8.2.2.9 “Register RXFOLLOWUP” on page 119. Note that an interrupt may be generated when a wakeup search or a preamble detection ends. All other interrupts can be enabled with the interrupt enable register.

7.33 Signal signature recognition unit

The signal signature recognition unit provides a user-friendly and easy method to support quick and configurable RX tools. The basic challenge in RX mode is to distinguish noise or unwanted disturbers from the wanted RX signal. This signal quality decision must be taken within the shortest time possible to save system power consumption. The RX process must start after successful signal quality detection. The RX process basically consists of data and clock regeneration. To make the system even more robust to ambient noise and/or disturbers, the data and clock recovery can be gated by additional methods. If the baud rate and the coding of the RX signal is known, a wakeup pattern matching unit can be activated. Table 21 gives a comprehensive overview of the various available units. All units are individually selected and configured.

Table 21. Overview of the signal signature recognition unit

Recognition unit	Block name	Signal process	Started by	Purpose
RSSI level classification	RSSI level classification	digitized RSSI	-	determine correct signal strength; upper and lower limit can be defined
Modulation amplitude classification	modulation amplitude classification	demodulated baseband	start of wakeup search	determine correct FSK/ASK modulation amplitude
Data classification	slicer	demodulated baseband	start of wakeup search, only if initial acquisition is enabled	enable selection for different data slicer behavior (fast settling, long averaging, hold of previously acquired levels)
	chip timing verification and code checker	slicer output	slicer output valid after start of wakeup search	decode and search for correct Manchester coding and special coding sequences
	baud-rate checker	slicer output	FIRST_SYNC or RESYNC of the timing verification after start of wakeup search	check for correct baud rate
	preamble checker	slicer output	end of wakeup search	configurable 1-to-32 bit preamble pattern matching
Wakeup search timer	wakeup search timer	-	start of wakeup search	start/end of recognition sequence

7.33.1 RSSI level classification

The RSSI circuit is used for ASK demodulation, for determining the front-end gain switch threshold and for signal level detection. Two different application scenarios can be supported by a level detection circuit.

- Check for a carrier signal strength within a given threshold, i.e. above a minimum level or below a maximum level or between minimum and maximum
- Check for a carrier signal strength outside a given threshold, i.e. below a minimum level or above a maximum level

The first scenario can be used to determine the presence of a carrier as a precondition for other demodulation or classification measures. The second scenario is useful to quickly check for occupied channels in a multi-channel system.

The RSSI classification unit is a window comparator with programmable threshold values.

7.33.1.1 Functional block diagram

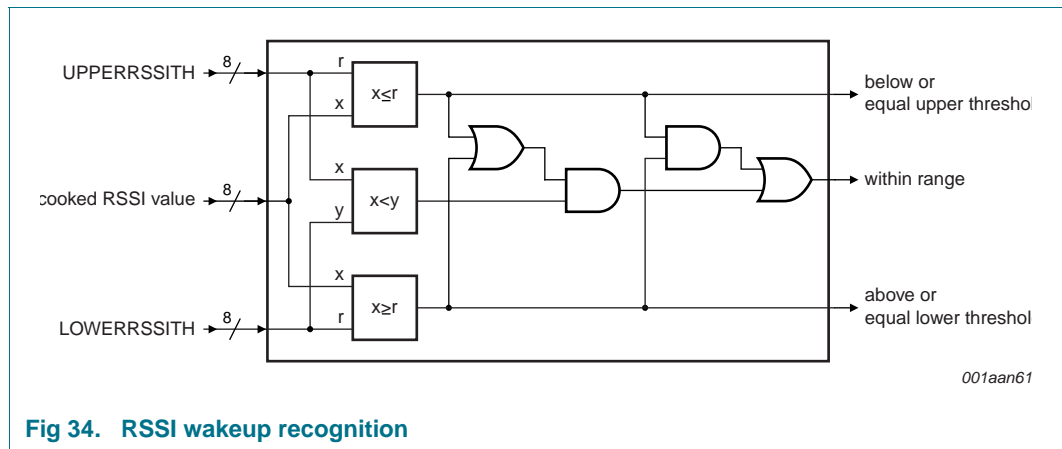


Fig 34. RSSI wakeup recognition

Input signals:

- 8-bit digitized RSSI value
- 8-bit upper limit of the desired RSSI range
- 8-bit lower limit of the desired RSSI range

Output signals:

Two individual signals, which indicate whether the input signal is above or below the respective threshold; these two indicators are provided as (latched) status information.

The logic combination of the two output signals indicates that the RSSI signal is within the range defined by the two thresholds. The definition of what is intended by the phrase 'within the range' depends on whether the value of the upper limit is greater or less than the lower limit. This is illustrated in [Figure 35](#).

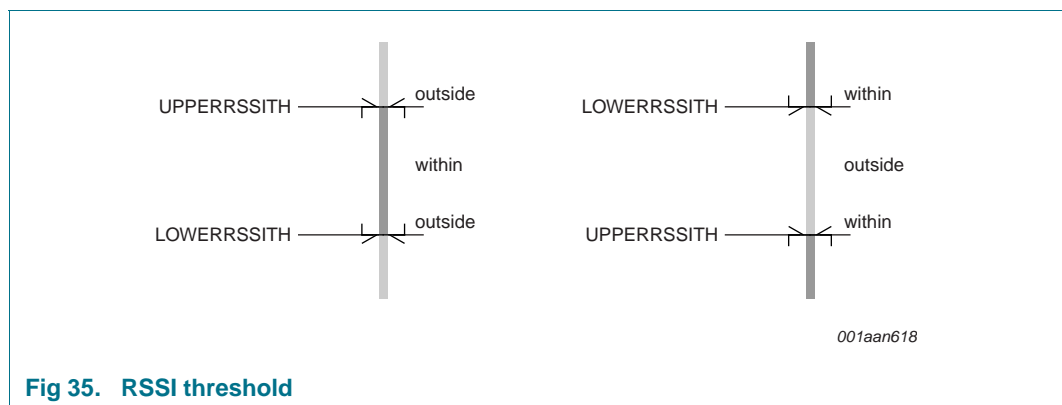


Fig 35. RSSI threshold

If a single minimum threshold is desired, the UPPERRSSITH[7:0] value must be set to 255 (FFh). To achieve a single maximum threshold, the LOWERRSSITH[7:0] register must be set to logic 0.

7.33.2 Modulation amplitude classification

This block consists of two sub-blocks, the first of which is the amplitude measurement, which is followed by a threshold comparison and the decision logic.

7.33.2.1 Method to determine the modulation amplitude

The modulation amplitude classification block measures the magnitude of the signal transitions within one chip interval. The baseband signal is delayed by one chip interval using an oversampling ratio of 4 samples per chip interval. A raw amplitude measurement is computed for each sample by subtracting the delayed sample and taking the absolute value of the difference. Then for each chip interval the maximum of the four adjacent raw values is determined.

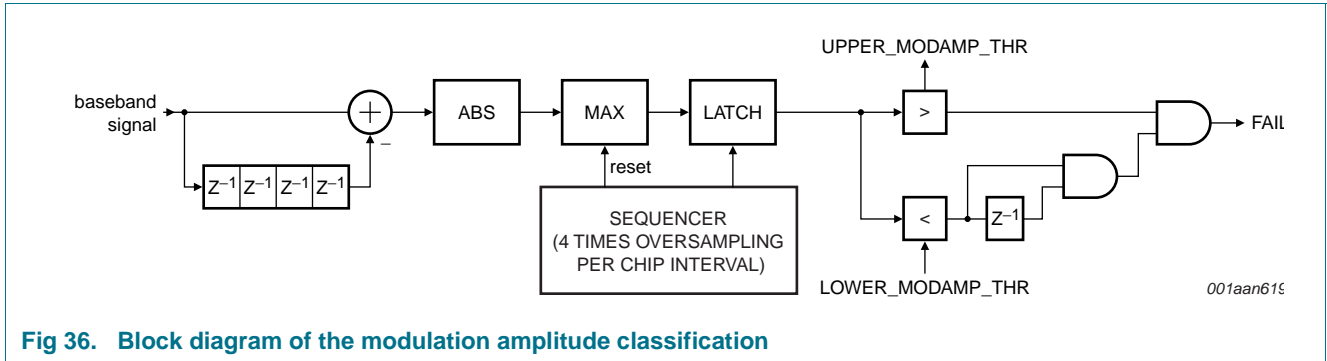


Fig 36. Block diagram of the modulation amplitude classification

If there is a transition in the chip interval, the output of this measurement is valid. If there is no transition in the interval the output from the measurement can be much lower than the nominal amplitude. This appears as a gap in the sequence of measurements. If we consider a Manchester coded signal having at least one transition within each two-chip interval, we have to accept (and ignore) at most one gap between valid measurements. The modulation amplitude is compared against the threshold defined with register LMODAMPTH and if it is lower than the threshold for a duration greater than NUM_MODAMP_GAPS_x[1:0] × (chip duration), then a 'modulation amplitude too low' error is reported in bit 0 of register SIGMONERROR.

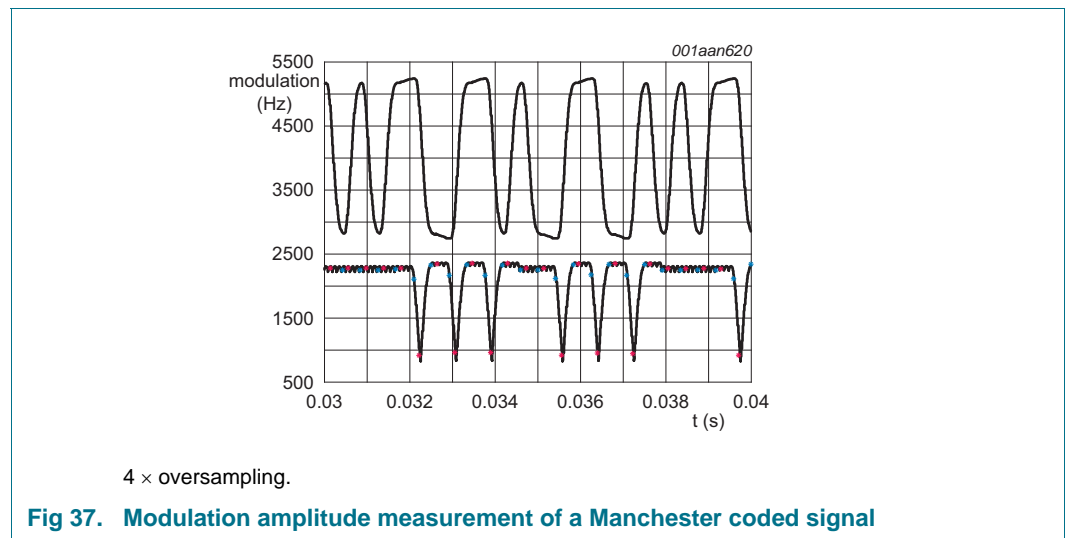


Fig 37. Modulation amplitude measurement of a Manchester coded signal

Figure 37 shows an example of the amplitude measurement when measuring a noise-free Manchester encoded baseband signal. The top waveform is the baseband signal. Note that this signal can have an arbitrary offset. The lower waveform shows the output of the amplitude measurement. The red dots show the actual values (oversampling rate of 4 versus the chip-clock) used for computation.

Due to the ripple in the output signal (lower trace) and the discrete sampling time, the sampled signal can be lower than the theoretical maximum value. Worst case input signals for this algorithm produce a maximum amplitude error of 8 % of the maximum theoretical value.

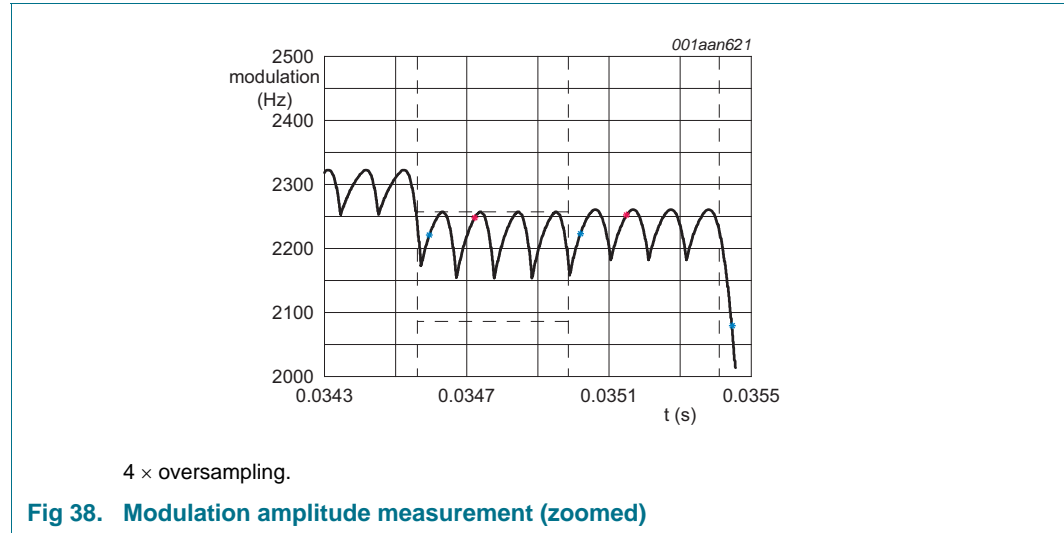


Fig 38. Modulation amplitude measurement (zoomed)

In this example the upper horizontal dashed line corresponds to the actual amplitude A_{act} . The lower horizontal dashed line corresponds to $A_{act} - 8\% = 0.92 A_{act}$. Consider this when calculating the lower and upper limit for the modulation amplitude detection. The higher limit can be set close to the expected value, the lower limit must be at least 8 % lower than the expected value.

The amplitude measurement for each chip interval is compared with two programmable thresholds. If the measured amplitude is above the upper threshold, the result is immediately classed as a FAIL. If the measured amplitude is below the lower threshold, this can be either a low amplitude condition or a gap. The outcome is a FAIL if two successive amplitude measurements deliver a value which is below the lower threshold; there must be no more than one gap between valid measurements.

The lower and upper thresholds can be independently selected with the 8 bit registers LOWER_MODAMP_TH and UPPER_MODAMP_TH, respectively. The actual threshold value is defined by the associated register settings according to [Equation 38](#).

$$xxxThresholdValue = \min(2^{xxx_MODAMP_TH[7:4]} \times xxx_MODAMP_TH[3:0], 7FFFh) \quad (38)$$

Where xxx stands for LOWER_ or UPPER_.

Example: FSK signal Manchester coded, 2 kbit/s respectively 4 kchip/s, modulation deviation: ± 1.5 kHz.

The FSK signal must be mapped to the output range of the FSK demodulator. The output signal range is 0 to 32256. This range equates to a frequency deviation of 200 kHz respectively 600 kHz, depending on bit LARGE_FM_DEM_RANGE in register EXPERT2. The expected peak-to-peak modulation amplitude is $1.5 / 200 \times 32256 = 242$.

The UPPER_MODAMP_TH is set to at least the expected value: $16 \times 2^4 = 256$.

UPPER_MODAMP_TH_MANT[3:0] = 15d = 1111b

UPPER_MODAMP_TH_EXP[7:4] = 4d = 0100b.

The LOWER_MODAMP_TH should be set to 92 % of the maximum expected value:
 $242 \times 0.92 = 222$.

The closest programmable value not exceeding this is $13 \times 24 = 208$. Therefore, the LOWER_MODAMP_TH should be programmed as follows:

LOWER_MODAMP_TH_MANT[3:0] = 13d = 1101b

LOWER_MODAMP_TH_EXP[7:4] = 4d = 0100b

The lower and the upper thresholds can be disabled. The lower threshold is disabled by setting LOWER_MODAMP_TH to 0d and the higher threshold is disabled by any value:
 $UPPER_MODAMP_TH \geq 2^{15}$.

7.34 Data classification

The data slicer is used for the timing, code and baud rate classification modules.

7.34.1 Data slicer

The device features a versatile collection of different data slicers with different initialization and adaptation mechanisms, including:

- an edge-sensitive slicer with minimum latency: used in applications where fast data slicer settling times are crucial
- a level-sensitive slicer: more robust to noise, appropriate when a longer settling time is acceptable

7.34.1.1 Number of corrupted bits in RX mode

The number of corrupted bits during the start of RX mode depends on the selected slicer method and the associated settings. The edge slicer provides the fastest possible settling time, only 1 chip period (1 / 2 bit) is lost. The loss of level-sensitive slicer bits depends on its initialization setting. If the initialization sequence is selected, 4 chips (2 bits) or 16 chips (8 bits) can be lost. It is possible to recover all bits, provided the level sensitive slicer is pre-initialized to the correct threshold.

7.34.1.2 Slicer description

The level-sensitive slicer is configured by the RXDCONx registers; see [Section 8.2.1.33 "Register RXDCON0" on page 112](#). The level slicer threshold can also be initialized with a desired value by programming registers SLICERINITL and SLICERINITH. This could be used to improve level slicer settling time. The actual level slicer threshold currently used can be read from these registers at any time.

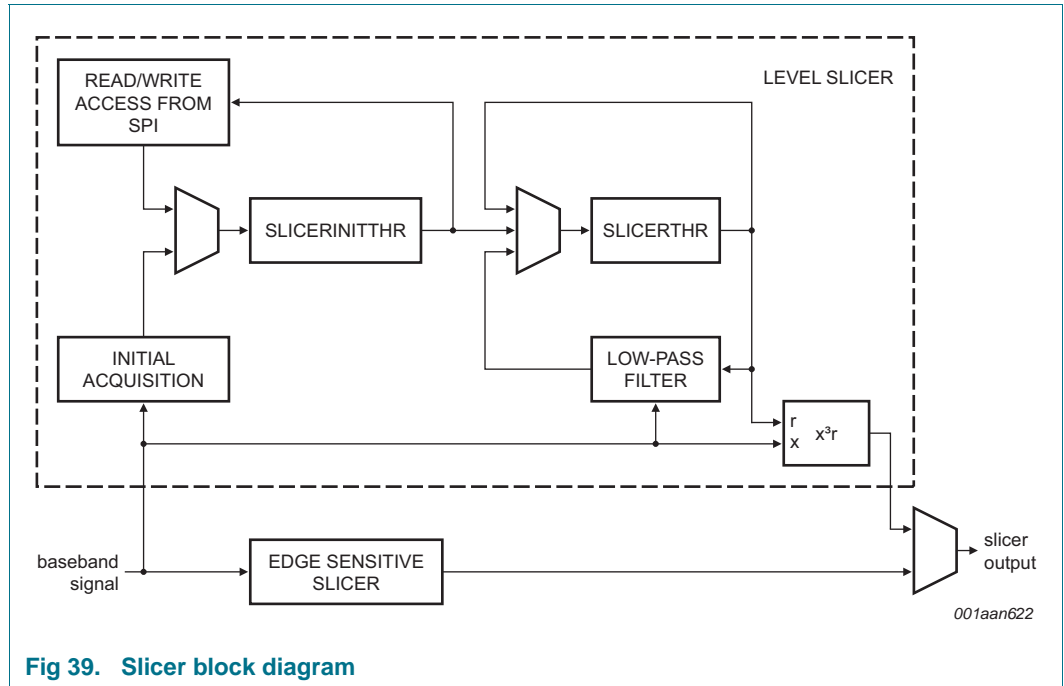


Fig 39. Slicer block diagram

The edge-sensitive slicer will not make use of these two registers. The EDGE_MODAMP_TH contains the expected peak modulation amplitude with which the edge slicer is initialized. The expected peak modulation value is provided by the EDGE_MODAMP_TH[7:0] register; see [Section 8.2.1.32 “Register EMODAMPTH” on page 111](#). The EDGE_MODAMP_TH is calculated by:

$$\text{ThresholdValue} = 2^{\text{EDGE_MODAMP_TH}[7:4]} \times \text{EDGE_MODAMP_TH}[3:0] \tag{39}$$

7.34.2 Edge slicer

The edge slicer operates as a differentiating slicer in combination with a fixed-level slicer. The time-constant is automatically adjusted in accordance with the selected chip rate of the baud-rate generator unit. This slicer is also capable of demodulating NRZ code with long constant bit sequences provided the expected peak modulation amplitude initializes correctly. The basic principle of the edge slicer is explained in [Figure 40](#).

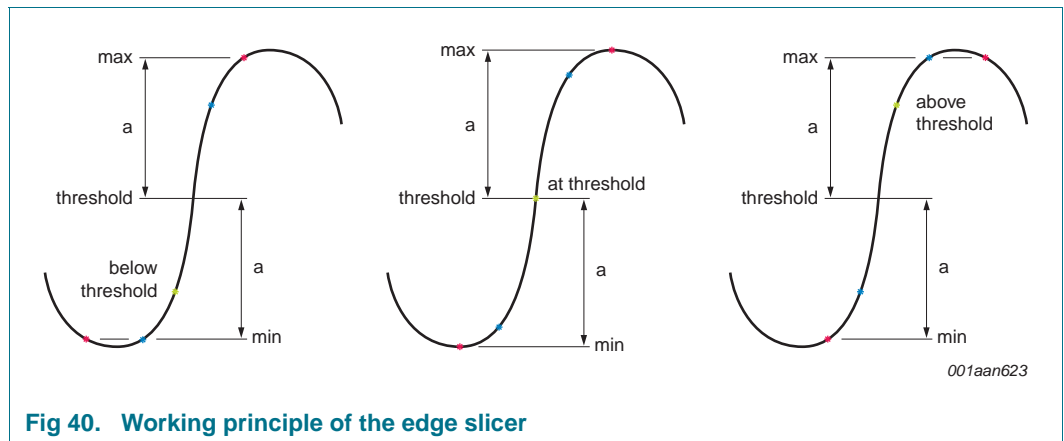


Fig 40. Working principle of the edge slicer

The slicer operating mode slicer is selected by the slicer selection bits SLICERSEL_W[1:0]; see [Table 84 “SLICERSEL_W bit functions” on page 112](#).

The edge slicer takes five adjacent samples at intervals equivalent to $\frac{1}{4}$ of the chip width. The four outermost samples (red and blue dots in [Figure 40](#)) are used to make up a dynamic threshold and the middle sample (green dot) is compared against this. The threshold value is the average of the maximum and minimum of the four outermost points.

The exact description of the algorithm for the edge slicer is:

1. Consider 5 consecutive samples taken at a distance $\frac{1}{4}$ of the chip period width.
2. Compute the minimum and the maximum of all samples except the middle one.
3. Take the average of the maximum and the minimum as the slicer threshold.
4. Compute the maximum and the minimum of the two neighbors of the middle sample.
5. Take the difference of the maximum and the minimum as the amplitude measurement.
6. Compare the measured amplitude against the peak value of the signal which is provided by register EMODAMPTH; see [Section 8.2.1.32 “Register EMODAMPTH” on page 111](#).
7. If the amplitude is above the threshold, set the slicer output according to the comparison of the signal (middle sample) with respect to the slicer threshold.
8. If the amplitude is below the threshold, keep the current state of the slicer output.

The following list summarizes the properties of the edge slicer algorithm:

- Because the input signal needs to be fed through a delay line and because of the necessary linear interpolation the slicer has a delay of about one chip interval.
- Since the slicer acts only on valid signal edges and since it ignores what is between these edges, it can handle arbitrary coded signals, including NRZ.
- The slicer output is valid after the first signal edge and the slicer delay.
- Due to its differentiating function, the edge slicer is more susceptible to noise than slicer threshold generation methods which average over the signal (level-sensitive slicer).

The slicer needs to know the expected amplitude of the baseband signal for amplitude classification, this can be easily provided for FSK signals.

The following configuration settings must be initialized when the edge slicer is used.

Expected peak modulation value: must be provided by the EDGE_MODAMP_TH[7:0] register; see [Section 8.2.1.32 “Register EMODAMPTH” on page 111](#). The EDGE_MODAMP_TH[7:0] value must be calculated using the following procedure:

$$\text{ThresholdValue} = 2^{\text{EDGE_MODAMP_TH}[7:4]} \times \text{EDGE_MODAMP_TH}[3:0] \quad (40)$$

Example: FSK signal Manchester coded, 2 kbit/s respectively, 4 kchip/s, modulation deviation: ± 1.5 kHz.

The FSK signal must be mapped to the output range of the FSK demodulator. The output signal range is from 0 to 32256. This range equates to a frequency deviation of 200 kHz to 600 kHz depending on bit LARGE_FM_DEM_RANGE in register EXPERT2. The expected peak modulation amplitude is $1.5 / 200 \times 32256 = 242$. The EDGE_MODAMP_TH is set as close as possible to the expected value: $15 \times 2^4 = 240$.

EDGE_MODAMP_TH_MANT[3:0] = 15d = 1111b

EDGE_MODAMP_TH[7:4] = 4d = 0100b

7.34.2.1 Edge slicer signal monitor setting

The lower and upper thresholds for the peak-to-peak amplitude of the baseband signal (FSK modulation) are simply the TX peak-to-peak frequency deviation plus and minus a guard band tolerance (factor of 3 / 4 or 5 / 4) mapped to the output range of the FSK demodulator. They can be calculated with the following equations:

Register LMODAMPTH = $3000 \times (32256 / 200000) \times (3 / 4) = 362$.

Register UMODAMPTH = $3000 \times (32256 / 200000) \times (5 / 4) = 605$.

Register UMODAMPTH must be set to a value higher than 605 ($10 \times 2^6 = 640$).

UMODAMPTH[3:0] = 10d = 1010b

UMODAMPTH[7:4] = 6d = 0110b

Register LMODAMPTH must be set to a value lower than 362 ($11 \times 2^5 = 352$).

LMODAMPTH[3:0] = 11d = 1011b

LMODAMPTH[7:4] = 5d = 0101b

Remark: the amplitude threshold must be set to the expected peak amplitude value.

7.34.3 Level-sensitive slicer

The level-sensitive slicer offers various features which can be configured to improve noise immunity or to reduce latency; see [Section 8.2.1.33 "Register RXDCON0" on page 112](#).

These include:

- User-definable initialization value
- Initial acquisition of the threshold by averaging the baseband signal over 2, 4, and 8 bits
- Continuously variable threshold configured according to output from 1st-order low-pass filter

The slicer operating mode is selected with slicer selection bits SLICERSEL_x[1:0] according to [Table 84 "SLICERSEL_W bit functions" on page 112](#).

The time-constant for the low-pass filter is derived from the baud-rate generator settings. It is assumed that a Manchester encoded single bit comprises two chips.

The various level slicer initialization mechanisms are controlled by bits SLICERINITSEL_x[1:0]. If the slicer is initialized, its output becomes invalid for at least one cycle, which restarts the deglitcher and the edge detector. The output remains valid even when the slicer threshold is updated after the initial acquisition refines its threshold value (after 4 and 8 bits).

7.34.3.1 Level-sensitive slicer initial acquisition

The initial acquisition generates a first estimate of the threshold by averaging the RX baseband signal over a fixed time interval of two bits. If a constant 0 or 1 sequence or an alternating 01 sequence is received, the expected value of the error is exactly zero. If a Manchester encoded signal is being received, the maximum error can be $\frac{1}{4}$ of the whole swing, which is sufficient for an initial estimation. After having calculated this average, the slicer output changes from UNKNOWN to VALID.

The following samples from the baseband signal are used to improve the initially found threshold. After processing an additional 2-bit interval (4 bits in total), a new average is computed having less uncertainty as the initial value (by a factor $\sqrt{2}$). This is used as the new slicer threshold. Once an additional 4-bit interval is accumulated, having processed 8 bits in total, the final, more accurate estimate for the threshold can be calculated. This threshold value can be read via register SLICERINITH. Register SLICERINITL is automatically updated every time a new initial slicer threshold is available.

It is possible that the 2-bit interval period used for the initial estimate lies in a time period where there is either no RF, RF with only CW (no modulation) or the frame start containing Manchester code violations. In this case the slicer output may have no edges for a long time interval, which may indicate an incorrectly chosen threshold value. If the timing verification block detects a timeout (time interval between edges > 3.5 chip width) it makes sense to reset the threshold estimation in order to get a better initial threshold value. The slicer's output is again UNKNOWN after the reset for the next 2-bit interval. The slicer's output becomes VALID again and the classification of its output edges may provide successful data reception. If the RX signal is not usable the slicer may be reset several times until the selected RX operation is aborted.

If the initial acquisition is not used during the wakeup search, it might be useful to disable the auto-reset feature mentioned above. This can be accomplished by a dedicated setting in register SLICERINITSEL.

The initial acquisition operation always inhibits the use of the slicer output (status UNKNOWN) during the calculation of the first two bits, regardless of whether the initial acquisition was triggered for the first time (by an RX event) or if it was re-triggered from a bit timeout.

The initial acquisition updates the slicer initialization register and the slicer register after the calculation of 2, 4, and 8 bits (selected by INIT_ACQ_BITS) provided the RX event was not interrupted by the higher-level state machine. In these circumstances the initial acquisition is stopped to avoid unwanted data corrupting the calculation of the threshold.

Access register SLICERINITH only via the SPI if the initial acquisition is not active. Failure to comply with this may result in the reading of unstable values and the content of register SLICERINITH may become undefined.

7.34.4 Deglitcher and edge detector

The purpose of the deglitcher is to suppress multiple signal transitions when a noisy baseband signal crosses the slicer threshold. The deglitcher operates as follows: if a signal transition is detected, the deglitcher passes the transition to its output and then it locks this output for a certain time period, which can be selected by `DEGLITCHER_WINDOW_LEN[1:0]` according to [Table 79](#) “[DEGLITCHER_WINDOW_LEN bit functions](#)” on page 110.

The lock timer is held in its reset state while the slicer output is invalid. This means that the deglitcher can only enter its locking state when the edge detector produces an output event.

The edge detector locates the edges in the deglitched slicer output and supplies the blocks which measure and classify time intervals between edges. The edge detector produces edges only after the slicer output is valid. If the slicer produces a transition at the same time as its output becomes valid, it is suppressed by the edge detector. The deglitcher lock window is also suppressed by the edge detector and only becomes active when the edge detector produces an output event.

7.35 Timing classification block

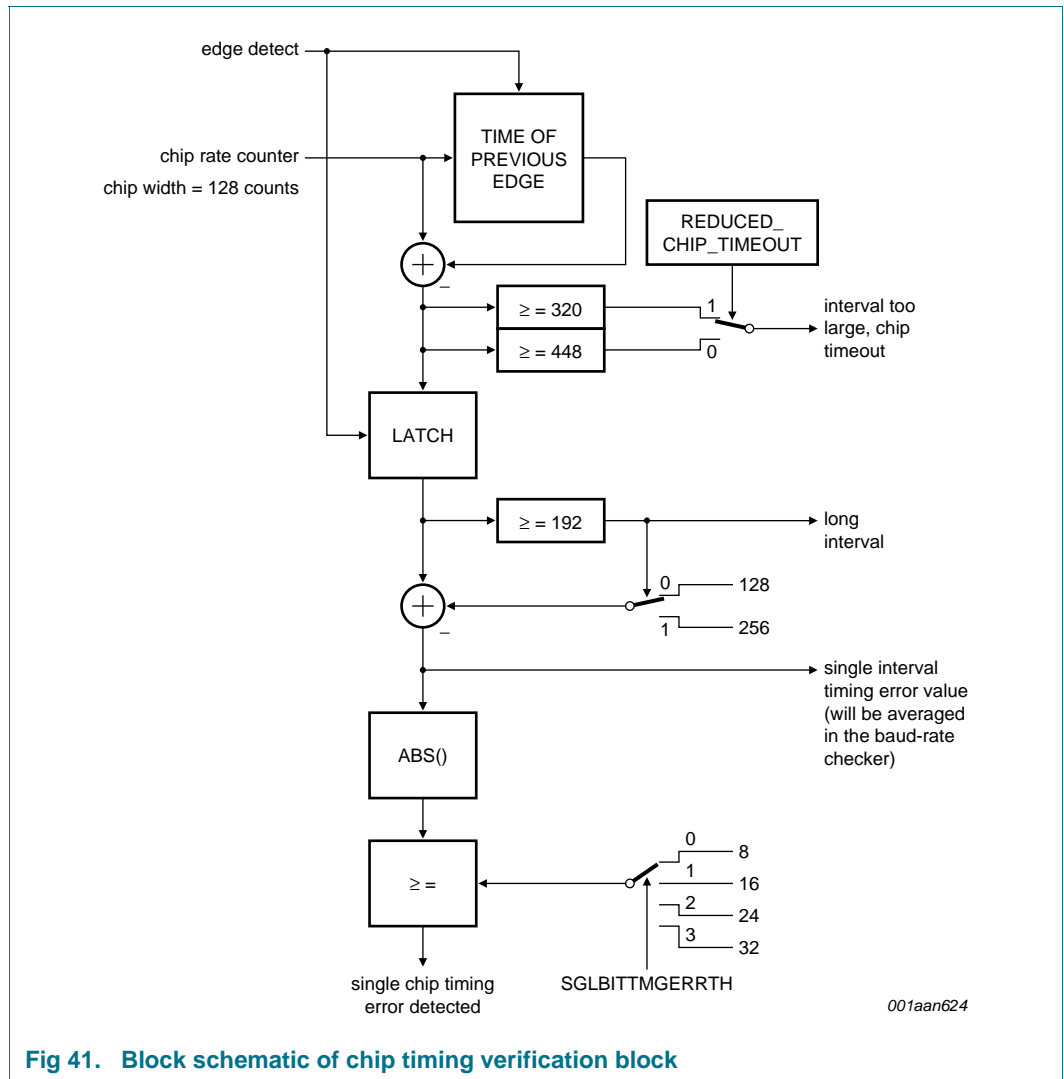
The purpose of this module is to classify the time intervals between the transitions from the slicer and to determine whether the RX signal is a Manchester coded signal. Certain additional conditions can be selected.

The property of a Manchester coded signal, used as the main classification criteria in this block, is that there are only two different time intervals, namely one chip width or two chip widths between two transitions.

7.35.1 Chip timing verification

In the proposed implementation, the signal is oversampled with an OSR of 128, giving a time measurement resolution that is better than 1 %. The time interval between each pair of transitions is measured. If the measured time interval is $< 1.5 \times$ chip width, then it is assumed that the associated nominal width is $1 \times$ chip width and so $1 \times$ chip width is subtracted from the measurement to calculate the timing error. If the measured time interval is $> 1.5 \times$ chip width then it is assumed that the associated nominal width is $2 \times$ chip width and so $2 \times$ chip width is subtracted from the measurement to calculate the timing error. This measurement includes a timeout such that widths greater than $3.5 \times$ chip width are always rejected. The absolute value of the timing error is calculated and compared to a limit which can be chosen from the 16, 24, 32, or 48 counts of the oversampling clock according to the setting of bits `SGLBITTMGERRTH[1:0]`; see [Section 8.2.2.7 “Register TIMINGCHK” on page 117](#). The time interval is accepted if its absolute value is below the limit. This corresponds to timing errors which are less than 12.5 %, 18.75 %, 25 % and 37.5 % of a nominal chip width, respectively. The single-chip timing verification block is a powerful means to classify signals with a given baud rate. The edges of these signals are assumed to emerge at a virtual chip grid. Therefore, the same absolute error limit is applied for short and long intervals to allow a specified range of edge jitter.

The chip timeout value can be changed with an expert bit. The standard value is $3.5 \times T_{\text{CHIP}}$. This value can be reduced to $2.5 \times T_{\text{CHIP}}$ if bit `REDUCED_CHIP_TIMEOUT` is set; see [Section 8.2.4.3 “Register EXPERT2” on page 125](#).



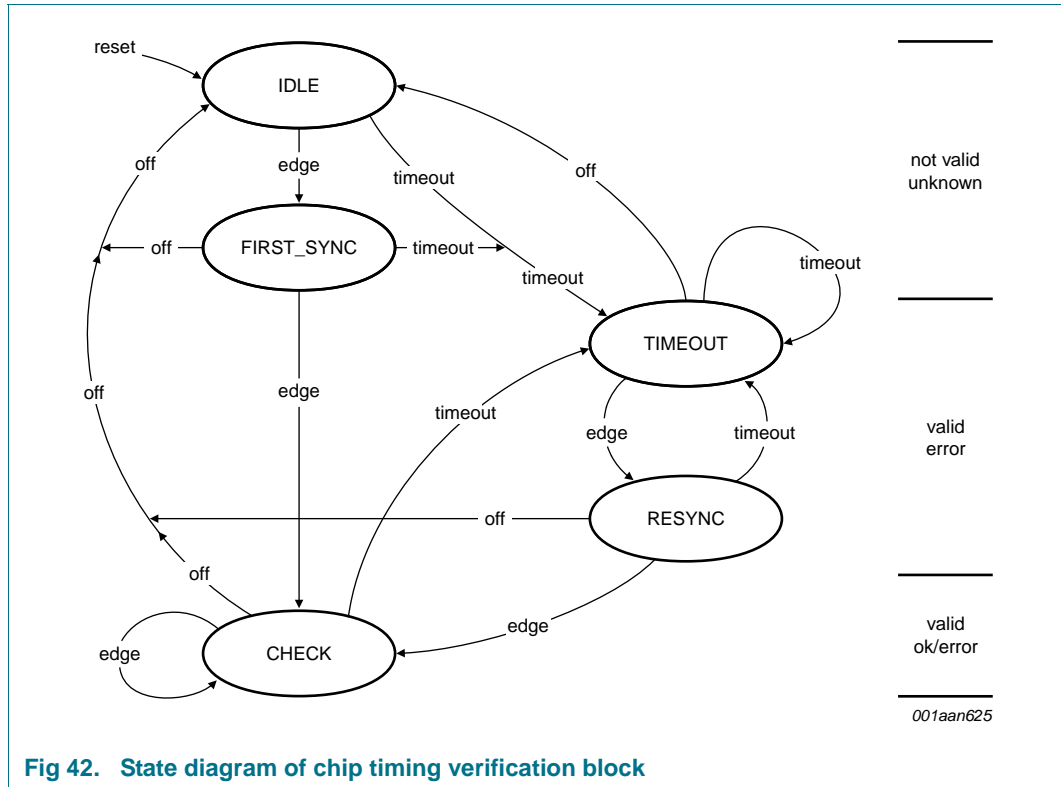


Fig 42. State diagram of chip timing verification block

After the first synchronization (reception of two edges) the chip timing verification block becomes VALID and the chip timing CHECK begins. The last chip timing step is directly used as the ERROR criteria when in this state.

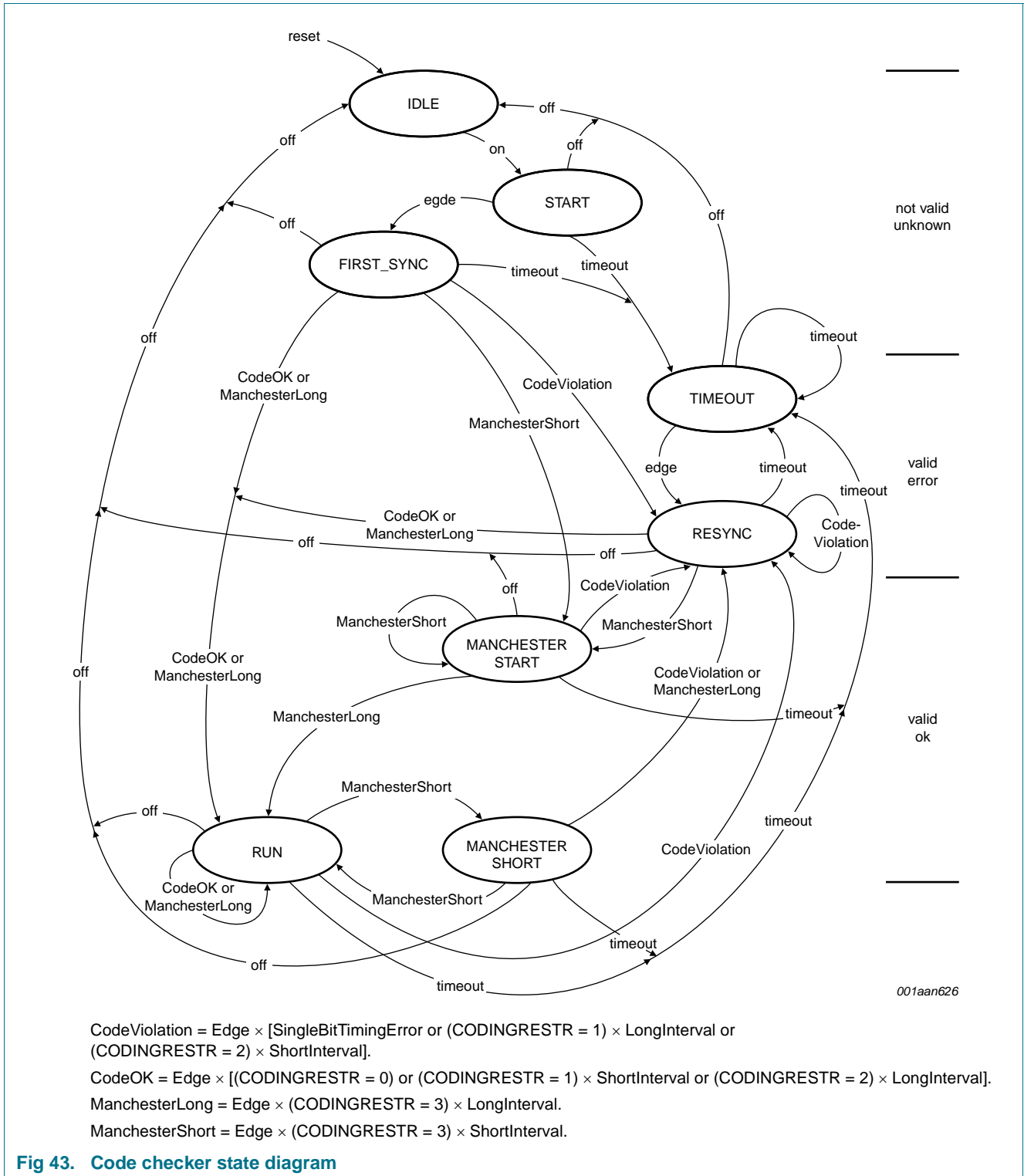
If a timeout occurs, the state machine signals an ERROR. Upon reception of two consecutive edges, the timing verification block can be re-synchronized, the state machine then again entering the CHECK state.

Remark: a single chip timing error will not change the state of the state machine unless it is a timeout.

7.35.2 Code checker

Typical wakeup patterns consist either of a constant 0 sequence, a constant 1 sequence, or an alternating 01 sequence. In these cases the pattern only contains a single time interval length. It is therefore possible to apply further restrictions on the accepted time intervals.

Correct chip timing is a pre-requisite for the code checker. A single bit timing error always causes a code checker error. Changing the setting of CODINGRESTR_W[1:0], while the code checker is running is not recommended; see [Section 8.2.1.35 “Register RXDCON2” on page 113](#). This can cause a false error indication. A false error indication may arise at a later stage if Manchester code checking is newly selected. The Manchester MANCHESTER START state is not necessarily executed immediately.



The timeout is derived from the chip timing verification block, i.e. a timeout is generated if a bit exceeds a length of $3.5 \times$ chip width.

The OK/ERROR information is directly derived from the state machine. The RESYNC state is initiated after a code violation is recognized by any of the other states, unlike the chip timing verification block which only enters the RESYNC state after the occurrence of a timeout.

If CODINGRESTR_W[1:0] is set, it is only possible to differentiate between a run of zeros or a run of ones (short time intervals) if the first long time interval is received, thus determining if the data represents a 01 or a 10 transition. Once the long time interval is received, the remaining sequence can be checked against Manchester coding rules. After a long interval is detected, short intervals must always be in pairs; the following sequence is illegal: SSSSLLSSLSSSSLSSSL.

7.35.3 Baud-rate checker

An averaging facility is implemented to increase the accuracy of the single time interval check and baud-rate detection by a factor of 4. This averaging is performed on blocks of 8 bits, where the first block starts whenever the chip timing block reaches either FIRST_SYNC state or RESYNC state. Correct timing of a single bit is a prerequisite for the baud-rate checker, therefore averaging is restarted even if a single bit timing error occurs.

The baud-rate checker has no information about the coding of the signal. Thus it is possible that a sequence of 8 bits comprises 17 instead of 16 chips, e.g. if 15 short intervals followed by one long interval are to be examined. If a sequence of several 8-bit blocks is assessed, the accumulated timing uncertainty is never more than 1 chip.

Averaging over 16 chips requires dividing the sum of the individual timing errors by 16, thus causing an unnecessary loss of precision. Therefore the division is omitted and only the timing errors are summed during an 8-bit block. The product of the 8 bits is compared against a limit which can be selected by SUMBITTMGERRTH[2:0] according to [Table 100 "SUMBITTMGERRTH bit functions" on page 117](#).

This block can be easily extended to allow the number of observed bits to be adjusted to either 8, 16, 24 or 32 bits according to the baud rate observation length setting BROBSLENGTH[1:0]; see [Table 99 "BROBSLENGTH bit functions" on page 117](#).

The output of the baud-rate checker is only VALID after the absolute value of the sum of the received 8 bits is checked against the limit. The output immediately signals an ERROR if the limit is violated. If the sum value is within the limit, the measurement proceeds until either a limit violation is detected or the requested number of bits are observed. In the latter case the output becomes VALID and signals OK.

The baud-rate checker continues checking on an 8-bit basis after the requested number of bits was checked successfully. The ERROR signal is updated at the end of every 8-bit sequence. It stays VALID and OK if the baud rate is within the limit. If the baud rate is outside the limit, an ERROR is signaled and the baud-rate checker restarts. The ERROR signal is retained as long as no 8-bit sequence is within the limit. If the selected observation length is greater than 8 bits, the baud-rate checker enters the NOT VALID state as soon as the first correct 8-bit sequence is received and finally signals VALID and OK after successful reception of the selected observation length. This mechanism assures that the baud-rate checker can only signal VALID and OK once the selected number of consecutive bits are received with the correct baud rate.

On the occurrence of a timeout or a single bit timing error, the baud-rate checker resets immediately, NOT VALID is signaled instantaneously and the baud-rate checker restarts.

7.35.4 Timeout timer for the wakeup search

The control logic includes a timeout timer for the wakeup search operation. When used, this timer generates a negative wakeup detection output provided a positive wakeup detection is not generated prior to the timer expiration. When this timer is disabled, the output of the wakeup search operation is instantly negative upon a failure signal from any of the detection operations.

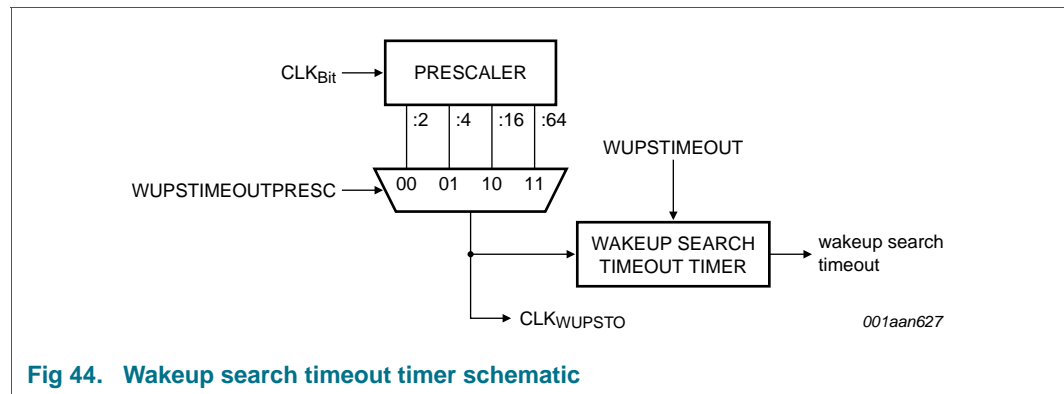


Fig 44. Wakeup search timeout timer schematic

The wakeup search timer consists of a prescaler and a timer register. The clock is derived from the mainscaler clock and is therefore associated with the selected baud rate.

The timeout can be selected by WUPSTIMEOUT[5:0] and is calculated as $WUPSTIMEOUT_{5:0} \times T_{WUPSTO}$ for WUPSTIMEOUT[5:0] = 1 to 63d.

The value WUPSTIMEOUT[5:0] = 0 disables the timeout timer and selects an infinite timeout.

The generated timeout has an uncertainty of -2 to $0 T_{BIT}$ regardless of the setting of WUPSTIMEOUTPRESC[1:0] and WUPSTIMEOUT[5:0].

Timeout timer resolution and range:

- The fastest bit rate of 50 kbit/s requires the timeout to be adjusted in a range of 40 μ s up to 80 ms with a resolution of 40 μ s, 80 μ s, 320 μ s, and 1.28 ms respectively.
- A bit rate of 1 kbit/s requires the timeout to be adjusted in a range of 2 ms up to 4 s with a resolution of 2 ms, 4 ms, 16 ms, and 64 ms respectively; see [Section 8.2.2.4 "Register WUPSTO" on page 116](#).

7.36 Wakeup search logic

A summary of the signal monitoring conditions which can be used as wakeup criteria are shown in [Table 22](#).

Table 22. Overview of signal monitoring methods

Block name	Processes the signal	Started by	Output is valid after	Can be started by
RSSI level classification	digitized RSSI	-	input is valid	-
Modulation amplitude classification	demodulated baseband	start of wakeup search	2 chips	-
Slicer		start of wakeup search only if initial acquisition is enabled	2 bits if initial acquisition, otherwise immediately	timeout from chip timing verification, only if enabled and in mode 2
Chip timing verification and code checker	slicer output	slicer output valid after start of wakeup search	$0 < t < 5$ chips (2 chip time-outs)	in mode 2 by the slicer, only if initial acquisition is enabled
Baud-rate checker		FIRST_SYNC or RESYNC of the timing verification after start of wakeup search	$8 \text{ bits} \leq t \leq$ configured observation length (8, 16, 24 or 32 bits)	in mode 2 by the chip timing verification with another FIRST_SYNC or RESYNC
Wakeup search timer	-	start of wakeup search	FAIL after configured timeout	-

At the start of a wakeup search the following blocks are reset:

- wakeup search timer
- modulation amplitude classification
- chip timing verification and code checker
- baud-rate checker
- the slicer (conditionally)

The slicer is only reset if configured to acquire the value from the slicer initialization register (SLICERINITSEL_x[1:0] not equal to 00b). If slicer initial acquisition is selected, the chip timing verification, code checker block and baud-rate checker are held in the reset state for the duration of the slicer initial acquisition mode.

Register SIGMON_EN_W[5:0] provides enable bits which determine signal monitors that are considered for the overall wakeup detection decision; see [Section 8.2.2.1 “Signal monitoring register SIGMON0” on page 114](#). All signal monitors operate regardless of these enable bits and, after the wakeup search ends, their results are available in the corresponding status bits. [Section 7.36.1](#) and [Section 7.36.2](#) describe how the individual results from several signal monitors can be combined to achieve an overall wakeup decision.

Each of the signal monitors can have an invalid period caused by an initialization or resynchronization during which the output result is not considered. The logic depicted in [Figure 45](#) shows how this information is translated into the PASS/FAIL condition used by the wakeup search logic. If a signal monitor is in its invalid state, neither a PASS or FAIL condition is generated. If a signal monitor is not selected for the wakeup search, the FAIL is always zero and the PASS always one. The PASS and FAIL signals are exclusively used for the wakeup search logic and they must not be confused with the actual state of the corresponding signal monitor (signals VALID and ERROR) which can be observed in registers SIGMONSTATUS and SIGMONERROR; see [Section 8.2.2.10 “Register SIGMONSTATUS” on page 121](#).

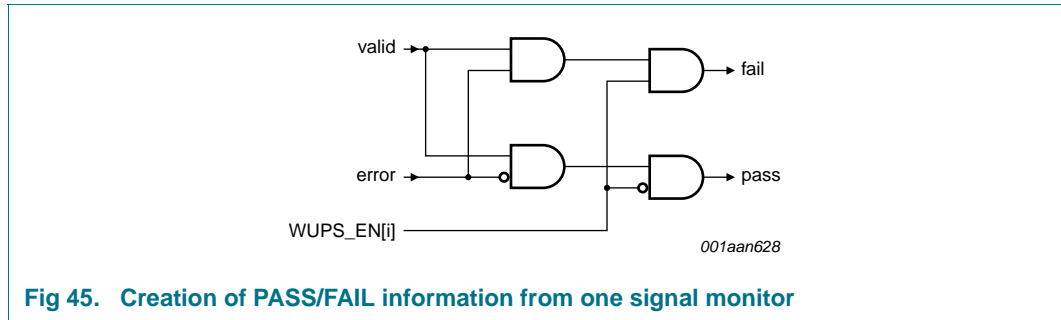


Fig 45. Creation of PASS/FAIL information from one signal monitor

Two different mechanisms are provided for the wakeup search:

- 'pessimistic wakeup search' or mode 1
- 'optimistic wakeup search' or mode 2

In the pessimistic wakeup search (mode 1) the wakeup search timer has no meaning and therefore will not influence the result. In the optimistic wakeup search (mode 2) the wakeup search timer is always active.

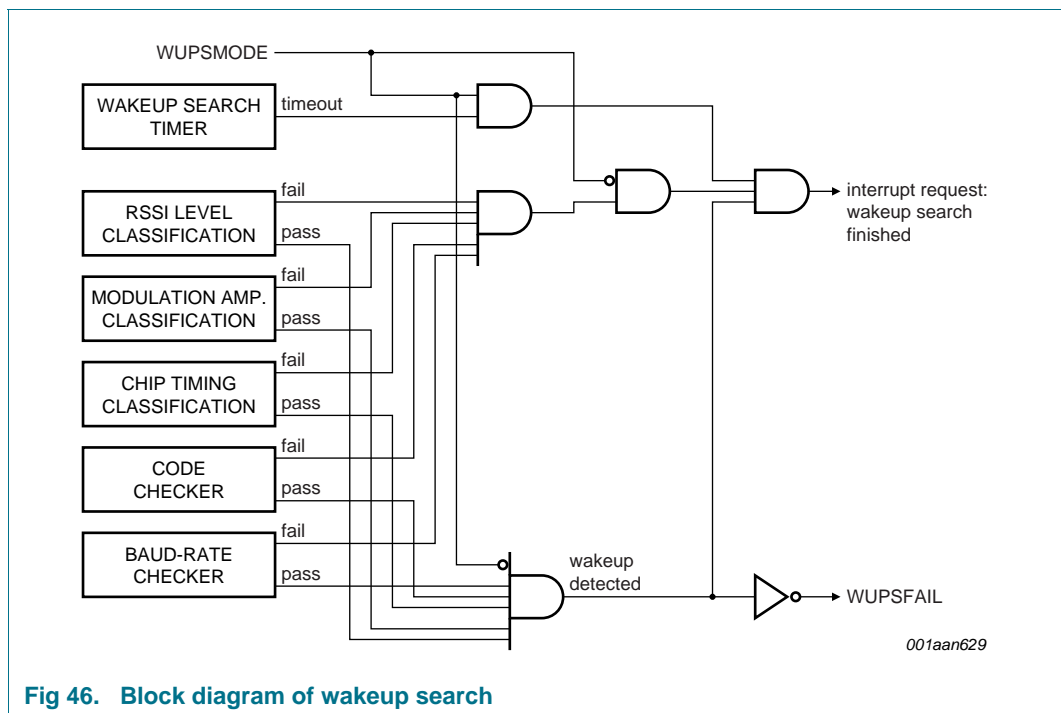


Fig 46. Block diagram of wakeup search

At the end of the wakeup search an interrupt request is generated and the result is stored in bit WUPSFALL. If this bit is set, it signals that the wakeup criteria was not met. Otherwise it is cleared. The content of this bit is undefined prior to first use of the wakeup search.

The polarity of bit WUPSFALL is chosen so that register SIGMONSTATUS can be used as a mask for register SIGMONERROR when the host controller is interested in retrieving the cause of an unsuccessful wakeup detection. If the wakeup search was successful (bit WUPSFALL is cleared) the content of register SIGMONERROR is not required to be considered as all relevant bits are cleared.

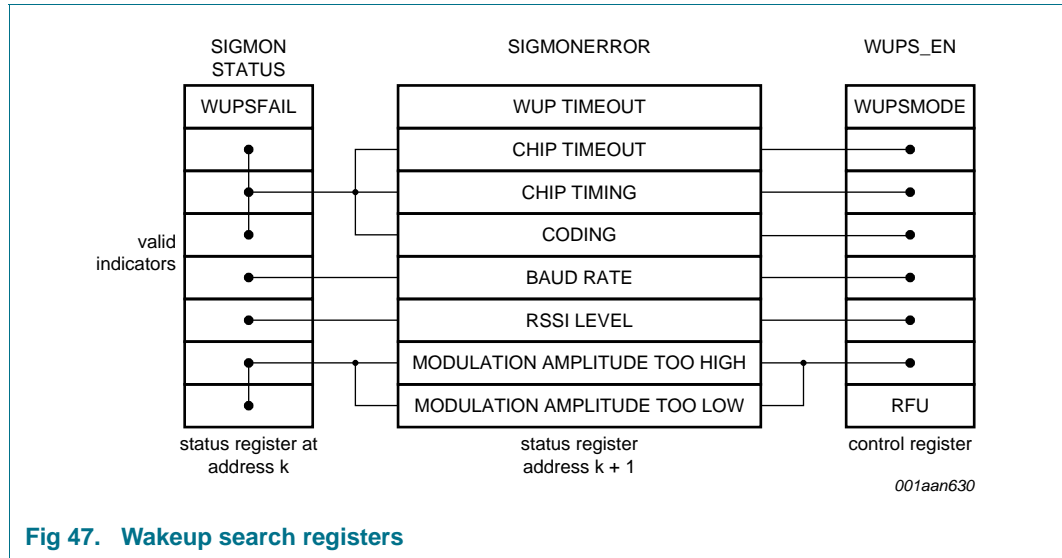


Fig 47. Wakeup search registers

7.36.1 Sampling the signal monitoring status

Since the information from the OL2381's signal monitoring method is made up of more than 8 bits, it is desirable to provide a mechanism which ensures that the controller can always retrieve a consistent set of status information. Therefore the OL2381 provides three status registers: SIGMONSTATUS, SIGMONERROR and RSSILEVEL into which the status is simultaneously transferred, whenever it is either actively requested by the controller or automatically saved by the wakeup search logic; see [Section 8.2.2.12 "Register RSSILEVEL" on page 122](#).

There are two cases in which the status is sampled:

- after a read command, regardless of the address that follows, but only if bit STATAUTOSAMPLE is set; see [Section 8.2.2.8 "Register RXCON" on page 118](#)
- always at the end of a wakeup search

Bit STATAUTOSAMPLE either allows software to control the sampling of the status information with each read command (logic 1) or allows the status to be unaffected by any read command (logic 0). This allows consistent read and write command status information to be read as shown by the examples given in [Table 23](#) and [Table 24](#).

Table 23. Example 1: Using single byte reads

Command	Description
Write (STATAUTOSAMPLE, 1)	enable status sampling with the next read
Read (SIGMONSTATUS)	this samples the consistent status
Write (STATAUTOSAMPLE, 0)	disable status sampling with the next reads
Read (SIGMONERROR)	consistent with line 2
Read (RSSILEVEL)	consistent with line 2
Read (SIGMONSTATUS)	reads the same as line 2
Read (RSSILEVEL)	reads the same as line 5
Read (SIGMONERROR)	reads the same as line 4

The status of SIGMONSTATUS, SIGMONERROR and RSSILEVEL is only sampled in line 2. Single byte read commands (lines 4 and 5) only transfer the previously sampled status once bit STAUTOSAMPLE is set back to logic 0. Lines 4 to 8 do not change the contents of the registers because status sampling is already disabled.

Table 24. Example 2: Using read command auto-increment address

Command	Description
Write (STAUTOSAMPLE, 1)	enable status sampling with the next read
Read (SIGMONSTATUS, SIGMONERROR, RSSILEVEL)	using the address auto-increment feature, the status is sampled at the start of the read command and then, since the status registers occupy adjacent addresses, the continuous reading of these bytes transfers the consistent status to the controller

Bit STAUTOSAMPLE is automatically set to logic 0 at the end of a wakeup search. This guarantees that the important wakeup search results are retained until they are transferred to the controller. It can also be automatically set to logic 1 whenever the status register RSSILEVEL is transferred to the controller, provided bit AUTOSAMPLEMANUAL is cleared; see [Section 8.2.2.8 “Register RXCON” on page 118](#). This allows the scenario following a wakeup search: the status information is automatically sampled and stored in the status registers until the last status register (RSSILEVEL) is read. The controller now continues polling the signal monitors without switching the status into ‘live’ mode, because reading register RSSILEVEL automatically sets bit STAUTOSAMPLE. Note that further consistent status polling requires the address auto-increment feature to continue being used.

If automatic entry to ‘live’ mode is undesired, bit AUTOSAMPLEMANUAL can be set to keep bit STAUTOSAMPLE under software control. Note that bit STAUTOSAMPLE is always cleared after completing a wakeup search. This is necessary to guarantee that the wakeup search results are unconditionally sampled and saved until the controller acquires them.

7.36.2 Evaluating the wakeup search result

The bits in register SIGMONSTATUS provide the VALID information for the signal monitors. If a VALID flag is zero, the corresponding bit in register SIGMONERROR is also zero. Bit SIGMONERROR is set if an error occurs. The failing signal monitor can be identified by reading register SIGMONERROR. Calculating the expression SIGMONSTATUS & ~SIGMONERROR indicates which signal monitors provided a pass result; see [Table 107 “Signal monitor states set by registers SIGMONSTATUS and SIGMONERROR” on page 121](#).

7.37 Data reception

7.37.1 Preamble detection

A preamble detection can be issued upon completion of a wakeup search or at any time when expecting a frame. The preamble pattern can be configured with a length between 1 and 32 chips. The preamble length is set with the PREA_LEN[4:0] control bits. If PREA_LEN[4:0] is set to logic 0 a length of 32 chips is used. The bit error rate of the preamble can be configured with register PREA_TOL; see [Section 8.2.2.13 “Register PREACON” on page 122](#).

7.38 RX data decoding

After a wakeup search, if configured, a preamble detection and data reception follows seamlessly. After successful completion of the wakeup search and the preamble detection, the RX data is switched to the corresponding port pins, dependent on the device configuration. The data pin is kept LOW during wakeup search and HIGH during preamble detection. Data reception can be interleaved with SPI commands. Details are given in [Section 7.32.2 “Receive command” on page 55](#). The device has a Manchester code recovery feature which enables inversion of the RX data. The precondition of this code recovery unit is the full reception of a Manchester data stream with at least one polarity change within the code. The accumulated sum of data changes within a chip can be found in the MANCHESTER_COUNT[3:0] field in register EXTRXSTATUS; see [Section 8.2.3.1 “Register EXTRXSTATUS” on page 123](#). This is a 4-bit signed number which is applicable only when receiving data through the Manchester decoder. It is not needed if the frame start is properly synchronized with a preamble detection. If data reception is initiated with the DATA sub-command (without preamble detection), the Manchester decoding starts at the first chip it gets, without knowing whether this is the left or the right bit half. The RX data line can deliver the data correctly or inverted. If the signal contains any bit transitions, this counter counts up if the transition occurs at the assumed bit boundary (i.e. when it is correct) and it counts down if the transition occurs in the middle of the assumed bit grid (i.e. when it is incorrect). The result is that bit 3 of this counter is logic 0 if the data is decoded properly and it is logic 1 if the data is delivered inverted. The whole counter stays at zero if the RX signal contains no bit transitions, in which case it is not possible to tell whether the RX data is a long run of only zeros or a run of ones. If the sum is negative, the RX code must be treated as inverted, if the sum is positive, the data reception was correct. It is possible to invert the RX data stream by setting bit INV_RX_DATA; see [Section 7.13.1 “Clock recovery for RX mode” on page 29](#).

If the receiver is configured transparently (see register RXCON), the data pin is directly switched to the selected data slicer and mapped to the corresponding port pin after the RX command is issued.

7.39 RX clock generation

After a wakeup search, if configured, a preamble detection and clock recovery operate in parallel. Allow sufficient settling time from the start of data reception to the successful recovery of a stable clock. The run-in time (wakeup time and length of preamble) must be longer than the programmed settling time without code timing violations in-between the different phases to ensure correct operation. After successful completion of the wakeup search and the preamble detection, the bit or chip clock is switched to the corresponding port pin, depending on the device configuration. During wakeup search and preamble detection, the clock pin is kept at a constant HIGH. Data reception can be interleaved by SPI commands. Details are given in [Section 7.32.2 “Receive command” on page 55](#).

If bit RX_MANCHESTER is set, the clock rate is set to the bit rate so that every second chip is sampled at the correct time; see [Section 8.2.2.8 “Register RXCON” on page 118](#). This enables the microcontroller to directly decode the Manchester bit stream by sampling the RX data with the negative clock edges.

If the receiver is configured in a transparent mode, the clock pin is directly switched to clock recovery and mapped to the corresponding port pin after the RX command is issued.

7.40 RX digital signal processing

7.40.1 AM demodulator

AM demodulation requires bit DEMOD_ASK in register RXBW to be set; see [Section 8.2.1.25 “Channel filter bandwidth and RSSI filter settings register RXBW” on page 108](#). In this case, the data from ASK demodulator output will be connected to the digital baseband filter input.

7.40.2 FM demodulator

The FM demodulator consists of a discrete delay line and an XOR gate. This principle is used because it features perfect linearity over the full input frequency range. The FM demodulator takes the limited IF I signal and optionally also the Q signal as its input and produces a square-wave type output signal whose time varying average – the low frequency component – is directly proportional to the input frequency. [Figure 48](#) shows a detailed block diagram of the FM demodulator.

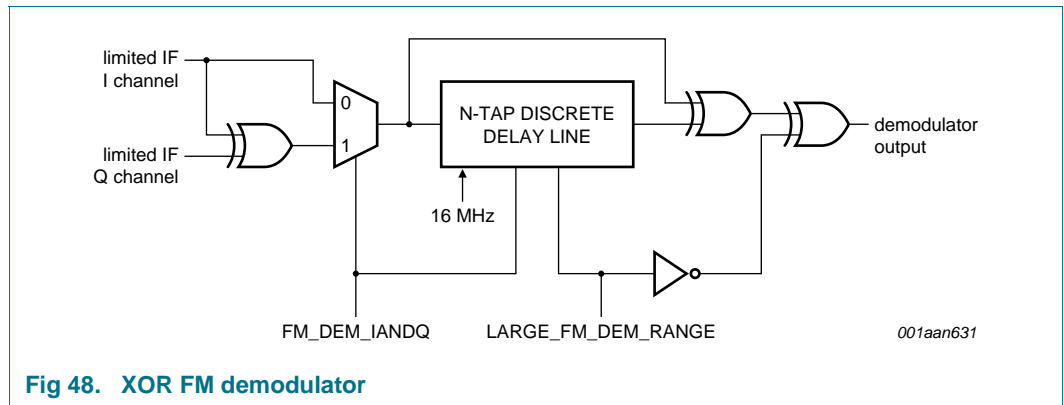


Fig 48. XOR FM demodulator

If bit FM_DEM_IANDQ is set to logic 0, only the limited I channel IF input is used for demodulation. In this case the demodulator is set to a center frequency of 300 kHz. If bit FM_DEM_IANDQ is set to logic 1, the I and the Q signals, which have a phase difference of 90°, are combined with an XOR gate. In these circumstances the demodulator is set to a center frequency of 600 kHz as the I and Q combination effectively doubles the frequency.

If the input frequency is within the specified range, the average value of the second XOR's output is a perfectly linear function of the input frequency.

If bit LARGE_FM_DEM_RANGE is cleared, the input frequency range of the FM demodulator is 200 kHz to 400 kHz. This is the appropriate setting for frequency deviations up to ± 100 kHz. If this bit is set to logic 1, the input frequency range is extended to between 0 Hz and 600 kHz, allowing for process frequency deviations, which are only limited by the analog channel filter. The demodulator output noise increases by the same factor (3) as the frequency range in these circumstances.

Switching to the large input frequency range is achieved by cutting the length of the delay line into one third of its original value. However, this also changes the slope of the output characteristics from positive to negative thereby inverting the demodulator output. The third XOR compensates for this inversion.

Table 25. FM demodulator configurations

See register EXPERT2 bit descriptions in [Table 117 on page 125](#).

D7	D6	Center frequency (kHz)	Input frequency range (kHz)	Maximum frequency deviation (kHz)	Number of delay elements
0	0	300	200 to 400	±100	40
0	1	300	0 to 600	±300	13
1	0	600	200 to 400	±100	20
1	1	600	0 to 600	±300	7

7.40.3 Baseband filter

The baseband filter serves the following purposes:

- suppresses the high frequency (square-wave) components from the FM demodulator, leaving only the time-varying average, or baseband component of the demodulated signal
- suppresses spectral portions of the quantization noise from the demodulator and the demodulated noise coming from the RF input which do not fall into the baseband signal's bandwidth
- helps achieve a suitable sampling rate for further processing of the baseband signal

The baseband filter is a 3rd-order IIR filter topology that is optimized such that it features a step response with almost no ringing as shown in [Figure 50](#).

7.40.3.1 RX baseband configuration

The filter is split into a 1st-order and a 2nd-order section to minimize the internal quantization noise. [Figure 49](#) shows the baseband filter distributed over two filter blocks.

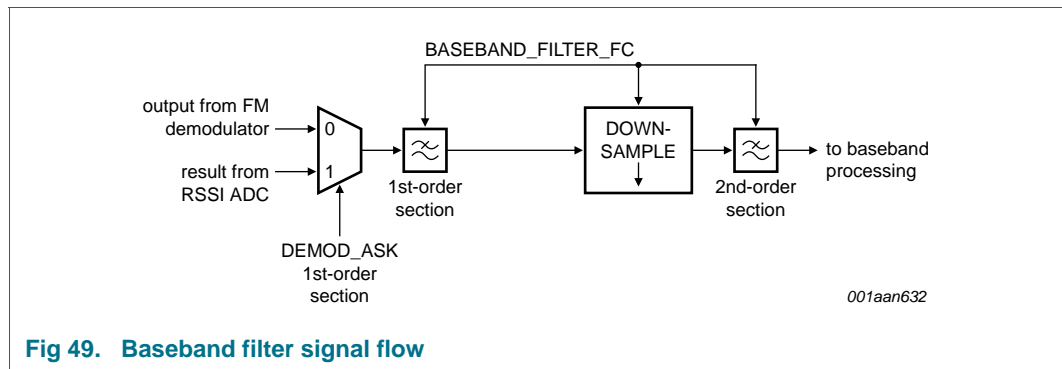


Fig 49. Baseband filter signal flow

The 1st and 2nd-order sections combine to make the 3rd-order baseband filter for ASK or FSK. The filter cut-off frequency is controlled by register BASEBAND_FILTER_FC control bits; see [Section 8.2.1.29 “Register RXBBCON” on page 109](#). The 1st-order section filters the RSSI information which is sampled with the ADC in the limiter/RSSI analog circuitry. Its cut-off frequency can be controlled separately by register RSSI_FILTER_FC; see [Section 8.2.1.25 “Channel filter bandwidth and RSSI filter settings register RXBW” on page 108](#).

Note that the baseband filter and the RSSI filter are two separate filters.

Figure 50 and Figure 51 show the step response and the frequency response of the baseband filter, respectively. Figure 50 shows that the step response has an undershoot (negative overshoot) of approximately 3 % and an almost unnoticeable overshoot. This demonstrates a characteristic close to that of an analog Bessel filter. Figure 51 contains one frequency response curve for each of the ten implemented cut-off frequency control values (0 to 9).

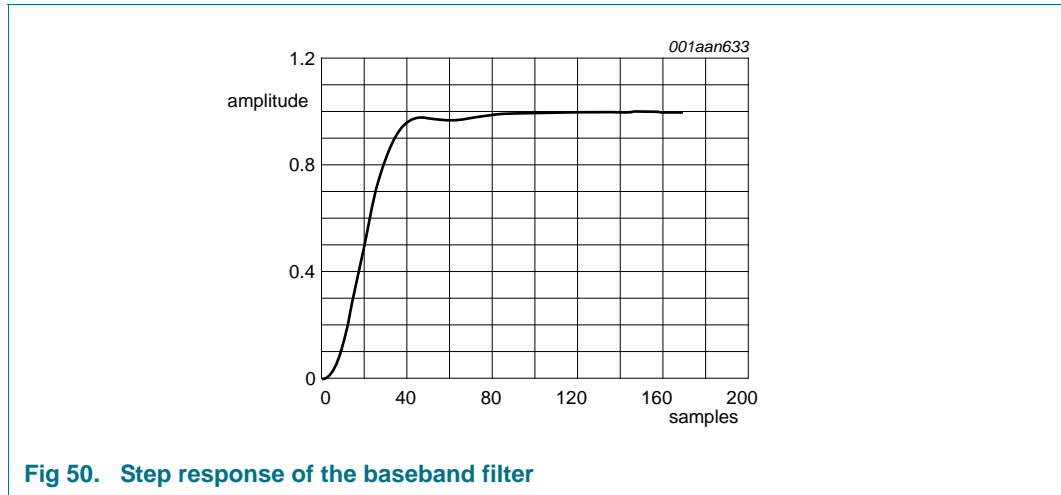


Fig 50. Step response of the baseband filter

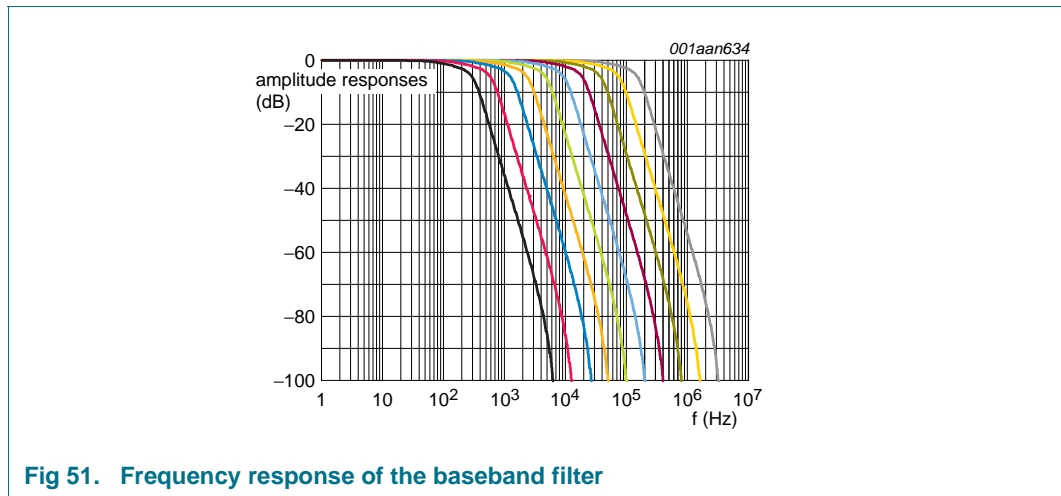


Fig 51. Frequency response of the baseband filter

The accurate output sampling frequency of the data filter can be calculated. The frequency is divided by a factor of 2 when the cut-off frequency control setting is incremented by 1. The relevant formula is:

$$f_c = \frac{114 \text{ kHz}}{2^{\text{FskFilterFc}}} \tag{41}$$

It can be seen that each increment in the cut-off frequency control setting divides the corner frequency of the filter by approximately a factor of 2.

Table 26. BASEBAND_FILTER_FC definition

D3	D2	D1	D0	Cut-off frequency (f_c)	Down-sampling factor	Output sampling rate
0	0	0	0	115.45 kHz	2	8 MHz
0	0	0	1	57.174 kHz	4	4 MHz
0	0	1	0	28.405 kHz	8	2 MHz
0	0	1	1	14.204 kHz	16	1 MHz
0	1	0	0	7.0795 kHz	32	500 kHz
0	1	0	1	3.5400 kHz	64	250 kHz
0	1	1	0	1.7701 kHz	128	125 kHz
0	1	1	1	885.12 Hz	256	62.5 kHz
1	0	0	0	442.59 Hz	512	31.25 kHz
1	0	0	1	221.31 Hz	1024	15625 Hz
-	-	-	-	undefined	undefined	undefined

7.41 RX debug interface

If the digital scan test and the channel filter multi-tone test are both not active (CF_MULTITONE_EN = 0), setting RXD_DBG_SEL[3:0] to a non-zero value switches ports P10/DATA/TEST4, P11/INT/TEST5 and P12/CLOCK into RX digital debug mode; see [Section 8.2.5.1 “Register TEST0” on page 126](#). In this mode the normal function of these pins is overwritten with the function of a fast 3-wire synchronous serial transmission, where:

- P12/CLOCK outputs the 16 MHz serial clock
- P10/DATA/TEST4 outputs the serial data. This data changes with the 16 MHz clock rising edge and it is stable at the clock falling edge. Each data word consists of 16 bits. Words are transmitted starting with the MSB and ending with the LSB.
- P11/INT/TEST5 outputs a synchronization pulse for each serial 16-bit data word. This line goes HIGH during transmission of bit 0, which is the last bit of each word. After the pulse, transmission continues with the MSB of the next 16-bit word.

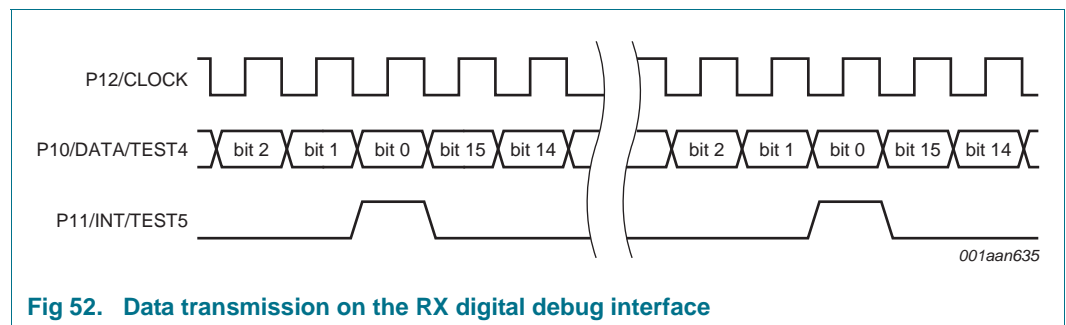


Fig 52. Data transmission on the RX digital debug interface

RXD_DBG_SEL[3:0] determines which 16-bit signal vector is sampled in parallel at 1 Msamples/s and output as a serial data stream as shown in [Figure 52](#). The available debug signal vectors are given in [Table 27](#).

Table 27. Available RX debug signal vectors

RXD_DBG_SEL	Bit range	Signal name	Signal description
1	[15:8]	w8RssiLevelOut	digitized RSSI result as it can be retrieved through the status register RSSI_LEVEL
1	[7]	wIFSettledIn	indicates when the 300 kHz IF signal is declared stable
1	[6]	wRssiSettled	indicates when the RSSI result is declared stable
1	[5:0]	r6RawRssiAdcValOut	raw RSSI ADC readings
2	[15:4]	w12FiltDRssi	RSSI signal after the 1st order low-pass filter
2	[3]	rFrontEndGainLoOut	indicates which of the front-end gain settings are applied. 0: RX_HI_GAIN, 1: RX_LO_GAIN
2	[2]	wRssiGtUpperTh	indicates when the RSSI result is greater than the threshold set with UPPERRSSITH
2	[1]	wRssiLtLowerTh	indicates when the RSSI result is less than the threshold set with LOWERRSSITH
2	[0]	wRssiOutsideLimitsOut	indicates when the RSSI is outside the limits defined with both LOWERRSSITH and UPPERRSSITH.
3	[15:4]	w12DataFilter1Res	baseband signal after the 1st-order section of the baseband filter
3	[3]	wLimIfIIn	digital IF input from the I channel limiter
3	[2]	wLimIfQIn	digital IF input from the Q channel limiter
3	[1]	wRawXorFmDemod	raw, unfiltered output from the XOR FM demodulator
3	[0]	wIFSettled	indicates when the 300 kHz IF signal is declared stable
4	[15:1]	w15BasebandSig	filtered and interpolated baseband signal
4	[0]	wBasebandValid	indicates when the baseband signal is declared valid
5	[15:1]	w15SlicerInitThrRegOut	contents of the initial slicer threshold register. This is the same as it is available through registers SLICERINITL and SLICERINITH.
5	[0]	wLoadInitSlicerThr	indicates when the initial threshold register is re-loaded. At chip rates > 7812 chip/s this pulse is shorter than the sampling interval and so pulses may be missed
6	[15:1]	w15SlicerThr	threshold of the level slicer.
6	[0]	wLoadSlicerThr	indicates when the threshold is re-loaded. At chip rates > 7812 chip/s this pulse is shorter than the sampling interval and so pulses may be missed.
7	[15:8]	ws8ClkRcvPllPhaseError	signed clock recovery phase error measurement value in offset binary format.
7	[7:0]	-	always zero (Reserved)
8	[15]	wRxFrame	indicates when data is being received
8	[14]	wRxData	RX data sampled with wRxClock and optionally Manchester decoded
8	[13]	wRxClock	Recovered bit clock
8	[12]	wPatternMatch	raw pattern match indicator from the preamble detection block
8	[11]	wChipClock	raw chip clock from clock recovery PLL
8	[10]	wEdgeDetected	edge detector output from deglitcher, pulses are shorter than the sampling interval for chip rates > 7812 chip/s so some pulses may be missed

Table 27. Available RX debug signal vectors ...continued

RXD_DBG_SEL	Bit range	Signal name	Signal description
8	[9]	wDeglitchedLevel	output from deglitcher block
8	[8]	wDeglitchedLevelValid	indicates when deglitcher output and edge detector output are valid
8	[7]	wSlicerResult	selected slicer result
8	[6]	wSlicerReady	indicates when selected slicer is ready to deliver a valid signal
8	[5]	wSlicerValid	indicates when selected slicer actually delivers a valid signal
8	[4]	wBasebandValid	indicates when baseband signal is declared valid
8	[3]	wRxRdyOut	indicates when RX hardware is ready and baseband signal is stable, same as bit RX_RDY in register DEVICE_STATUS
8	[2]	wIfSigSettledTo2ndOrderFilt	indicates when IF signal is declared stable, signal principally the same as the next but is longer for processing with slower clock
8	[1]	wIfSigSettled	indicates when IF signal is declared stable
8	[0]	wRxAnaRdy	indicates when analog RX hardware is ready (powered up and calibrated)
9	[15]	wCmdTimeout	indicates when a timeout occurs during a wakeup search or preamble detection
9	[14]	wSigMonFail	logic 1 if enabled signal monitors indicate a fail condition
9	[13]	wSigMonPass	logic 1 if signal monitors indicate a pass condition
9	[12]	wCmdTimeoutEn	indicates when command timeout counter is active
9	[11]	wCTVTimeout	indicates a chip timing verification timeout (no edges for more than (3.5 – REDUCED_CHIP_TIMEOUT) times the chip duration)
9	[10]	wSingleBitTmgError	single chip timing error (interval between two edges exceeds limits defined by SGLBITTMGERRTH[1:0])
9	[9]	wCodeCheckerError	indicates code checker detected an error
9	[8]	wCTVValid	valid signal for chip timing verification block, indicates validity of chip timeout, single chip timing error and code checker
9	[7]	wBaudrateCheckerError	indicates baud-rate checker error
9	[6]	wBaudrateCheckerValid	baud-rate checker result is valid signal
9	[5]	wRssiOutsideLimits	indicates current RSSI result is outside limits defined by registers UPPERRSSITH and LOWERRSSITH
9	[4]	wRssiSettledOut	indicates when RSSI result is declared stable
9	[3]	wSigAmpTooHigh	indicates baseband amplitude (modulation amplitude) is greater than limit defined by register UPPER_MODAMP_TH
9	[2]	wSigAmpTooHighValid	valid indicator for signal wSigAmpTooHigh
9	[1]	wSigAmpTooLow	indicates baseband amplitude (modulation amplitude) smaller than limit defined by register LOWER_MODAMP_TH
9	[0]	wSigAmpTooLowValid	valid indicator for signal wSigAmpTooLowValid
9	-	-	always zero (reserved)

8. Special function registers

8.1 Overview

A map of the Special Function Registers (SFR) is shown in [Table 28](#).

The SFRs are arranged into two banks: bank 0 and bank 1. Bank 0 or bank 1 can be selected by setting bit BANK_SEL in register BANKSEL, visible in both banks, accordingly.

Bytes 0 to 2Dh and 3Fh can always be accessed, independent of the setting of bit BANK_SEL in register BANKSEL (3Fh). Clearing bit BANK_SEL enables bytes 2Eh to 3Eh in bank 0; the contents of bank 1 remain unchanged. Setting register BANKSEL activates bytes 2Eh to 3Eh in bank 1.

Reading from a status register returns the current status of the device. Writing to a status register is ignored by the device. Status bits are identified by [4] in [Table 28](#).

All control registers can be accessed via the SPI interface. If a control register contains less than 8 bits, writing to a non-existent bit has no effect and reading from a non-existent bit always returns a zero. All registers are control registers (Write only) unless otherwise indicated.

Some register bits provide information about the implemented state-machines. These additional status bits can change independently of SPI transmission. These bits are also identified by [4] in [Table 28](#), other bits such as VCO_SUBBAND[5:0] can also change.

The control registers remain stable during power-down. When a Power-on reset occurs, evaluated by reading bit IF_POR in register IFLAG), register bits identified by [1] in [Table 28](#) are preset to their default values.

Bits denoted by RFU are reserved. These bits are Read/Write but do not effect the device.

Table 28. Register map table

Register	Addr	Bank	Bit							Default value [7]	
			7 (MSB)	6	5	4	3	2	1		0 (LSB)
FC0L	00h	01	FC0L [1]			0	0	0	0	0000 0000	
FC0M	01h	01	FC0M [1]							0000 0000	
FC0H	02h	01	FC0H [1]							1011 0001	
FC1L	03h	01	FC1L [2]			0	0	0	0	XXXX XXXX	
FC1M	04h	01	FC1M [2]							XXXX XXXX	
FC1H	05h	01	FC1H [2]							XXXX XXXX	
FC2L	06h	01	FC2L [2]			0	0	0	0	XXXX XXXX	
FC2M	07h	01	FC2M [2]							XXXX XXXX	
FC2H	08h	01	FC2H [2]							XXXX XXXX	
FC3L	09h	01	FC3L [2]			0	0	0	0	XXXX XXXX	
FC3M	0Ah	01	FC3M [2]							XXXX XXXX	
FC3H	0Bh	01	FC3H [2]							XXXX XXXX	
VCOCON	0Ch	01	FORCE_VCO_CAL [3]	VCO_CAL_RUNNING [4]	VCO_SUBBAND [2]					0SXX XXXX	
LOCON	0Dh	01	CLK2SCLK_DELAY [1]			SKIP_VCO_CAL [1]	LOCK_DET_ON [1]	VCO_BAND [1]	RF_LO_DIV [1]	0000 0001	
TIMING0	0Eh	01	MAINSCL [1]							0000 0000	
TIMING1	0Fh	01	WATCHDOG_TIME [1]	PRESC [1]			MAINSCH [1]			0110 0000	
PORTCON0	10h	01	P11C [1]			P11INV [1]	P10C [1]		P10INV [1]	0010 1000	
PORTCON1	11h	01	P13C [1]		P13INV [1]	P12C [1]		P12INV [1]	0000 1110		
PORTCON2	12h	01	SEP_SDO [1]	SEP_RX_OUT [1]	SEP_TX_LINES [1]	RFU [1]	RFU [1]	P14C [1]	P14INV [1]	0000 0000	
PWRMODE	13h	01	0	0	0	POLLTIM_EN [1]	DEV_MODE [5]		PD [3]	RESET [3]	000S 0000
IEN	14h	01	IE_TXRX_RDY [1]	IE_EOF [1]	IE_PREA [1]	IE_WUPS [1]	IE_POLLTIM [1]	IE_WATCHDOG [1]	IE_BROWN_OUT [1]	0	0000 0000
IFLAG	15h	01	IF_TXRX_RDY [1]	IF_EOF [1]	IF_PREA [1]	IF_WUPS [1]	IF_POLLTIM [1]	IF_WATCHDOG [1]	IF_BROWN_OUT [1]	IF_POR [1]	0000 0001
POLLWUPTIME	16h	01	POLLWUPTIME [1]							1111 1111	
POLLACTION	17h	01	POLL_MODE [1]		RX_FREQ [2]		RX_CMD [2]	RX_GAIN [2]		SET_RX_FLAGS [2]	00XX XXXX
CLOCKCON	18h	01	MANUALPT_CAL [3]	PTCAL_RUNNING [4]	EXTPOLL_TIMRNG [1]	CLKSOURCESEL [1]			EXT_CLK_BUF_EN [1]	XODIS [1]	0S00 0100

Table 28. Register map table ...continued

Register	Addr	Bank	Bit								Default value ^[1]	
			7 (MSB)	6	5	4	3	2	1	0 (LSB)		
DEVSTATUS	19h	01	0	PA_ON ^[4]	PA_PWR_RDY ^[4]	LO-PWR_RDY ^[4]	RX_RDY ^[4]	TX_RDY ^[4]	LO_RDY ^[4]	REFCLK_RDY ^[4]	0SSS SSSS	
FDEV	1Ah	01	FDEV_EXP ^[2]				FDEV_MANT ^[2]				XXXX XXXX	
FRMP	1Bh	01	0	FRMP_EXP ^[2]			FRMP_MANT ^[2]				0XXX XXXX	
ACON0	1Ch	01	ASK0 ^[1]	0	AMH0X ^[2]	AMH0 ^[1]				10X1 1111		
ACON1	1Dh	01	ASK1 ^[2]	0	0	AMH1 ^[2]				X00X XXXX		
ACON2	1Eh	01	0	0	0	AML ^[1]				0000 0000		
ARMP	1Fh	01	0	ARMP_EXP ^[2]			ARMP_MANT ^[1]				0XX0 0000	
TXCON	20h	01	DOUBLE_SD_RESULT ^[1]	INV_TX_DATA_RFU ^[1]	TXCLKSEL_RFU ^[1]	TXCLKOUTSEL_RFU ^[1]	RFU ^[1]	RFU ^[1]	PAM_RFU ^[1]		0000 0001	
RXGAIN	21h	01	RX_HI_GAIN ^[1]				RX_LOW_GAIN ^[1]				1111 0000	
RXBW	22h	01	DEMOD_ASK ^[2]	CF_BW ^[1]			RSSI_FILTER_FC ^[2]				X000 XXXX	
GAINSTEP	23h	01	0	RSSI_GAIN_STEP_ADJ ^[2]							0XXX XXXX	
HIGAINLIM	24h	01	HI_GAIN_LIMIT ^[2]								XXXX XXXX	
UPPERRSSITH	25h	01	UPPERRSSITH ^[2]								XXXX XXXX	
LOWERRSSITH	26h	01	LOWERRSSITH ^[2]								XXXX XXXX	
RXBBCON	27h	01	DEGLITCHER_WINDOW_LEN ^[2]	BASEBAND_SETTL_TIME ^[2]			BASEBAND_FILTER_FC ^[2]				XXXX XXXX	
UMODAMPTH	28h	01	UPPER_MODAMP_TH_EXP ^[2]				UPPER_MODAMP_TH_MANT ^[2]				XXXX XXXX	
LMODAMPTH	29h	01	LOWER_MODAMP_TH_EXP ^[2]				LOWER_MODAMP_TH_MANT ^[2]				XXXX XXXX	
EMODAMPTH	2Ah	01	EDGE_MODAMP_TH_EXP ^[2]				EDGE_MODAMP_TH_MANT ^[2]				XXXX XXXX	
RXDCON0	2Bh	01	NUM_MODAMP_GAPS_W ^[2]	SLICERSEL_W ^[2]		SLICER_INITSEL_W ^[2]		INIT_ACQ_BITS_W ^[2]			XXXX XXXX	
RXDCON1	2Ch	01	NUM_MODAMP_GAPS_P ^[2]	SLICERSEL_P ^[2]		SLICER_INITSEL_PD ^[2]		INIT_ACQ_BITS_PD ^[2]			XXXX XXXX	
RXDCON2	2Dh	01	NUM_MODAMP_GAPS_D ^[2]	SLICERSEL_D ^[2]		CODINGRESTR_W ^[2]		CODING_RESTR_P ^[2]	CODING_RESTR_D ^[2]		XXXX XXXX	
SIGMON0	2Eh	0	WUPS_MODE ^[2]	SIGMON_EN_W ^[2]							0	XXXX XXX0
SIGMON1	2Fh	0	EN_PREADET_TIMEOUT ^[2]	SIGMON_EN_P ^[2]							ACCU_SIG_FAILS_P ^[2]	0XXX XXXX

Table 28. Register map table ...continued

Register	Addr	Bank	Bit								Default value ^[7]	
			7 (MSB)	6	5	4	3	2	1	0 (LSB)		
SIGMON2	30h	0	0				SIGMON_EN_D ^[2]				ACCU_SIG FAILS_D ^[2]	XXXX XXXX
WUPSTO	31h	0	WUPSTIMEOUTPRESC ^[2]			WUPSTIMEOUT ^[2]						XXXX XXXX
SLICERINITL	32h	0	SLICERINITTHR_LO ^[2]									XXXX XXXX
SLICERINITH	33h	0	0	SLICERINITTHR_HI ^[2]								0XXX XXXX
TIMINGCHK	34h	0	RFU ^[2]	BROBSLENGTH ^[2]		SUBMITTMGERRTH ^[2]			SGLBITTMGERRTH ^[2]			XXXX XXXX
RXCON	35h	0	STATAUTO SAMPLE ^[2]	AUTO SAMPLE MANUAL ^[2]	INV_RX_ DATA ^[2]	CLOCK_RECOV_TC ^[2]		RX_MAN CHESTER ^[2]	RX_CLOCK TRANSP ^[2]	RX_DATA_ TRANSP ^[2]		XXXX XXXX
RXFOLLOWUP	36h	0	PREA_FU_ TF ^[1]	PREA_FU_ CF ^[1]	WUPS_FU_TS ^[1]		WUPS_FU_ TF ^[1]	WUPS_FU_CS ^[1]		WUPS_FU_ CF ^[1]		1000 1000
SIGMONSTATUS	37h	0	SIGMONSTATUS ^[4]									SSSS SSSS
SIGMONERROR	38h	0	SIGMONERROR ^[4]									SSSS SSSS
RSSILEVEL	39h	0	RSSI_LEVEL ^[4]									SSSS SSSS
PREACON	3Ah	0	RFU ^[2]	PREA_TOL ^[2]		PREA_LEN ^[2]						XXXX XXXX
PREA0	3Bh	0	PREA0 ^[2]									XXXX XXXX
PREA1	3Ch	0	PREA1 ^[2]									XXXX XXXX
PREA2	3Dh	0	PREA2 ^[2]									XXXX XXXX
PREA3	3Eh	0	PREA3 ^[2]									XXXX XXXX
EXTRXSTATUS	2Eh	1	RX_HI_ GAIN ^[4]	LIVE_ STATUS ^[4]	RXCMD ^[4]		MANCHESTER_COUNT ^[4]					SSSS SSSS
CFRCCAL	2Fh	1	CF_IQ_CAL_ RUNNING ^[4]	CF_RC_ CAL_ RUNNING ^[4]	0	0	CF_RC_CAL_RES ^[4]					SS00 SSSS
CFIQCAL	30h	1	START_CF_ IQ_CAL ^[3]	CF_IQ_CALVAL ^[1]								0000 0000
EXPERT0	31h	1	RED_VCO_ SWING ^[1]	LARGE_ PLL_RST_ DELAY ^[1]	FASTCFFIL TSETTL ^[1]	PLL_ICP ^[1]					0000 0100	
EXPERT1	32h	1	XOSTARTUPDELAY ^[1]		ASKRSTBB MID ^[1]	RFU ^[1]	RFU ^[1]	DISFRAC ^[1]	LOCK_DET_TIME ^[1]			0100 1001
EXPERT2	33h	1	FM_DEM_ IANDQ ^[1]	LARGE_FM_ DEM_ RANGE ^[1]	WIDE_ AMPL_ WINDOW ^[1]	REDUCED_ CHIP_ TIME ^[1]	TWORSSIM SBITS SLOW ^[1]	FASTRSSI FILTSETTL ^[1]	CAP_RSSI ^[1]			0000 0010

Table 28. Register map table ...continued

Register	Addr	Bank	Bit								Default value [7]
			7 (MSB)	6	5	4	3	2	1	0 (LSB)	
EXPERT3	34h	1	0	0	0	0	RFU[1]	ALLOWREG SWITCH[6]	LTDIQ PHASECAL [1]	DONOT DISTURB PTCAP[1]	0000 0000
TEST0	35h	1	CF_MULTITONE_EN[6]	DIG_TEST_SEL[6]			RXD_DBG_SEL[6]				0110 0000
TEST1	36h	1	IQ_TEST_LV[6]	ANA_TEST_SEL[6]			REG_DIG_DIS[6]	PLL_CTRL[6]		VCO_TEST_ON[6]	0000 0000
TEST2	37h	1	REG_VCO_ON[6]	REG_PLL_ON[6]	REG_PA_ON[6]	FORCE_REG_VCO_RDY[5]	FORCE_REG_PLL_RDY[5]	FORCE_REG_PA_RDY[5]	FORCE_LOCK_DETECTED [5]	FORCE_XO_RDY[1]	0000 0000
TEST3	38h	1	VCO_ON[6]	PRESC_ON[6]	PFD_ON[6]	CLK_PLL_ON[6]	TX_ON[6]	RX_GAP_ON[6]	RX_ON[6]	PA_STEP_T EST[6]	0000 0000
TEST4	39h	1	FORCE_CF_RC_CAL[3]	SKIP_CF_RC_CAL[6]	CF_RC_ADJUSTCAL[6]		MAN_CF_RC_CALVAL[2]				0000 XXXX
TEST5	3Ah	1	XO_IOFFS[2]			XO_IOFF SSINK_EN [2]	XO_IOFF SEN[6]	XO_KICK_DIS[6]	XO_DET_DIS[6]	XO_BIAS_DIS[6]	XXXX 0000
RFU	3Bh	1	-[1]								0000 0000
TCBEN0	3Ch	1	-[3]								0000 0000
TCBR	3Dh	1	-				IDDQ1[1]	IDDQ0[1]	ASYNC SCAN[1]	SCANEN[1]	0000 0000
TCBEN1	3Eh	1	-[3]								0000 0000
BANKSEL	3Fh	01	0	0	0	0	0	0	0	BANK_SEL [5]	0000 0000

[1] Bits/field preset at power-on.

[2] Bits cannot be preset.

[3] Command bits.

[4] Status bit (Read only) and indicated by 'S' in the Default value column. Their values are undefined because they depend on the device status after a reset.

[5] Bits/field reset in power-down mode.

[6] Test bits.

[7] 'X' denotes the bit is undefined after a device reset; the value is completely random and independent of the device status.

8.2 Register descriptions

The SFRs are arranged into two banks: bank 0 and bank 1. Bank 0 or bank 1 can be selected by setting bit BANK_SEL in register BANKSEL, visible in both banks, accordingly.

8.2.1 Registers visible in both bank 0 and bank 1

8.2.1.1 Frequency control registers

The frequency control registers contain the PLL frequency control information. Four values can be stored to provide four independent frequency settings available for TX and RX purposes. The frequency values have 20 bits. These 20 bits are divided into 4 least significant bits (L) a medium significant byte (M) and a high significant byte (H).

Table 29. Frequency control register FC0L - (address 00h) bit description

Reset value = 00h.

Bit	Symbol	Value	Description
7	FC0L	0	lower 4 bits of 15-bit fractional part of operating frequency value FCx
6		0	
5		0	
4		0	
3	-	0	-
2		0	
1		0	
0		0	

Table 30. Frequency control register FC0M - (address 01h) bit description

Reset value = 00h.

Bit	Symbol	Value	Description
7	FC0M	0	middle 8 bits of 15-bit fractional part of operating frequency value FCx
6		0	
5		0	
4		0	
3		0	
2		0	
1		0	
0		0	

Table 31. Frequency control register FC0H - (address 02h) bit description

Reset value = B1h.

Bit	Symbol	Value	Description
7	FC0H	0	5 integer bits of operating frequency value FCx
6		0	
5		0	
4		0	
3		0	

Table 31. Frequency control register FC0H - (address 02h) bit description ...continued
Reset value = B1h.

Bit	Symbol	Value	Description
2	FCxH	1	high 3 bits of 15-bit fractional part of operating frequency value FCx
1		1	
0		0	

Frequency control register FC1L (address 03h); same bit description as FC0L, but reset value = XXh.

Frequency control register FC1M (address 04h); same bit description as FC0M, but reset value = XXh.

Frequency control register FC1H (address 05h); same bit description as FC0H, but reset value = XXh.

Frequency control register FC2L (address 06h); same bit description as FC0L, but reset value = XXh.

Frequency control register FC2M (address 07h); same bit description as FC0M, but reset value = XXh.

Frequency control register FC2H (address 08h); same bit description as FC0H, but reset value = XXh.

Frequency control register FC3L (address 09h); same bit description as FC0L, but reset value = XXh.

Frequency control register FC3M (address 0Ah); same bit description as FC0M, but reset value = XXh.

Frequency control register FC3H (address 0Bh); same bit description as FC0H, but reset value = XXh.

8.2.1.2 VCO control register VCOCON

Table 32. VCO control register VCOCON - (address 0Ch) bit description

Bit	Symbol	Value	Description
7	FORCE_VCO_CAL	0	starts a VCO calibration unconditionally when requested by microcontroller. 1 = calibration starts.
6	VCO_CAL_RUNNING	S	status bit indicates the VCO calibration is requested or is in progress. 0 = sub-band value, which can be read from this register, is valid and stable.
5	VCO_SUBBAND	X	resulting sub-band settings from the automatic VCO calibration, value can be overwritten at any time by the microcontroller. If the value is written during an ongoing calibration, the result is undefined. 0 = maximum frequency, and 63h to the minimum frequency.
4		X	
3		X	
2		X	
1		X	
0		X	

8.2.1.3 Local oscillator control register LOCON

Table 33. Local oscillator control register LOCON - (address 0Dh) bit description

Bit	Symbol	Value	Description
7	CLK2SCLK_DELAY	0	delay from the 9th SCLK edge in a TX/RX command until the device starts driving the SCLK line. Only applicable if bit SEP_TX_LINES is logic 0 when sending a TX command, or bit SEP_RX_OUT is logic 0 when sending an RX command.
6		0	
5		0	
4		0	
3	SKIP_VCO_CAL	0	automatic VCO calibration performed under the following circumstances: <ul style="list-style-type: none"> • if the active FCxH, VCO_BAND, RF_LO_DIV, DOUBLE_SD_RESULT, DISFRAC changes • if the device mode switches from/to RX mode • if frequency selection flags A, B change • if the PLL is started from idle mode calibration under the first three conditions can be suppressed by setting this bit. Calibration is always executed on the last condition: PLL start up.
2	LOCK_DET_ON	0	1 = lock detector continuously monitors the PLL during operation. When logic 0, the lock detector only monitors the PLL for a short time after VCO calibration.
1	VCO_BAND	0	must be set to 1 for RF frequency bands below 400 MHz. Must be set to logic 0 for all other bands.
0	RF_LO_DIV	1	0 = VCO frequency is divided by 2 to achieve TX and RX frequency above 500 MHz. 1 = VCO frequency is divided by 4 to achieve TX and RX frequency below 500 MHz.

8.2.1.4 Timing register TIMING0

Register TIMING0 (address 0Eh), MAINSCL[6:0]: main scaler lower byte of baud-rate generator; see [Table 34](#) for description.

8.2.1.5 Timing register TIMING1

Table 34. Timing register TIMING1 - (address 0Fh) bit description

Bit	Symbol	Value	Description
7	WATCHDOG_	0	programmable watchdog timeout: watchdog timeout = $\frac{2^{15+WATCHDOG_TIME}}{CLK_{ref}}$
6	TIME	1	
5	PRESC	1	baud-rate prescaler setting generator. Baud rate is calculated: baud rate = $\frac{CLK_{ref}}{2^{PRESC}} \times \frac{2^{11} + MAINSC}{2^{12}} \times \frac{1}{128}$ where CLK _{REF} = 16 MHz, PRESC is an exponent in the range 0 to 7 and 2 ¹¹ + MAINSC is the mantissa in the range 2048 to 4095. The resulting baud-rate clock can jitter by one prescaler clock cycle CLK _{PSC} .
4		0	
3		0	

Table 34. Timing register TIMING1 - (address 0Fh) bit description ...continued

Bit	Symbol	Value	Description
2	MAINSCH	0	3 highest bits of baud-rate generator's main scaler
1		0	
0		0	

8.2.1.6 Port control registers PORTCON0 to PORTCON2

Registers PORTCON0 to PORTCON2 define the function of Port pins P10, P11, P12, P13 and P14. Test functions can be enabled in combination with register TEST0. Register PORTCON2 defines the general SPI mode.

8.2.1.7 Port control register PORTCON0

Table 35. Port control register PORTCON0 - (address 10h) bit description

Bit	Symbol	Value	Description
7	P11C	0	configures P11/INT; see Table 37
6		0	
5		1	
4		0	
3	P11INV	1	inverts the pin polarity
2	P10C	0	configures P10/DATA; see Table 36
1		0	
0	P10INV	0	logic 1 inverts the pin polarity

Table 36. P10C port control data functions

D2	D1	Function
0	0	3-state
0	1	constant LOW
1	0	PRNG output
1	1	reserved

Table 37. P11C port control data functions

D7	D6	D5	D4	Function
0	0	0	0	3-state
0	0	0	1	always zero
0	0	1	0	interrupt request
0	0	1	1	clock output from clock generation according to CLKSOURCESEL[2:0] settings
0	1	0	0	CF_IQ_CAL_RUNNING
0	1	0	1	LO_RDY flag
0	1	1	0	RX_RDY flag
0	1	1	1	TX_RDY flag
1	0	0	0	PA_ON flag
1	0	0	1	PA_ON request

Table 37. P11C port control data functions ...continued

D7	D6	D5	D4	Function
1	0	1	0	reserved signal; always 0
1	0	1	1	
1	1	0	0	
1	1	0	1	
1	1	1	0	test signals controlled by DIG_TEST_SEL[2:0]; see Table 38 and Table 39
1	1	1	1	

The test signals shown in [Table 38](#) are available if register PORTCON0 bits D7 = 1, D6 = 1, D5 = 1, D4 = 0 and if DIG_TEST_SEL[2:0] in register TEST0 (address 35h), are set according to this table.

Table 38. Test signal I

D6	D5	D4	Function
0	0	0	digital regulator enable
0	0	1	VCO regulator enable
0	1	0	PLL regulator enable
0	1	1	PA regulator enable
1	0	0	XO enable
1	0	1	
1	1	0	
1	1	1	XO startup signal kick A

The test signals shown in [Table 39](#) are available if register PORTCON0 bits D7 = 1, D6 = 1, D5 = 1, D4 = 1 and if DIG_TEST_SET[2:0] in register TEST0 (address 35h), are set according to this table.

Table 39. Test signal II

D6	D5	D4	Function
0	0	0	I signal from limiter
0	0	1	channel filter RC calibration enable
0	1	0	polling timer enable
0	1	1	RSSI DAC value LSB
1	0	0	PLL lock detector enable
1	0	1	
1	1	0	reserved
1	1	1	

8.2.1.8 Port control register PORTCON1

Table 40. Port control register PORTCON1 - (address 11h) bit description

Bit	Symbol	Value	Description
7	P13C	0	configures P13/SDO
6		0	
5		0	
4	P13INV	0	1= inverts the pin polarity

Table 40. Port control register PORTCON1 - (address 11h) bit description ...continued

Bit	Symbol	Value	Description
3	P12C	0	configures P12/CLOCK; see Table 41
2		1	
1		1	
0	P12INV	0	1 = inverts the pin polarity

Table 41. P12C port control data functions

D3	D2	D1	Function
0	0	0	3-state
0	0	1	always zero
0	1	0	TX clock output: if bit SEP_TX_LINES = 1 and TX is activated or RX clock output; if bit SEP_RX_OUT = 1 and RX is activated.
0	1	1	clock generated output according to CLKSOURCESEL[2:0]
1	0	0	PLL feedback clock
1	0	1	uncalibrated polling timer clock
1	1	0	test signals controlled by DIG_TEST_SEL[2:0]; see Table 42 and Table 43
1	1	1	

The test signals shown in [Table 42](#) are available if register PORTCON1 bits D3 = 1, D2 = 1, D1 = 0 and if DIG_TEST_SET[2:0] in register TEST0 (address 35h), are set according to this table.

Table 42. Test signal III

D6	D5	D4	Function
0	0	0	digital regulator brown-out detection
0	0	1	VCO regulator brown-out detection
0	1	0	PLL regulator brown-out detection
0	1	1	PA regulator brown-out detection
1	0	0	XO_RDY
1	0	1	XO startup signal kick A
1	1	0	XO startup signal kick C
1	1	1	

The test signals shown in [Table 43](#) are available if register PORTCON1 bits D3 = 1, D2 = 1, D1 = 1 and if DIG_TEST_SET[2:0] in register TEST0 (address 35h), are set according to this table.

Table 43. Test signal IIII

D6	D5	D4	Function
0	0	0	Q signal from limiter
0	0	1	CF_RC_CAL_RUNNING flag
0	1	0	uncalibrated polling timer clock
0	1	1	RSSI ADC comparator output
1	0	0	PLL lock detector signal (raw)

Table 43. Test signal IIII ...continued

D6	D5	D4	Function
1	0	1	PLL lock detector signal (digitally filtered)
1	1	0	continuous 1 MHz clock
1	1	1	constant LOW (reserved)

Table 44. P13C port control data functions

D3	D2	D1	Function
0	0	0	3-state
0	0	1	always zero
0	1	0	TX modulation signal, including Manchester encoding if applicable; bistable signal. Modulator ramp control is handled separately.
0	1	1	RX_RDY or TX_RDY
1	0	0	REFCLK_RDY
1	0	1	LO_RDY
1	1	0	RX_RDY
1	1	1	TX_RDY

8.2.1.9 Port control register PORTCON2

Table 45. Port control register PORTCON2 - (address 12h) bit description

Bit	Symbol	Value	Description
7	SEP_SDO	0	1 = P13 is 3-state or SPI data output and has priority over the normal function of P13 [1]
6	SEP_RX_OUT	0	if set to 1 and a RX command is active, P10 is always (independent of P10C settings) used as RX data and P12 conditionally used as RX clock output, depending on P12C configuration, see Table 46 [1]
5	SEP_TX_LINES	0	if set to 1 and a TX command is active, P10 is always (independent of P10C settings) used as TX data input and P12 conditionally used as TX clock output, depending on P12C configuration, see Table 47 [1]
4	RFU	0	reserved
3	RFU	0	reserved
2	P14C	0	configures P14/PIND; see Table 48
1		0	
0	P14INV	0	1 = inverts the pin polarity

[1] SEP_xxx bits override all other P13 port settings. P10C configured functions are overridden if bit SEP_TX_LINES = 1 and TX is activated or if bit SEP_RX_OUT = 1 and RX is activated.

Table 46. SEP_RX_OUT data functions

SEP_RX_OUT	RX data output	RX clock output
0	SDIO or SDO, depending on SEP_SDO	SCLK
1	P10/DATA	P12/CLOCK (optional, only if P12C = 010b)

Table 47. SEP_TX_LINES data functions

SEP_TX_LINES	TX data input	TX clock output
0	SDIO	SCLK
1	P10/DATA	P12/CLOCK (optional, only if P12C = 010b)

Table 48. P14C port control data functions

D2	D1	Function
0	0	3-state
0	1	constant LOW
1	0	0 = RX_MODE, 1 = TX_MODE, or 3-state
1	1	0 = RX_MODE, 1 = TX_MODE, or 3-state

8.2.1.10 General power mode register PWRMODE

Table 49. General power mode register PWRMODE - (address 13h) bit description

Bit	Symbol	Value	Description
7	0	0	-
6		0	
5		0	
4	POLLTIM_EN	S	polling timer enable bit. Initialization occurs on every (power-on) reset. Bit POLLTIM_EN is set to the inverse of pin RSTDIS. Therefore this pin controls polling timer initial condition. 1 = polling initially disabled; see Table 50 and Table 51
3	DEV_MODE	0	device mode control bits; see Table 52
2		0	
1	PD	1	power-down bit: logic 1 puts device into standby mode where it consumes much less power. All analog RX and TX circuitry and the XTAL oscillator are turned off. All dynamic digital activity is stopped except SPI and polling timer, if enabled. ^[1]
0	RESET	0	reset bit: logic 1 puts the device into power-on state, the same state reached after powering up the device. If set logic 1 with a Write command, all other bits, simultaneously written to register PWRMODE, are ignored as the register is forced to the power-on state.

[1] Bit PD can also be set automatically at Power-on reset or setting bit RESET, watchdog timer timeout, or receive state machine request. A logic 1 cannot be read because the SPI Read command causes the OL2381 to exit Power-down mode.

Table 50. POLLTIM_EN data functions

D4	Function
0	polling timer off and no current is drawn
1	polling timer on

Table 51. Polling timer status after master reset

Pin RSTDIS	Status after master reset
LOW	POLLTIM_EN = 1: polling timer is activated with the settings of register POLLWUPTIME = 255 and EXTPOLLTIMRNG = 0.
HIGH	POLLTIM_EN = 0: polling timer off

Table 52. DEV_MODE[1:0] device mode control functions

D3	D2	Function
0	0	crystal oscillator or external clock buffer is enabled and after crystal oscillator stabilization (if selected) the device is supplied with the reference clock
0	1	PLL controlled local oscillator (LO) enabled. LO power-up procedure includes VCO sub-band calibration (unconditionally) and PLL lock-in detection
1	0	prepare and enable RX operation. LO enabled and after PLL acquires lock, RX is switched on and enabled
1	1	prepare and enable TX operation. LO enabled and after PLL acquires lock, TX path and PA regulator are switched on and enabled. Although PA is effectively on, power control is held at zero, resulting in PA RF leakage of approximately -30 dBm RF output.

8.2.1.11 Interrupt enable register IEN

Table 53. Interrupt enable register IEN - (address 14h) bit description

Bit	Symbol	Value	Description
7	IE_TXRX_RDY	0	triggered if either RX or TX mode is successfully reached after automatic start-up sequences issued [1]
6	IE_EOF	0	EOF is generated in data reception mode if an enabled signal monitor detects an unsatisfactory RX signal condition. This is the case when data reception mode is reached either automatically after a successful preamble detection or upon receipt of a DATA RX command.
5	IE_PREA	0	triggered on every completion of a preamble detection regardless of whether it was successful or not
4	IE_WUPS	0	triggered on every completion of a wakeup search regardless of whether it was successful or not
3	IE_POLTIM	0	triggered when a polling timer event takes place
2	IE_WATCHDOG	0	triggered when a watchdog overflow takes place
1	IE_BROWNOUT	0	triggered on brown-out detection of the voltage regulators (undervoltage detection)
0	0	0	0

[1] Issuing another TX or RX command will not trigger this interrupt when the device is already in TX or RX mode, respectively. An interrupt is only generated when the ready state is reached.

8.2.1.12 Interrupt flag register IFLAG

The IFLAG bits indicate if an interrupt source is triggered since this register was last read. The register bits are always set to logic 0 after being read.

Table 54. Interrupt flag register IFLAG - (address 15h) bit description

Bit	Symbol	Value	Description
7	IF_TXRX_RDY	0	set after completion of automatic start-up sequences (RX or TX)
6	IF_EOF	0	
5	IF_PREA	0	successful preamble detection (non-maskable)
4	IF_WUPS	0	successful wakeup search (non-maskable)
3	IF_POLLTIM	0	polling timer event (non-maskable)
2	IF_WATCHDOG	0	watchdog overflow
1	IF_BROWNOUT	0	undervoltage detection
0	IF_POR	1	first battery power-on reset (battery insertion detection). Setting bit RESET also sets the IF_POR flag.

8.2.1.13 Polling timer control register POLLWUPTIME

Table 55. Polling timer control register POLLWUPTIME - (address 16h) bit description

Bit	Symbol	Value	Description
7	POLLWUPTIME	1	sets polling timer wakeup time. Wakeup time is calculated by:
6		1	$T_{WUP} = (POLLWUPTIME + 1)T_{WUPTICK}$
5		1	where $T_{WUPTICK}$ is either 1 ms or 16 ms depending on bit
4		1	EXTPOLLIMRNG (extended polling timer range).
3		1	
2		1	
1		1	
0		1	

8.2.1.14 Polling action register POLLACTION

Table 56. Polling action register POLLACTION - (address 17h) bit description

Bit	Symbol	Value	Description
7	POLL_MODE	0	defines the operating mode the device enters after a polling timer event, see Table 57
6		0	
5	RX_FREQ	X	RX_FREQ[1:0] means the same as RX flags RA and RB (frequency selection)
4		X	
3	RX_CMD	X	bit RX_CMD means the same as RX flag RC. It allows a choice between a WUPS (logic 0) and a PRDA (logic 1) command.
2	RX_GAIN	X	RX_GAIN[1:0] means the same as RX flags RE and RF (gain step/switch selection bits)
1		X	
0	SET_RX_FLAGS	X	defines whether the current contents of RX flag register is used for the automatically initiated RX command (if logic 0) or whether RX flags RA, RB, RC, RE and RF are overwritten with the contents of RX_FREQ[1:0], RX_CMD and RX_GAIN[1:0] settings of this register, respectively, before the command is actually launched (if logic 1). If the flags are overwritten, the RX flag RD is set to logic 1 to make the sub-command either a WUPS or a PRDA command.

Table 57. POLL_MODE[1:0] device mode control functions

D7	D6	Function
0	0	after signaling the polling timer interrupt, which is unmaskable, the device remains in Power-down mode
0	1	after signaling the polling timer interrupt, which is unmaskable, the device leaves Power-down mode, which turns the crystal oscillator or the external clock buffer on
1	0	device is fully powered up to RX mode. If the polling timer interrupt is enabled, an interrupt occurs, either with the polling timer event or when the receiver is ready
1	1	device is fully powered up to RX mode. After RX settles, an RX command is automatically initiated as configured by the remaining bits of this register. It is guaranteed that at least one interrupt will occur in the command sequence.

8.2.1.15 Clock connection register CLOCKCON

Table 58. Clock connection register CLOCKCON - (address 18h) bit description

Bit	Symbol	Value	Description
7	MANUALPTCAL	0	manual start of polling timer calibration. Reading bit MANUALPTCAL always yields zero. Manual calibration is only executed if polling timer and crystal oscillator are running. Otherwise the request is ignored.
6	PTCALRUNNING	S	status bit set when polling timer calibration is running
5	EXTPOLLTIMRNG	0	extended polling timer range calculated by: $T_{WUPTICK} = 1 + 15 \times EXTPOLLTIMRNG$ ms; see Table 59
4	CLKSOURCESEL	0	clock selection for selected port pin; see Table 60
3		0	
2		1	
1	EXT_CLK_BUF_EN	0	external clock buffer enable bit is used to turn on clock buffer for external clock. The effect of this bit also depends on bit XODIS; see Table 61
0	XODIS	0	

Table 59. EXTPOLLTIMRNG bit functions

EXTPOLLTIMRNG	Wakeup counter resolution $T_{WUPTICK}$	Selectable wakeup times T_{WUP}
0	1 ms	1 ms to 256 ms
1	16 ms	16 ms to 4096 ms

Table 60. CLKSOURCESEL bit functions

D4	D3	D2	Port pin
0	0	0	reference clock (16 MHz)
0	0	1	reference clock / 2 (8 MHz)
0	1	0	reference clock / 4 (4 MHz)
0	1	1	reference clock / 8 (2 MHz)
1	0	0	4 × chip clock

Table 60. CLKSOURCESEL bit functions ...continued

D4	D3	D2	Port pin
1	0	1	2 × chip clock
1	1	0	chip clock
1	1	1	bit clock

Table 61. EXT_CLK_BUF_EN / XODIS bit functions

D1	D0	Function
0	0	crystal oscillator enabled. Digital reference clock disabled during oscillator start-up.
0	1	crystal oscillator and external clock buffer disabled
1	0	crystal oscillator enabled. Digital reference clock permanently enabled and during oscillator start-up.
1	1	crystal oscillator disabled and external clock buffer enabled. Digital reference clock permanently enabled.

8.2.1.16 Device status register DEVSTATUS

Table 62. Device status register DEVSTATUS - (address 19h) bit description

Bit	Symbol	Value	Description
7	0	0	-
6	PA_ON	0	logic 1 indicates PA is turned on by a TX command. This remains set until ramp-down is completed (if engaged) after request is made to terminate transmission. Logic 0 indicates PA is not transmitting (although it may be supplied with power and thus emitting some RF (-30 dBm) due to leakage.
5	PA_PWR_RDY	0	logic 1 indicates PA regulator is supplying power to the PA
4	LO_PWR_RDY	0	logic 1 indicates VCO and PLL regulators are delivering power to these LO sections
3	RX_RDY	S	status bit: automated RX mode preparation sequence ready, device ready for RX
2	TX_RDY	S	status bit: automated TX mode preparation sequence ready, device ready for TX
1	LO_RDY	S	status bit: VCO running, PLL settled and locked
0	REFCLK_RDY	S	status bit: XTAL oscillator stable or external clock available. External clock stability is not checked by the device.

8.2.1.17 Register FDEV

Register FDEV bits set the TX FSK frequency deviation; see [Section 7.20.1 “Frequency modulation” on page 42](#) for the calculation of the frequency deviation that is actually applied.

Table 63. FSK frequency deviation register FDEV - (address 1Ah) bit description

Bit	Symbol	Value	Description
7	FDEV_EXP	X	FSK frequency deviation 3-bit exponent
6		X	
5		X	

Table 63. FSK frequency deviation register FDEV - (address 1Ah) bit description ...continued

Bit	Symbol	Value	Description
4	FDEV_MANT	X	FSK frequency deviation 5-bit mantissa. 0 = no modulation.
3		X	
2		X	
1		X	
0		X	

8.2.1.18 FSK ramp adjustment register FRMP

Register FRMP bits adjust the FSK ramp (GFSK-type modulation); see [Section 7.20.2 “Soft FSK” on page 43](#).

Table 64. FSK ramp adjustment register FRMP - (address 1Bh) bit description

Bit	Symbol	Value	Description
7	0	0	
6	FRMP_EXP	X	soft FSK ramp duration 3-bit exponent
5		X	
4		X	
3	FRMP_MANT	X	soft FSK ramp duration 4-bit mantissa. 0 = no ramp (squarewave-shaped modulation).
2		X	
1		X	
0		X	

8.2.1.19 Register ACON0**Table 65. Register ACON0 - (address 1Ch) bit description**

Bit	Symbol	Value	Description
7	ASK0	1	if 1 and if ACON0 is the active configuration set, then ASK modulation is used instead of FSK modulation
6	0	0	
5	AMH0X	X	if test bit PA_STEP_TEST (TEST3.0) is logic 1, this is the MSB of the linear 6-bit power control word
4	AMH0	1	if this power control set is selected for transmission (TX command flag F = 0), this becomes the output power control in FSK mode or the power setting when the modulation signal is 0 in ASK mode
3		1	
2		1	
1		1	
0		1	

8.2.1.20 Register ACON1**Table 66. Register ACON1 - (address 1Dh) bit description**

Bit	Symbol	Value	Description
7	ASK1	X	if set to logic 1 and if ACON1 is the active configuration set, then ASK modulation is used instead of FSK modulation
6	0	0	0
5	0	0	0

Table 66. Register ACON1 - (address 1Dh) bit description ...continued

Bit	Symbol	Value	Description
4	AMH1	X	if this power control set is selected for transmission (TX command flag F = 1), this becomes the output power control in FSK mode or the power setting when the modulation signal is 0 in ASK mode
3		X	
2		X	
1		X	
0		X	

8.2.1.21 Register ACON2**Table 67. Register ACON2 - (address 1Eh) bit description**

Bit	Symbol	Value	Description
7	0	0	-
6	0	0	-
5	0	0	-
4	AML	0	If ASK modulation is selected, this controls the output power when the modulation signal is 1.
3		0	
2		0	
1		0	
0		0	

8.2.1.22 Register ARMP

The ARMP bits adjust the ASK ramp (soft power-on sequence); see [Section 7.18 "Soft ASK, ramp control" on page 41](#) for more details. These settings are also applied in FSK mode to ramp the carrier up and down at the start and end of the transmission frame.

Table 68. Register ARMP - (address 1Fh) bit description

Bit	Symbol	Value	Description
7	0	0	-
6	ARMP_EXP	0	ARMP amplitude ramp duration 2-bit exponent
5		0	
4	ARMP_MANT	0	ARMP amplitude ramp duration 5-bit mantissa
3		0	
2		0	
1		0	
0		0	

8.2.1.23 Transmitter control register TXCON

Table 69. Transmitter control register TXCON - (address 20h) bit description

Bit	Symbol	Value	Description
7	DOUBLE_SD_RESULT	0	configures the Sigma delta fractional-N modulation; see Section 7.14.7 "Delta-sigma modulator for fractional-N synthesis" on page 30 for details
6	INV_TX_DATA	0	logic 0 produces center frequency plus frequency deviation in FSK mode and also the power value set with AMHx in ASK mode; a logic 1 produces center frequency minus frequency deviation in FSK mode and also the power value set by AML. Setting bit INV_TX_DATA inverts this assignment. This is valid for NRZ mode and for the first bit half in Manchester mode; during the second half, the signal is inverted with respect to the first half.
5	TXCLKSEL	0	clock source for data-transmission synchronization. When logic 1, the bit clock is used as the TX clock ($CLK_{TX} = CLK_{BIT}$). If logic 0, the chip clock is used as the TX clock ($CLK_{TX} = CLK_{CHIP}$). If automatic Manchester generation is required the bit clock must be selected.
4	TXCLKOUTSEL	0	selects the clock output at port pin SCLK or P12/CLOCK
3		0	
2	RFU	0	reserved
1	PAM	0	power mode selection for PA. The PA supply voltage can be selected between 3 different levels, enabling different output power ranges to be selected.
0		1	

Table 70. RX frequency offset

RF_LO_DIV	DOUBLE_SD_RESULT	Offset value	Frequency resolution (Hz)	RX frequency offset
0	0	614	488.3	299.805 kHz
0	1	307	976.6	
1	0	1228	244.1	
1	1	614	488.3	

Table 71. Clock output selection for the TX command, TXCLKOUTSEL

D4	D3	Selected clock at SCLK or P12/CLOCK during TX command
0	0	CLK_{TX}
0	1	$CLK_{TX} \times 2$
1	0	$CLK_{TX} \times 4$
1	1	no clock selected

Table 72. PAM definition^[1]

D1	D0	PA supply	Output power range
0	0	1.5 V	-17 dBm to 10 dBm
0	1	1.75 V	-13 dBm to 11 dBm
1	0	1.95 V	-11 dBm to 12 dBm
1	1	reserved	-

- [1] The values were obtained using a fixed matching network, with an output load of 150 Ω at 900 MHz. In specific cases where power values below -10 dBm are required, adapt the optimum matching network. Power steps of 1 dB (maximum) are valid only when the output power is above 0 dBm.

8.2.1.24 Receiver gain control register RXGAIN

Table 73. Receiver gain control register RXGAIN - (address 21h) bit description

Bit	Symbol	Value	Description
7	RX_HI_GAIN	1	sets the desired gain for high gain mode including both RF front-end gain and channel filter gain settings
6		1	
5		1	
4		1	
3	RX_LO_GAIN	0	sets the desired gain for low gain mode including both RF front-end gain and channel filter gain settings
2		0	
1		0	
0		0	

8.2.1.25 Channel filter bandwidth and RSSI filter settings register RXBW

Table 74. Channel filter bandwidth and RSSI filter settings register RXBW - (address 22h) bit description

Bit	Symbol	Value	Description
7	DEMOD_ASK	X	switches the digital baseband filter input and baseband signal processing chain to the ASK demodulator output
6	CF_BW	0	channel filter bandwidth selection bits, see Table 75
5		0	
4		0	
3	RSSI_FILTER_FC	X	RSSI corner frequency selection bits
2		X	
1		X	
0		X	

Table 75. CF_BW bit functions

D6	D5	D4	Bandwidth (kHz)
0	0	0	300
0	0	1	200
0	1	0	150
0	1	1	100
1	0	0	75
1	0	1	50

8.2.1.26 Register GAINSTEP

Table 76. Register GAINSTEP - (address 23h) bit description

Bit	Symbol	Value	Description
7	0	0	-
6	RSSI_GAIN_STEP_ADJ	X	the receiver automatically adds this value to the filtered and properly scaled RSSI reading whenever it is in low gain mode to compensate for the difference (high gain minus low gain). This seamlessly extends the RSSI's dynamic range by switching the RX chain gain.
5		X	
4		X	
3		X	
2		X	
1		X	
0		X	

8.2.1.27 Register HIGAINLIM

Table 77. Register HIGAINLIM - (address 24h) bit description

Bit	Symbol	Value	Description
7	HI_GAIN_LIMIT	0	8-bit gain switching threshold value [1]
6		0	
5		0	
4		0	
3		X	
2		X	
1		X	
0		X	

[1] If the RSSI reading exceeds this value during a wakeup search, the RX gain can be switched from RX_HI_GAIN to RX_LO_GAIN automatically provided it is programmed to do so (flags E, F = 01b).

8.2.1.28 Registers UPPERSSITH and LOWERSSITH

Registers UPPERSSITH (address 25h) and LOWERSSITH (address 26h) contain the 8-bit upper and lower RSSI threshold level respectively. This value is compared against the digitized RSSI value in the RSSI level classification unit.

8.2.1.29 Register RXBBCON

Table 78. Register RXBBCON - (address 27h) bit description

Bit	Symbol	Value	Description
7	DEGLITCHER_	X	control the deglitcher's hold-off time to suppress multiple signal transitions when a noisy baseband signal crosses the slicer threshold, see Table 80
6	WINDOW_LEN	X	

Table 78. Register RXBBCON - (address 27h) bit description ...continued

Bit	Symbol	Value	Description
5	BASEBAND_	X	adjusts the baseband settling delay. Delay is the time between the declared valid IF signal and the declared valid baseband signal. The delay is $2 \times (1 + \text{BASEBAND_SETTL_TIME}) \times \text{chip duration}$. Correct adjustment of this delay is essential if operating a wakeup search in pessimistic mode, because signal measurement and classification must not be started until the whole RX chain (including the channel and baseband filters) are settled. The dominant settling time is usually the baseband filter and must be taken into account
4	SETTL_TIME	X	
3	BASEBAND_	X	baseband digital filter cut-off frequency
2	FILTER_FC	X	
1		X	
0		X	

Table 79. DEGLITCHER_WINDOW_LEN bit functions

D7	D6	Deglitcher lock duration
0	0	0
0	1	2 / 16 of chip width
1	0	3 / 16 of chip width
1	1	4 / 16 of chip width

8.2.1.30 Register UMODAMPTH

Table 80. Register UMODAMPTH - (address 28h) bit description

Bit	Symbol	Value	Description
7	UPPER_MODAMP_	X	$\text{UPPER_MODAMP_TH_EXP} = \max\left\{0, \left\lfloor \log_2\left(\frac{\text{UMODAMPTH}}{7.75}\right) \right\rfloor\right\}$
6	TH_EXP	X	
5		X	
4		X	
3	UPPER_MODAMP_	X	$\text{UPPER_MODAMP_TH_MANT} = 0.5 + \frac{\text{UMODAMPTH}}{2^{\text{UPPER_MODAMP_TH_EXP}}}$
2	TH_MANT	X	
1		X	
0		X	

Register UMODAMPTH contains the upper modulation amplitude measurement threshold level (modulation amplitude classification unit). In FSK mode one increment corresponds to approximately 6.2 Hz when bit LARGE_FM_DEM_RANGE is logic 0 and approximately 18.6 Hz when bit LARGE_FM_DEM_RANGE is logic 1. In ASK mode one increment corresponds to approximately 1.5 dB/512 = 0.00293 dB.

In FSK mode:
$$\text{UMODAMPTH} = F_{DEV} \times \frac{1 + \frac{T}{100}}{200 \text{ kHz} \times (1 + 2 \times \text{LARGE_FM_DEM_RANGE})} \times 32256$$
where F_{DEV} = nominal peak-to-peak frequency deviation (Hz), T = tolerance (%).

In ASK mode: $UMODAMPTH = ASK_{MOD} \times \frac{1 + \frac{T}{100}}{1.5} \times 512$ where $ASK_{MOD} = ASK$ modulation amplitude ratio (dB), T = tolerance (%).

Remark: The specified amplitude is peak-to-peak.

8.2.1.31 Register LMODAMPTH

Register LMODAMPTH (address 29h) contains the lower modulation amplitude measurement threshold level (modulation amplitude classification unit). It configures the threshold level similar to register UMODAMPTH.

In FSK mode: $LMODAMPTH = F_{DEV} \times \frac{1 + \frac{T}{100}}{200 \text{ kHz} \times (1 + 2 \times \text{LARGE_FM_DEM_RANGE})} \times 32256$ where F_{DEV} = nominal peak-to-peak frequency deviation (Hz), T = tolerance (%).

In ASK mode: $LMODAMPTH = ASK_{MOD} \times \frac{1 + \frac{T}{100}}{1.5} \times 512$ where $ASK_{MOD} = ASK$ modulation amplitude ratio (dB), T = tolerance (%).

Remark: The specified amplitude is peak-to-peak.

8.2.1.32 Register EMODAMPTH

Table 81. Register EMODAMPTH - (address 2Ah) bit description

Bit	Symbol	Value	Description
7	EDGE_MODAMP_TH	0	expected peak modulation value; calculation of
6		0	EDGE_MODAMP_TH ; see register
5		0	UMODAMPTH
4		0	
3		0	
2		0	
1		0	
0		0	

The EMODAMPTH register contains the expected peak modulation value used as the amplitude reference value for the edge slicer. It configures the threshold level similar to register UMODAMPTH.

In FSK mode: $EMODAMPTH = F_{DEV} \times \frac{F_{DEV}}{200 \text{ kHz} \times (1 + 2 \times \text{LARGE_FM_DEM_RANGE})} \times 32256$ where F_{DEV} = nominal peak-to-peak frequency deviation (Hz).

In ASK mode: $EMODAMPTH = \frac{ASK_{MOD}}{3} \times 512$ where $ASK_{MOD} = ASK$ modulation amplitude ratio (dB).

Remark: The specified amplitude is peak.

8.2.1.33 Register RXDCON0

Table 82. Register RXDCON0- (address 2Bh)

Register	Nomenclature
RXDCON0	wakeup search settings
RXDCON1	preamble detection settings
RXDCON2	data reception settings

Table 83. Register RXDCON0 - (address 2Bh) bit description

Bit	Symbol	Value	Description
7	NUM_MODAMP_GAPS_W	X	the maximum expected duration, expressed as a number of chip widths, between any two transitions minus 1, for example, if data stream '0000' were Manchester encoded, the data stream at chip level appears as '01010101', a transition occurring every single chip width, therefore the value is logic 0.
6		X	
5	SLICERSEL_W	X	data slicer selection for wakeup search phase, see Table 84
4		X	
3	SLICERINIT_SEL_W	X	initial initialization mode selection for selected slicer type for wakeup search phase
2		X	
1	INIT_ACQ_BITS_W	X	2, 4 or 8-bit averaging on initial acquisition during wakeup search. The initial acquisition updates slicer initialization register and slicer threshold after every calculation of 2, 4, and 8 bits; see Table 86
0		X	

Table 84. SLICERSEL_W bit functions

D5	D4	Function
0	0	edge slicer selected
0	1	level-sensitive slicer selected. The low-pass filter is not activated, which means that the current slicer threshold is held constant. Slicer threshold initialization is accomplished according to the setting of SLICERINITSEL_W[1:0]
1	0	level-sensitive slicer is selected and low-pass filter with a time-constant of 2 bits (4 chips) is activated continuously. Slicer threshold initialization is accomplished according to the setting of SLICERINITSEL_W[1:0].
1	1	level-sensitive slicer is selected and low-pass filter with a time-constant of 8 bits (16 chips) is activated continuously. Slicer threshold initialization is accomplished according to the setting of SLICERINITSEL_W[1:0].

Table 85. SLICERINITSEL_W bit functions

D3	D2	Function
0	0	slicer threshold is never initialized

Table 85. SLICERINITSEL_W bit functions ...continued

D3	D2	Function
0	1	slicer threshold is initialized with the content of register SLICERINITH at the start of a RX event.
1	0	initial acquisition is achieved at the start of a RX event. Slicer threshold is updated each time a new result is available from the initial acquisition.
1	1	same as setting 10 but the initial acquisition is automatically restarted when a chip duration timeout occurs

Table 86. INIT_ACQ_BITS_x bit functions

D1	D0	Number of bits used to calculate slicer threshold
0	0	0
0	1	2
1	0	4
1	1	8

8.2.1.34 Register RXDCON1

Table 87. Dynamic RX mode control register RXDCON1 - (address 2Ch) bit description

Bit	Symbol	Value	Description ^[1]
7	NUM_MODAMP_	X	number of expected modulation gaps during preamble detection
6	GAPS_P	X	
5	SLICERSEL_P	X	data slicer selection for preamble detection phase
4		X	
3	SLICERINIT_	X	initial initialization mode selection for selected slicer type for preamble detection and data reception
2	SEL_PD	X	
1	INIT_ACQ_BITS_PD	X	2, 4 or 8-bit averaging on initial acquisition during preamble detection and data reception. Initial acquisition updates the slicer initialization register and slicer threshold after every calculation of 2, 4, and 8 bits.
0		X	

[1] See [Table 82](#) for detailed explanation of control bits.

8.2.1.35 Register RXDCON2

Table 88. Dynamic RX mode control register RXDCON2 - (address 2Dh) bit description

Bit	Symbol	Value	Description
7	NUM_MODAMP_	X	number of expected modulation gaps during data reception
6	GAPS_D	X	
5	SLICERSEL_D	X	data slicer selection for data reception phase
4		X	

Table 88. Dynamic RX mode control register RXDCON2 - (address 2Dh) bit description

Bit	Symbol	Value	Description
3	CODINGRESTR_W	X	wakeup search, coding verification unit. Selection of the permitted signal encoding, see Table 89
2		X	
1	CODINGRESTR_P	X	coding restriction for preamble detection. If logic 0, no restriction, both time intervals (1 × chip and 2 × chip width) are accepted in an arbitrary order. If logic 1, both time intervals are accepted and the sequence is checked for Manchester coding.
0	CODINGRESTR_D	X	coding restriction selection for data reception. If logic 0, no restriction, both time intervals (1 × chip and 2 × chip width) are accepted in an arbitrary order. If logic 1, both time intervals are accepted and the sequence is checked for Manchester coding.

[1] See [Table 82](#) for detailed explanation of control bits.

Table 89. CODINGRESTR_W bit function

D3	D2	Function
0	0	no restriction, both time intervals (1 × chip and 2 × chip width) are accepted in an arbitrary order
0	1	only short time interval (1 × chip width) is accepted
1	0	only long time interval (2 × chip width) is accepted
1	1	both time intervals are accepted and the sequence is checked for Manchester coding

8.2.2 Registers only visible in bank 0

8.2.2.1 Signal monitoring register SIGMON0

Table 90. Signal monitoring registers SIGMON0, SIGMON1 and SIGMON2

Register	Nomenclature
SIGMON0	wakeup search settings
SIGMON1	preamble detection settings
SIGMON2	data reception settings

Table 91. Signal monitoring control register SIGMON0 - (address 2Eh) bit description

Bit	Symbol	Value	Description
7	WUPSMODE	X	wakeup search mode selection bit, see Table 92
6	SIGMON_EN_W	X	selection of signal monitor (signal signature recognition unit) to be activated during wakeup search, see Table 93
5		X	
4		X	
3		X	
2		X	
1		X	
0	0	0	-

Table 92. WUPSMODE bit functions

D7	Function
0	'pessimistic' wakeup search (also called mode 1): wakeup search ends when either one of the enabled signal monitors signals a FAIL or all enabled signal monitors signal PASS. In the first case the result of the wakeup search is FAIL; in the latter case it is PASS
1	'optimistic' wakeup search (also called mode 2): wakeup search ends when either all enabled signal monitors signal a PASS or the wakeup search timer expires. In the first case the result of the wakeup search is PASS; in the latter case it is FAIL.

Table 93. SIGMON_EN_W bit functions

Bit	Symbol	Value	Description (if set)
6	SIGMON_EN_W	X	enable chip timeout
5		X	enable chip timing
4		X	enable coding check
3		X	enable baud-rate check
2		X	enable RSSI level check
1		X	enable modulation amplitude detection

8.2.2.2 Signal monitoring control register SIGMON1

Table 94. Signal monitoring control register SIGMON1 - (address 2Fh) bit description

Bit	Symbol	Value	Description
7	EN_PREADET_TIMEOUT	X	if logic 1, wakeup search timeout (WUPSTO) is also applied to the preamble detection
6	SIGMON_EN_P	X	selection of signal monitor (signal signature recognition unit) to be active during preamble detection, see Table 93
5		X	
4		X	
3		X	
2		X	
1		X	
0	ACCU_SIG_FAILS_P	X	logic 1 causes error indicators to be accumulated over the duration of preamble detection. Accumulator is reset at the start of preamble detection and when the microcontroller samples the status.

8.2.2.3 Signal monitoring control register SIGMON2

Table 95. Signal monitoring control register SIGMON2 - (address 30h) bit description

Bit	Symbol	Value	Description
7	0	0	-
6	SIGMON_EN_D	X	selection of signal monitor (signal signature recognition unit) to be active during data reception, see Table 93 . If an enabled signal monitor detects an abnormal condition, it is indicated by the IF_EOF (End-of-Frame flag).
5		X	
4		X	
3		X	
2		X	
1		X	
0	ACCU_SIG_FAILS_D	X	logic 1 causes the error indicators to be accumulated over the duration of data reception. The accumulator is reset at the start of data reception and when the microcontroller samples the status.

8.2.2.4 Register WUPSTO

Table 96. Wakeup search timeout control register WUPSTO - (address 31h) bit description

Bit	Symbol	Value	Description
7	WUPSTIMEOUTPRESC	X	prescaler for wakeup search timeout counter, see Table 97
6		X	
5	WUPSTIMEOUT	X	sets timeout to $WUPSTIMEOUT[4:0] \times T_{WUPSTO}$ for $WUPSTIMEOUT[4:0] = 1$ to 63. Value $WUPSTIMEOUT[4:0] = 0$ disables the timeout timer and sets timeout to infinity
4		X	
3		X	
2		X	
1		X	
0		X	

Table 97. WUPSTIMEOUTPRESC bit functions

D7	D6	Clock selection for wakeup search timeout timer T_{WUPSTO}
0	0	$T_{BIT} \times 2$
0	1	$T_{BIT} \times 4$
1	0	$T_{BIT} \times 16$
1	1	$T_{BIT} \times 64$

8.2.2.5 Register SLICERINITL

Register SLICERINITL (address 32h) bits are the slicer's LSBs data threshold acquired during intialisation. This register can be read to measure, for example, the TX to RX frequency offset or to save a correct threshold value for later use. The register can be written, for example to restore a previously saved threshold value. Note that the register SLICERINIT value is different from the actual threshold value.

8.2.2.6 Register SLICERINITH

Register SLICERINITH (address 33h) bits are the slicer's MSBs data threshold acquired during initialization.

8.2.2.7 Register TIMINGCHK

Register TIMINGCHK (address 34h) configures the timing-check units.

Table 98. Register TIMINGCHK - (address 34h) bit description

Bit	Symbol	Value	Description
7	RFU	X	reserved
6	BROBSLENGTH	X	baud rate observation length setting: number of observed bits configurable to 8, 16, 24 or 32 bits, see Table 99
5		X	
4	SUMBITTMGERRTH	X	baud-rate checker threshold value for the sum of 8-bits timing, see Table 100
3		X	
2		X	
1	SGLBITTMGERRTH	X	single chip timing check threshold value. The time interval is accepted if its absolute value is below the limit. Corresponds to timing errors which are less than 12.5 %, 18.75 %, 25 % or 37.5% of a nominal chip width respectively; see Table 101
0		X	

Table 99. BROBSLENGTH bit functions

D6	D5	Number of nominal bits to be considered for baud-rate checker
0	0	8
0	1	16
1	0	24
1	1	32

Table 100. SUMBITTMGERRTH bit functions

D4	D3	D2	Total timing error threshold in $T_{CHIP} / 128$ per 8 bits	Relative limit with respect to 8 nominal bits (%)
0	0	0	16	0.78
0	0	1	24	1.17
0	1	0	32	1.56
0	1	1	48	2.34
1	0	0	64	3.13
1	0	1	96	4.69
1	1	0	128	6.25
1	1	1	192	9.38

Table 101. SGLBITTMGERRTH bit functions

D1	D0	Single chip timing error threshold in $T_{CHIP} / 128$ per interval
0	0	16
0	1	24
1	0	32
1	1	48

8.2.2.8 Register RXCON

Table 102. Receive mode control register RXCON - (address 35h) bit description

Bit	Symbol	Value	Description
7	STATAUTOSAMPLE	X	allows the software to control whether the status is sampled when certain Read commands are issued. Automatically set to logic 0 after a wakeup search and preamble detection to save the result of this command
6	AUTOSAMPLEMANUAL	X	logic 1 prevents bit STATAUTOSAMPLE being set on completion of an RSSILEVEL read
5	INV_RX_DATA	X	inverts the slicer output. If logic 0, in FSK mode the lower frequency is received as logic 1 and the higher frequency is received as logic 0, whereas in ASK mode the lower RF amplitude is received as logic 0 and the higher RF amplitude is received as logic 1. If synchronizing the Manchester decoder with a preamble it samples the slicer output in the middle of the first half of a bit.
4	CLOCK_RECOV_TC	X	set time-constant of clock recovery settling time, see Table 103
3		X	
2	RX_MANCHESTER	X	if logic 1, data is Manchester decoded. Manchester decoding is done by skipping every other chip clock pulse. Which two possible pulse trains is omitted is set after recognizing the programmed preamble during a preamble detection. If data reception is initiated without prior preamble detection, there is an equal chance that either the right or the wrong clock pulse train is suppressed. In the first case, RX data is decoded properly; in the latter case, RX data is inverted. The MANCHESTER_COUNT in register EXTRXSTATUS helps determines if data was received correctly or inverted.
1	RX_CLOCK_TRANSP	X	if logic 1, the clock output is always the chip clock produced by the clock recovery PLL. If logic 0, the clock output is always the bit clock which is equal to the chip clock in NRZ mode during data reception. During wakeup search and preamble detection the clock is held HIGH. The microcontroller must sample the RX data line with the bit clock 1-to-0 transition.
0	RX_DATA_TRANSP	X	If logic 1, the data output is taken from the deglitched slicer result. If logic 0, the deglitched slicer result is re-sampled with the bit clock's rising edge. Therefore the microcontroller must take the data with the bit clock 1-to-0 transition. During the wakeup search, the data line is kept LOW, whereas during preamble detection it is held HIGH.

Table 103. CLOCK_RECOV_TC bit functions

D4	D3	Maximum settling time (chips)	Maximum bit edge phase error (deg)	Tolerance (%)
0	0	3 (not recommended)	8	8

Table 103. CLOCK_RECOV_TC bit functions ...continued

D4	D3	Maximum settling time (chips)	Maximum bit edge phase error (deg)	Tolerance (%)
0	1	7	15	4
1	0	15	30	2
1	1	31	60	1

8.2.2.9 Register RXFOLLOWUP

Table 104. Receive mode follow-up control register RXFOLLOWUP - (address 36h) bit description

Bit	Symbol	Value	Description
7	PREA_FU_TF	1	<p>this bit is only effective: when preamble detection (PRDA), was initiated by the polling timer event, and preamble detection failed.</p> <p>if this bit is logic 1: device enters power-down.</p> <p>if this bit is logic 0: device stops, but stays on, a non-maskable interrupt occurs.</p>
6	PREA_FU_CF	0	<p>this bit is only effective: when preamble detection (PRDA), was initiated by command, and preamble detection failed.</p> <p>if this bit is logic 1: device enters power-down.</p> <p>if this bit is logic 0: device stops, but stays on.</p>
5 4	WUPS_FU_TS	0 0	<p>these bits are only effective: when wakeup search (WUPS), was initiated by the polling timer event, and a WUPS signal was detected.</p> <p>if these bits are logic 0X: device stops, but stays on, a non-maskable interrupt occurs.</p> <p>if these bits are logic 11: device enters data receive mode. a non-maskable interrupt occurs.</p> <p>if these bits are logic 10: device enters PRDA mode.</p>

Table 104. Receive mode follow-up control register RXFOLLOWUP - (address 36h) bit description ...continued

Bit	Symbol	Value	Description
3	WUPS_FU_TF	1	<p>this bit is only effective:</p> <ul style="list-style-type: none"> when wakeup search (WUPS), was initiated by the polling timer event, and WUPS detection failed. <p>if this bit is logic 1:</p> <ul style="list-style-type: none"> device enters power-down. <p>if this bit is logic 0:</p> <ul style="list-style-type: none"> device stops, but stays on, a non-maskable interrupt occurs.
2	WUPS_FU_CS	0	<p>these bits are only effective:</p> <ul style="list-style-type: none"> when wakeup search (WUPS), was initiated by command, and a WUPS signal was detected. <p>if these bits are logic 0X:</p> <ul style="list-style-type: none"> device stops, but stays on. a non-maskable interrupt occurs. <p>if these bits are logic 11:</p> <ul style="list-style-type: none"> device enters data receive mode. <p>if these bits are logic 10:</p> <ul style="list-style-type: none"> device enters PRDA mode.
1		0	
0	WUPS_FU_CF	0	<p>this bit is only effective:</p> <ul style="list-style-type: none"> when wakeup search (WUPS), was initiated by command, and WUPS detection failed. <p>if this bit is logic 1:</p> <ul style="list-style-type: none"> device enters power-down. <p>if this bit is logic 0:</p> <ul style="list-style-type: none"> device stops, but stays on.

8.2.2.10 Register SIGMONSTATUS

Table 105. Status register SIGMONSTATUS - (address 37h) bit description

See [Section 7.36 "Wakeup search logic" on page 76](#) for further details.

Bit	Symbol	Value	Description
7	SIGMONSTATUS	S	if logic 1, the previous wakeup search or preamble detection has failed. If logic 0, the command completed successfully. Other status registers can be read to ascertain more information if required.
6		S	chip timeout
5		S	chip timing
4		S	coding
3		S	baud rate
2		S	RSSI level
1		S	modulation amplitude too high
0		S	modulation amplitude too low

8.2.2.11 Register SIGMONERROR

Table 106. Status register SIGMONERROR - (address 38h) bit description

Bit	Symbol	Value	Description
7	SIGMONERROR	S	WUP timeout
6		S	chip timeout
5		S	chip timing
4		S	coding
3		S	baud rate
2		S	RSSI level
1		S	modulation amplitude too high
0		S	modulation amplitude too low

Table 107. Signal monitor states set by registers SIGMONSTATUS and SIGMONERROR

SIGMONSTATUS	SIGMONERROR	Signal monitor status
0	0	decision not yet available
0	1	not possible
1	0	no error detected
1	1	error detected

8.2.2.12 Register RSSILEVEL

Table 108. Register RSSI - (address 39h) bit description

Bit	Symbol	Value	Description
7	RSSI_LEVEL	0	result of RSSI conversion
6		0	
5		0	
4		0	
3		X	
2		X	
1		X	
0		X	

Register RSSI contains the measured RSSI level at the completion of a wakeup search or preamble detection, or at the moment the microcontroller recently triggered sampling the RX signal status.

8.2.2.13 Register PREACON

Table 109. Preamble detection control register PREACON - (address 3Ah) bit description

Bit	Symbol	Value	Description
7	RFU	0	reserved
6	PREA_TOL	X	definition of allowed chip errors during preamble detection, see Table 110
5		X	
4	PREA_LEN	X	definition of pattern length of preamble to be detected. Defined in chips, 1 to 31 is the length in chips; 0 = 32 chips.
3		X	
2		X	
1		X	
0		X	

Table 110. PREA_TOL bit functions

D6	D5	Value
0	0	0
0	1	1
1	0	2
1	1	3

8.2.2.14 Register PREA0

Register PREA0 (address 3Bh) contains the 8 least-significant chips[7:0] of the preamble pattern assuming the preamble MSB is sent first.

8.2.2.15 Register PREA1

Register PREA1 (address 3Ch) contains bits [15:8] of the preamble pattern.

8.2.2.16 Register PREA2

Register PREA2 (address 3Dh) contains bits [23:16] of the preamble pattern.

8.2.2.17 Register PREA3

Register PREA3 (address 3Eh) contains bits [31:24] of the preamble pattern.

8.2.3 Registers only visible in bank 1

8.2.3.1 Register EXTRXSTATUS

Table 111. Register EXTRXSTATUS - (address 2Eh) bit description

Bit	Symbol	Value	Description
7	RX_HIGH_GAIN	S	logic 1 when high gain is selected, logic 0 when low gain is selected (either automatically or by command)
6	LIVE_STATUS	S	logic 0 if the consistent set of status information is automatically sampled on completion of wakeup search or preamble detection. Logic 1 if the status was sampled by a Read operation from one of the 4 receiver status registers.
5	RX_CMD	S	RX sub-command code during which, or on completion, the status is sampled. 00 = IDLE, 01 = WUPS, 10 = PREA and 11 = DATA.
4		S	
3	MANCHESTER_COUNT	S	accumulated sum of RX data changes within a single chip period, see Section 7.38 "RX data decoding" on page 81
2		S	
1		S	
0		S	

8.2.3.2 Register CFRCCAL

Table 112. Register CFRCCAL - (address 2Fh) bit description

Bit	Symbol	Value	Description
7	CF_IQ_CAL_RUNNING	S	status bit indicates running IQ calibration
6	CF_CAL_RUNNING	S	status bit indicates running RC calibration
5	0	0	-
4	0	0	-
3	CF_RC_CAL_RES	S	result of RC auto-calibration
2		S	
1		S	
0		S	

8.2.3.3 Register CFIQCAL

Table 113. IQ calibration register CFIQCAL - (address 30h) bit description

Bit	Symbol	Value	Description
7	START_CF_IQ_CAL	0	setting this bits starts the I/Q calibration sequence
6	CF_IQ_CALVAL	S	configuration for the best I/Q calibration. The result of a triggered calibration sequence used in production test. Configuration value must be initialized and stored by the external microcontroller for every individual device to achieve best image rejection performance.
5		0	
4		0	
3		0	
2		0	
1		0	
0		0	

8.2.4 Expert registers

The expert registers enable the use of built-in functions for special application cases. It is recommended that these settings are not changed.

8.2.4.1 Register EXPERT0

Table 114. Register EXPERT0 - (address 31h) bit description

Bit	Symbol	Value	Description
7	RED_VCO_SWING	0	automatically set at lower band, if logic 1, VCO output swing and LO power consumption are reduced. If logic 0, VCO is running at highest drive level.
6	LARGE_PLL_RST_DELAY	0	if logic 1, the PLL phase detector reset pulse width is increased from 2.1 ns to 3.1 ns
5	FASTCFFILTSETTL	0	if logic 0, sufficient delay is provided until the channel filter is declared settled after an input transient. Especially important if a WUPS is performed in pessimistic mode. Logic 1 reduces the delay allowing faster operation. A small reduction of settling accuracy is acceptable for all other RX commands.
4	PLL_ICP	0	manual programming of PLL charge pump current. The final charge pump current can be computed as a function of the register setting using formula: $I_{cp} = PLL_ICP \times 15 \mu A$ see Section 7.14.4 "Charge pump" on page 30 .
3		0	
2		1	
1		0	
0		0	

8.2.4.2 Register EXPERT1

Table 115. Register EXPERT1 - (address 32h) bit description

Bit	Symbol	Value	Description
7	XOSTARTUPDELAY	0	sets/influences delay after XO_READY detection.
6		1	Required for influencing automated startup sequences, see Table 116
5	ASKRSTBBMID	0	applies only when receiving ASK. If left at logic 0, baseband filter resets to logic 0 (corresponding to minus infinite dBm plus noise level) after an input transient. If logic 1, baseband filter resets to the mid-point corresponding to RSSI mid-range in dBm.
4	RFU	0	reserved
3		1	
2	DISFRAC	0	disables PLL fractional-N mode
1	LOCK_DET_TIME	0	sets additional delay after 'physical' PLL lock detection.
0		1	Available delays are: 00 = 16 μs , 01 = 32 μs , 10 = 48 μs , 11 = 64 μs , required for influencing automated startup sequences.

Table 116. XOSTARTUPDELAY bit functions

D7	D6	Delay time
0	0	256 μs

Table 116. XOSTARTUPDELAY bit functions ...continued

D7	D6	Delay time
0	1	512 μ s (default Power-on reset value)
1	0	768 μ s
1	1	1024 μ s

8.2.4.3 Register EXPERT2

Table 117. Register EXPERT2 - (address 33h) bit description

Bit	Symbol	Value	Description
7	FM_DEM_IANDQ	0	if logic 1, I and Q limiter outputs are used for FSK demodulation
6	LARGE_FM_DEM_RANGE	0	logic 0 selects 200 kHz range (200 kHz to 400 kHz), logic 1 selects 600 kHz range (0 Hz to 600 kHz). 0 Hz is a theoretical value limited to the channel filter AC coupling lower corner frequency.
5	WIDE_AMPL_WINDOW	0	selects the number of samples window to be used for edge detection amplitude. Logic 0 selects 2 samples at -1 and +1 either side of center. Logic 1 selects 4 samples at -2, -1, +1 and +2 either side of center.
4	REDUCED_CHIP_TIMEOUT	0	selects timeout value for the chip timing verification block. Logic 0 selects 3.5 chips, logic 1 selects 2.5 chips.
3	TWORSSIMSBITSSLOW	0	determines time taken to acquire the 2 MSBs in the RSSI ADC. Logic 0 selects 3 clocks for bit 5 and 1 clock for bit 4. Logic 1 selects 2 clocks for bit 5 and 2 clocks for bit 4.
2	FASTRSSIFILTSETTL	0	controls the RSSI filter settling time. Logic 0 selects 4 time-constants settling to within 2 % of the last step. Logic 1 selects 2 time-constants settling to within 14 % of the last step.
1	CAPRSI	1	allows the RSSI analog data low-pass filter to be trimmed changing the filter capacitor values which affect the low-pass cut-off frequency, see Table 119
0		0	

Table 118. FM demodulator configurations

D7	D6	Center frequency (kHz)	Input frequency range (kHz)	Maximum frequency deviation (kHz)	Number of delay elements
0	0	300	200 to 400	\pm 100	40
0	1	300	0 to 600	\pm 300	13
1	0	600	200 to 400	\pm 100	20
1	1	600	0 to 600	\pm 300	7

Table 119. CAPRSSI bit functions

D1	D0	Typical capacitor value (pF)	Time-constant (R = 300 k Ω typical)
0	0	0	0 (parasitics only)

Table 119. CAPRSSI bit functions ...continued

D1	D0	Typical capacitor value (pF)	Time-constant (R = 300 k Ω typical)
0	1	2	0.6 μ s
1	0	5	1.5 μ s
1	1	12	4.8 μ s

8.2.4.4 Register EXPERT3

Table 120. Register EXPERT3 - (address 34h) bit description

Bit	Symbol	Value	Description
7	0	0	-
6	0	0	-
5	0	0	-
4	0	0	-
3	TESTBUFFERCAL	0	logic 1 turns the calibration path on. Required during test buffer calibration
2	ALLOWREGSWITCH	0	controls the behavior of the REG_XXX_ON test bits. If logic 0, the REG_XXX_ON bits are OR'd to the normal control lines allowing unconditional turn-on of selected regulators. If logic 1, the REG_XXX_ON bits replace the normal control lines allowing full control (on and off) of the regulators.
1	LTDIQPHASECAL	0	if logic 0, all possible matching combinations in the RX chain are attempted in order to achieve the best image rejection. If logic 1, certain phase trimming values are forbidden to eventually achieve a better overall performance over temperature.
0	DONOTDISTURBPTCAL	0	if logic 0, a polling timer calibration can run in parallel with the PLL startup. If logic 1, the PLL startup, when requested, is delayed until the polling timer calibration ends.

8.2.5 Test registers

The test register bits are initialized to logic 0 after power-up. Test registers must never be used in standard applications.

8.2.5.1 Register TEST0

Table 121. Register TEST0 - (address 35h) bit description

Bit	Symbol	Value	Description
7	CF_MULTITONE_EN	0	channel filter multi-tone testing
6	DIG_TEST_SEL	0	selects digital test signals to be used in conjunction with the P11C[3:0] and P12C[3:0] settings, see Section 8.2.1.7 on page 96 and Section 8.2.1.8 on page 97
5		0	
4		0	
3	RXD_DBG_SEL	0	selects digital test signals
2		0	
1		0	
0		0	

8.2.5.2 Register TEST1

Table 122. Register TEST1 - (address 36h) bit description

Bit	Symbol	Value	Description
7	IQ_TEST_LV	0	must be set if IF output signals test buffer is used at supply voltages below 2.0 V
6	ANA_TEST_SEL	0	selects analog test signal
5		0	
4		0	
3	REG_DIG_DIS	0	disables voltage regulator digital section
2	PLL_CTRL	0	test and configures PLL
1		0	
0	VCO_TEST_ON	0	enables VCO test

8.2.5.3 Register TEST2

Table 123. Register TEST2 - (address 37h) bit description

Bit	Symbol	Value	Description
7	REG_VCO_ON	0	enables VCO voltage regulator
6	REG_PLL_ON	0	enables PLL voltage regulator
5	REG_PA_ON	0	enables PA voltage regulator
4	FORCE_REG_VCO_RDY	0	overrides VCO ready signal [1]
3	FORCE_REG_PLL_RDY	0	overrides PLL ready signal [1]
2	FORCE_REG_PA_RDY	0	overrides PA ready signal [1]
1	FORCE_LOCK_DETECT	0	overrides PLL lock detect signal [1]
0	FORCE_XO_RDY	0	overrides XO ready signal [1]

[1] These bits override internal status information and enable automatic sequences to run even if the corresponding status information indicates a failing block.

8.2.5.4 Register TEST3

Table 124. Register TEST3 - (address 38h) bit description

Bit	Symbol	Value	Description
7	VCO_ON	0	enable VCO
6	PRESC_ON	0	enable prescaler
5	PFD_ON	0	enable PLL phase detector
4	CLK_PLL_ON	0	enable PLL clock
3	TX_ON	0	enable PA (TX section)
2	RX_GAP_ON	0	enable bandgap reference, required for RX mode
1	RX_ON	0	enable receiver
0	PA_STEP_TEST	0	enable PA test mode, to bypass internal step-decoding block

8.2.5.5 Register TEST4

Table 125. Register TEST4 - (address 39h) bit description

Bit	Symbol	Value	Description
7	FORCE_CF_RC_CAL	0	issues an RC auto-calibration on request
6	SKIP_CF_RC_CAL	0	prevents RC auto-calibration
5	CF_RC_ADJUSTCAL	0	enables verification of the channel filter RC auto-calibration accuracy: time-constant reference value is adjusted by this value; see Table 126
4		0	
3	MAN_CF_RC_CALVAL	X	for manual entry of the RC auto-calibration value in CF_RC_CAL_RES[3:0]
2		X	
1		X	
0		X	

Table 126. Time-constant reference settings for RC auto-calibration

CF_RC_ADJUST CAL		R variation (%)
D5	D4	
0	0	0
0	1	+12.5
1	0	-6.2
1	1	-4.1

8.2.5.6 Register TEST5

Table 127. Register TEST5 - (address 3Ah) bit description

Bit	Symbol	Value	Description
7	XO_IOFFS	0	sets programmable offset current for oscillator control loop
6		0	
5		0	
4	XO_IOFFSET_SINK_EN	0	only active if XO_IOFFSET_EN is logic 1. If logic 1, the bias source must sink the offset current otherwise it is sourced
3	XO_IOFFSET_EN	0	enables crystal oscillator offset current: controls a test signal to control the bias current. Must be logic 0 during normal crystal oscillator operation.
2	XO_KICK_DIS	0	disables crystal oscillator start-up kick: controls a test signal to disable the start-up kick after power-on. Must be logic 0 during normal crystal oscillator operation.
1	XO_DET_DIS	0	disables crystal oscillator detector: controls a test signal to disable the detector. Must be logic 0 during normal crystal oscillator operation.
0	XO_BIAS_DIS	0	disables crystal oscillator bias circuit

9. Limiting values

Table 128. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
T_{stg}	storage temperature		-55	+125	°C	
T_j	junction temperature		-	+95	°C	
V_{IO}	input/output voltage	any VCC or I/O pin to GND	-0.3	+3.6	V	
		all other pins to GND	-0.3	+2.8	V	
		RF_OUT pin to GND; RF peak voltage	-0.3	+4.2	V	
I_{IO}	input/output current	maximum DC current for I/O pins	-	4	mA	
$P_{i(max)}$	maximum input power	RX	-	12.9	dBm	
I_{lu}	latch-up current		[1][2]	100	-	mA
V_{ESD}	electrostatic discharge voltage	human body model	[3]			
		pins VREG_PA, RF_OUT; peak	1.5	-	kV	
		all other pins; peak	2	-	kV	
		machine model	[3]			
		pins VREG_PA, RF_OUT; peak	100	-	V	
		all other pins; peak	200	-	V	
P_{tot}	total power dissipation		-	120	mW	

- [1] Only applies to pins which are connected to active devices in the application. According to the standard, only relevant for VCC pins and digital I/Os.
- [2] Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in the Operating conditions and Electrical characteristics section of this specification is not implied.
- [3] This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maximum.

10. Static characteristics

Table 129. Static characteristics

$T_{amb} = -25\text{ °C to }+85\text{ °C}$, $V_{CC_xxx} = 2.7\text{ V}$, $GND_xxx = 0\text{ V}$; capacitors of 22 nF // 270 pF connected between V_{REG_PLL} and GND_PLL , V_{REG_VCO} and GND_VCO . Capacitor of 47 nF // 270 pF connected between V_{REG_PA} and GND_PA and V_{REG_DIG} and GND_DIG quartz crystal NDK NX5032SA with $C_L = 12\text{ pF}$, unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Current consumption						
V_{CC}	supply voltage		2.1	2.7	3.6	V
T_{amb}	ambient temperature		-25	+25	+85	°C

Table 129. Static characteristics ...continued

$T_{amb} = -25\text{ °C}$ to $+85\text{ °C}$, $V_{CC_xxx} = 2.7\text{ V}$, $GND_xxx = 0\text{ V}$; capacitors of $22\text{ nF} // 270\text{ pF}$ connected between V_{REG_PLL} and GND_PLL , V_{REG_VCO} and GND_VCO . Capacitor of $47\text{ nF} // 270\text{ pF}$ connected between V_{REG_PA} and GND_PA and V_{REG_DIG} and GND_DIG quartz crystal NDK NX5032SA with $C_L = 12\text{ pF}$, unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{CC}	supply current	power-down mode				
		+25 °C	-	0.5	1.6	μA
		+85 °C	-	5	-	μA
$I_{CC(LO)}$	local oscillator supply current	crystal oscillator on, digital module active; PLL and PA off	-	900	1200	μA
		315 MHz/434 MHz/868 MHz band; LO and PLL on; PA off	-	5	7	mA
$I_{CC(RX)}$	receiver supply current	315 MHz/434 MHz/868 MHz band				
		+25 °C	15.5	16.5	18	mA
		-25 °C to +85 °C	13.5	16.5	21.5	mA
$I_{CC(TX)}$	transmitter supply current	315 MHz/434 MHz/868 MHz band; PA matching dependent				
		10 dBm output power	-	22	25	mA
		6 dBm output power	-	14	17	mA

Digital I/Os

V_{IH}	HIGH-level input voltage	$V_{CC} = 2.1\text{ V}$ to 3.6 V	$0.8V_{CC}$	-	V_{CC}	V
V_{IL}	LOW-level input voltage	$V_{CC} = 2.1\text{ V}$ to 3.6 V	0	-	0.4	V
I_{IH}	HIGH-level input current		-1	-	+1	μA
I_{IL}	LOW-level input current		-1	-	+1	μA
V_{OH}	HIGH-level output voltage	SPI pins (SCLK, SDIO and SDO); $V_{CC} = 2.1\text{ V}$ to 3.6 V	$0.7V_{CC}$	-	V_{CC}	V
		$V_{CC} = 2.1\text{ V}$ to 3.6 V	$0.8V_{CC}$	-	V_{CC}	V
V_{OL}	LOW-level output voltage	SPI pins (SCLK, SDIO and SDO); $V_{CC} = 2.1\text{ V}$ to 3.6 V	0	-	$0.3V_{CC}$	V
		$V_{CC} = 2.1\text{ V}$ to 3.6 V	0	-	$0.2V_{CC}$	V
I_{OH}	HIGH-level output current		-1	-	-	mA
I_{OL}	LOW-level output current		1	-	-	mA
f_{io}	input/output frequency	10 pF output load	-	-	4	MHz

[1] Different biasing configurations are available in the receiver to trim performances (mainly sensitivity and linearity) versus power consumption.

11. Dynamic characteristics

Table 130. Dynamic characteristics

$T_{amb} = -25\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$, $V_{CC_xxx} = 2.7\text{ V}$, $GND_xxx = 0\text{ V}$; capacitors of $22\text{ nF} // 270\text{ pF}$ connected between $VREG_PLL$ and GND_PLL , $VREG_VCO$ and GND_VCO ; capacitor of $47\text{ nF} // 270\text{ pF}$ connected between $VREG_PA$ and GND_PA and $VREG_DIG$ and GND_DIG ; quartz crystal NDK NX5032SA with $C_L = 12\text{ pF}$; unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{RF}	RF frequency	315 MHz	300	315	320	MHz
		434 MHz	415	434	450	MHz
		868 MHz	865	868	870	MHz
		915 MHz	902	915	928	MHz
$f_{RF(step)}$	RF frequency step	315 MHz	-	150	-	Hz
		434 MHz	-	200	-	Hz
		868 MHz	-	400	-	Hz
		915 MHz	-	415	-	Hz

Modulation

f_{chip}	chip rate	Manchester (or NRZ) encoding	0.4	-	112	kchip/s
$f_{chip(step)}$	chip rate step		-	0.1	-	kchip/s
Δf_{FSK}	FSK frequency deviation		[1]	-	249	kHz
Δf_{step}	step frequency deviation		[2]	3	6	%
$\Delta P_{o(ASK)}$	ASK output power difference	constant PAM; difference between (ACON0[4:0] = 0 to 31)	25	40	-	dB

Reference crystal oscillator

f_{xtal}	crystal frequency		15.95	16	16.05	MHz
$t_{startup(xtal)}$	crystal start-up time		[3]	-	1	ms
$C_{drv(xtal)}$	crystal driver capacitance	driver	-	1	-	pF
$R_{s(xtal)}$	crystal series resistance	$-10\text{ }^{\circ}\text{C}$ to $+65\text{ }^{\circ}\text{C}$; 2.1 V minimum; quartz crystal NDK NX5032SA; $C_L = 12\text{ pF}$	-	-	700	Ω
$V_{i(clk)}$	clock input voltage	external clock applied to pin XTAL2	[4]			
		clock HIGH	-	1.8	-	V
		clock LOW	-	0	-	V

PLL

$B_{PLL(loop)}$	PLL loop bandwidth	-3 dB closed loop at 868 MHz	[5]	-	150	kHz	
$t_{cal(VCO)}$	VCO calibration time	auto-calibration	[6]	-	110	μs	
$t_{lock(PLL)}$	PLL lock time		[6]	-	120	200	μs

TX power amplifier

Table 130. Dynamic characteristics ...continued

$T_{amb} = -25\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$, $V_{CC_xxx} = 2.7\text{ V}$, $GND_xxx = 0\text{ V}$; capacitors of $22\text{ nF} // 270\text{ pF}$ connected between $VREG_PLL$ and GND_PLL , $VREG_VCO$ and GND_VCO ; capacitor of $47\text{ nF} // 270\text{ pF}$ connected between $VREG_PA$ and GND_PA and $VREG_DIG$ and GND_DIG ; quartz crystal NDK NX5032SA with $C_L = 12\text{ pF}$; unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$P_{o(max)}$	maximum output power	at TX output; nominal power mode	[7] 10	11	-	dBm
$P_{o(min)}$	minimum output power	at TX output; low power mode	-	-	-15	dBm
ΔP_o	output power variation	at constant power-setting over temperature and supply voltage	-	± 1	-	dB
$N_{step(P_o)}$	number of output power steps		-	30	-	
C_o	output capacitance		-	0.7	-	pF
$t_{s(vreg)}$	voltage regulator settling time		-	3	10	μs
$t_{startup(PLL)TX}$	transmitter PLL start-up time	from PLL start-up to TX ready	-	200	300	μs
$P_{sp(TX)}$	transmitter spurious power	device operating in TX; modulation off (conducted measurements, standard matching circuit (LC, class E))	[8]			
		47 MHz to 230 MHz or 470 MHz to 862 MHz	-	-	-54	dBm
		below 1 GHz	-	-	-36	dBm
		above 1 GHz	-	-	-30	dBm
φ_n	phase noise	at TX output; ICP setting = 2; 434 MHz/868 MHz				
		50 kHz	-	-	-92/-86	dBc/Hz
		100 kHz	-	-	-92/-86	dBc/Hz
		1 MHz	-	-	-113/-107	dBc/Hz
		2 MHz	-	-	-121/-115	dBc/Hz
		5 MHz	-	-	-131/-125	dBc/Hz
		10 MHz	-	-	-134/-130	dBc/Hz

Receiver section

$ Z_i $	input impedance	at 868 MHz	[9] -	66 to j94	-	Ω
		at 434 MHz	[9] -	125 to j139	-	Ω
		at 315 MHz	[9] -	157 to j138	-	Ω
B	bandwidth	channel filter	[10] 50	-	300	kHz
$t_{startup(PLL)RX}$	receiver PLL start-up time	from PLL start-up to RX ready	[6] -	250	350	μs

Table 130. Dynamic characteristics ...continued

$T_{amb} = -25\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$, $V_{CC_xxx} = 2.7\text{ V}$, $GND_xxx = 0\text{ V}$; capacitors of $22\text{ nF} // 270\text{ pF}$ connected between $VREG_PLL$ and GND_PLL , $VREG_VCO$ and GND_VCO ; capacitor of $47\text{ nF} // 270\text{ pF}$ connected between $VREG_PA$ and GND_PA and $VREG_DIG$ and GND_DIG ; quartz crystal NDK NX5032SA with $C_L = 12\text{ pF}$; unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
NF	noise figure	cascaded; maximum front-end gain	-	7	-	dB

Table 130. Dynamic characteristics ...continued

$T_{amb} = -25\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$, $V_{CC_xxx} = 2.7\text{ V}$, $GND_xxx = 0\text{ V}$; capacitors of $22\text{ nF} // 270\text{ pF}$ connected between $VREG_PLL$ and GND_PLL , $VREG_VCO$ and GND_VCO ; capacitor of $47\text{ nF} // 270\text{ pF}$ connected between $VREG_PA$ and GND_PA and $VREG_DIG$ and GND_DIG ; quartz crystal NDK NX5032SA with $C_L = 12\text{ pF}$; unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
S _{RX}	receiver sensitivity	BER $\leq 10^{-3}$; E_b/N_0 of 9.8 dB maximum front-end gain				
		Manchester encoded data rate = 2.4 kbit/s; deviation = 2.4 kHz; channel filter B = 50 kHz	-109	-112	-	dBm
		Manchester encoded data rate = 4.8kbit/s; deviation = 4.8 kHz; channel filter B = 50 kHz	-108	-110	-	dBm
		Manchester encoded data rate = 9.6 kbit/s; deviation = 15 kHz; channel filter B = 75 kHz	-106	-109	-	dBm
		Manchester encoded data rate = 20 kbit/s; deviation = 20 kHz; channel filter B = 100 kHz	-103	-105	-	dBm
		Manchester encoded data rate = 2.4 kbit/s; channel filter B = 50 kHz; ASK modulation with 50 % duty cycle square wave; on/off keying; mean output power	-	-118	-	dBm
		Manchester encoded data rate = 4.8 kbit/s; channel filter B = 50 kHz; ASK modulation with 50 % duty-cycle square wave; on/off keying; mean output power	-	-117	-	dBm

Table 130. Dynamic characteristics ...continued

$T_{amb} = -25\text{ °C}$ to $+85\text{ °C}$, $V_{CC_xxx} = 2.7\text{ V}$, $GND_xxx = 0\text{ V}$; capacitors of $22\text{ nF} // 270\text{ pF}$ connected between $VREG_PLL$ and GND_PLL , $VREG_VCO$ and GND_VCO ; capacitor of $47\text{ nF} // 270\text{ pF}$ connected between $VREG_PA$ and GND_PA and $VREG_DIG$ and GND_DIG ; quartz crystal NDK NX5032SA with $C_L = 12\text{ pF}$; unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
α_{ch}	channel rejection	co-channel; using Edge Slicer	-	-11	-	dB
		wanted 3 dB above the sensitivity level, CW jammer, BER $\leq 10^{-2}$				
		channel spacing = channel bandwidth	10	-	-	dB
		≥ 2 channels separation	30	-	-	dB

Table 130. Dynamic characteristics ...continued

$T_{amb} = -25\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$, $V_{CC_xxx} = 2.7\text{ V}$, $GND_xxx = 0\text{ V}$; capacitors of $22\text{ nF} // 270\text{ pF}$ connected between $VREG_PLL$ and GND_PLL , $VREG_VCO$ and GND_VCO ; capacitor of $47\text{ nF} // 270\text{ pF}$ connected between $VREG_PA$ and GND_PA and $VREG_DIG$ and GND_DIG ; quartz crystal NDK NX5032SA with $C_L = 12\text{ pF}$; unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$\alpha_{sup(f)image}$	image frequency suppression		-	30	-	dB
		with calibration, 315 MHz and 434 MHz band with trimming at RT and nominal voltage; FSK modulation; Manchester encode data rate = 2.4 kbit/s channel filter B = 50 kHz	[11] 50	-	-	dB
		with calibration, 315 MHz and 434 MHz band with trimming at RT and nominal voltage; FSK modulation; Manchester encode data rate = 20 kbit/s channel filter B = 300 kHz	45	-	-	dB
		with calibration, 868 MHz band with trimming at RT and nominal voltage; FSK modulation; Manchester encode data rate = 2.4 kbit/s channel filter B = 50 kHz	[11] 45	-	-	dB
		with calibration, 868 MHz band with trimming at RT and nominal voltage; FSK modulation; Manchester encode data rate = 20 kbit/s channel filter B = 300 kHz	40	-	-	dB

Table 130. Dynamic characteristics ...continued

$T_{amb} = -25\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$, $V_{CC_xxx} = 2.7\text{ V}$, $GND_xxx = 0\text{ V}$; capacitors of $22\text{ nF} // 270\text{ pF}$ connected between $VREG_PLL$ and GND_PLL , $VREG_VCO$ and GND_VCO ; capacitor of $47\text{ nF} // 270\text{ pF}$ connected between $VREG_PA$ and GND_PA and $VREG_DIG$ and GND_DIG ; quartz crystal NDK NX5032SA with $C_L = 12\text{ pF}$; unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$\alpha_{ch(image)}$	image channel rejection	wanted 3 dB above the sensitivity level; CW jammer at image frequency; BER $\leq 10^{-2}$; calibration with external RF signal, FSK modulation	[11] -	22	-	dB
		315 MHz and 434 MHz; Manchester encoded data rate = 2.4 kbit/s; channel filter B = 50 kHz	[11] 40	-	-	dB
		315 MHz and 434 MHz; Manchester encoded data rate = 20 kbit/s; channel filter B = 300 kHz	[11] 30	-	-	dB
		868 MHz; Manchester encoded data rate = 2.4 kbit/s; channel filter B = 50 kHz	[11] 30	-	-	dB
		868 MHz; Manchester encoded data rate = 20 kbit/s; channel filter B = 300 kHz	[11] 25	-	-	dB
α_{oob}	out-of-band rejection	blocking signal				
		$\pm 1\text{ MHz}$ from edge band	40	-	-	dB
		$\pm 2\text{ MHz}$ from edge band	50	-	-	dB
		$\pm 5\text{ MHz}$ from edge band	60	-	-	dB
		$\pm 10\text{ MHz}$ from edge band	60	-	-	dB
ICP_{1dB}	1 dB input compression point	to mixer output; front-end maximum gain	-	-36	-	dBm

Table 130. Dynamic characteristics ...continued

$T_{amb} = -25\text{ °C}$ to $+85\text{ °C}$, $V_{CC_xxx} = 2.7\text{ V}$, $GND_xxx = 0\text{ V}$; capacitors of $22\text{ nF} // 270\text{ pF}$ connected between $VREG_PLL$ and GND_PLL , $VREG_VCO$ and GND_VCO ; capacitor of $47\text{ nF} // 270\text{ pF}$ connected between $VREG_PA$ and GND_PA and $VREG_DIG$ and GND_DIG ; quartz crystal NDK NX5032SA with $C_L = 12\text{ pF}$; unless otherwise specified. The Edge Slicer was used for all relevant measurements.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
IP3	third-order intercept point	+5 MHz and 10 MHz; to mixer output; front-end maximum gain	-	-23	-	dBm	
$P_{L(lo)}$	local oscillator leakage power	at RX input; LO > 1 GHz	-	-	-47	dBm	
$P_{sp(RX)}$	receiver spurious power	emission in RX mode					
		9 kHz to 1 GHz	-	-	-57	dBm	
		1 GHz to 4 GHz	-	-	-47	dBm	
RSSI							
$RSSI_{range(dyn)}$	received signal strength indicator dynamic range		-	80	-	dB	
$RSSI_{acc(abs)}$	absolute accuracy of received signal strength indicator	input power variation (in range of -90 dBm) to achieve nominal digital code of 89 LSB for any device under any condition	[11]	-	± 12	-	dB
$\Delta RSSI$	received signal strength indicator variation	input power variation (in range of -90 dBm) for one device over supply and temperature	[11]	-	± 3	-	dB
G_{RSSI}	RSSI gain		0.4	-	0.9	dB/LSB	
$RSSI_{min}$	minimum received signal strength indicator	linked to reference sensitivity	-	-110	-100	dBm	

[1] Minimum frequency deviation is the resolution of the LO (dependent on application settings); crystal/band dependent.

[2] Detailed information is given in [Section 7.20.1 on page 42](#).

[3] Start-up time includes XOSTARUPDELAY = 256 μ s.

[4] Only for test purposes, and not to be used in the application.

[5] On-chip loop filter: ICP value = 2.

[6] Guaranteed by design.

[7] Using a SAW filter in the TX path with this device may produce undesired operation.

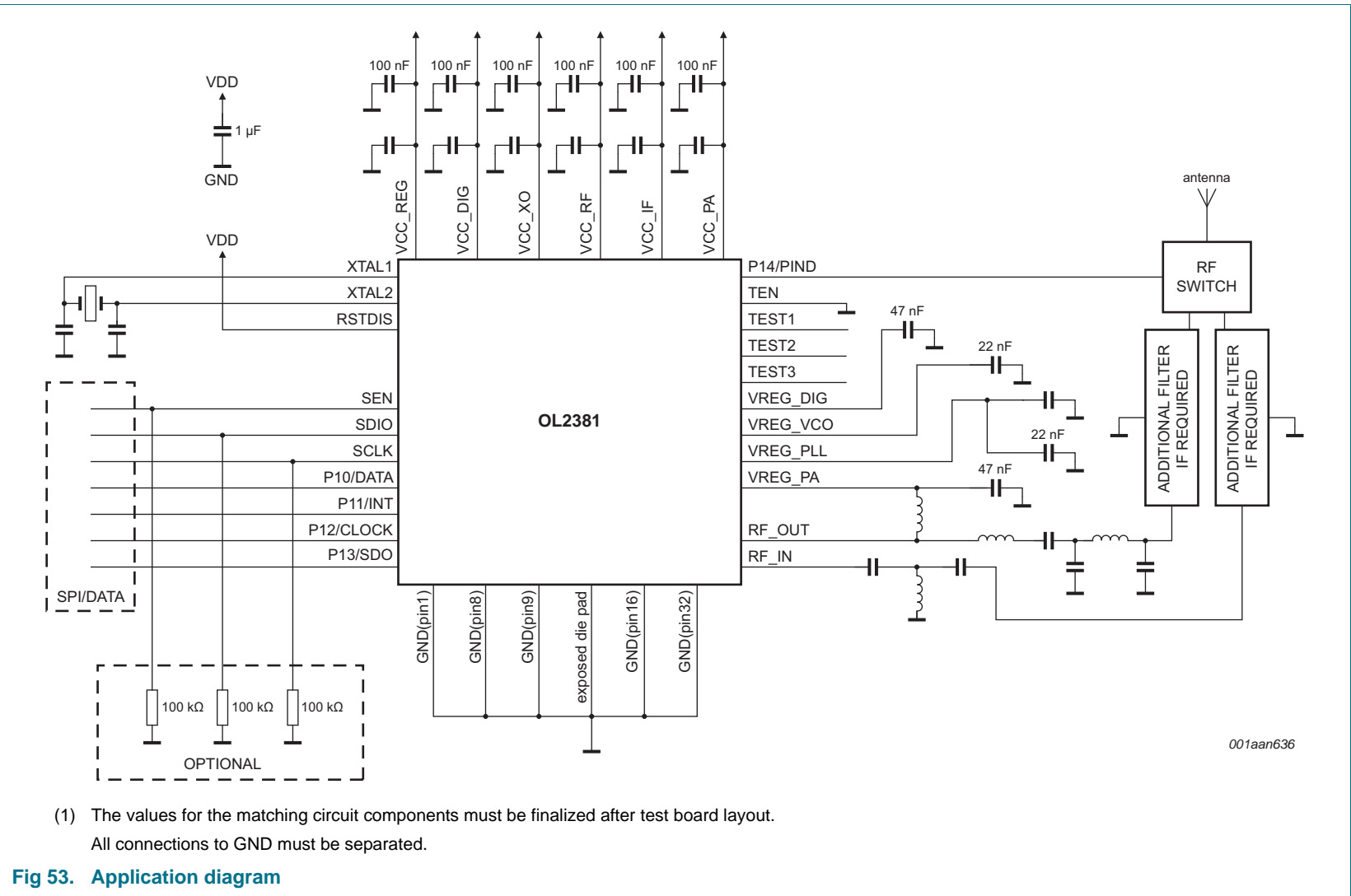
[8] Tested at 315 MHz, 434 MHz and 868 MHz at an output power limit of 5 dBm.

[9] Input resistance in series with reactance in high gain mode. These values are indicative, determine input impedance on an application basis, and refer to the application note.

[10] There are six bandwidth settings for 50 kHz, 75 kHz, 100 kHz, 150 kHz, 200 kHz and 300 kHz.

[11] Values derived from characterization result.

12. Application information



13. Package outline

HVQFN32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 5 x 5 x 0.85 mm

SOT617-3

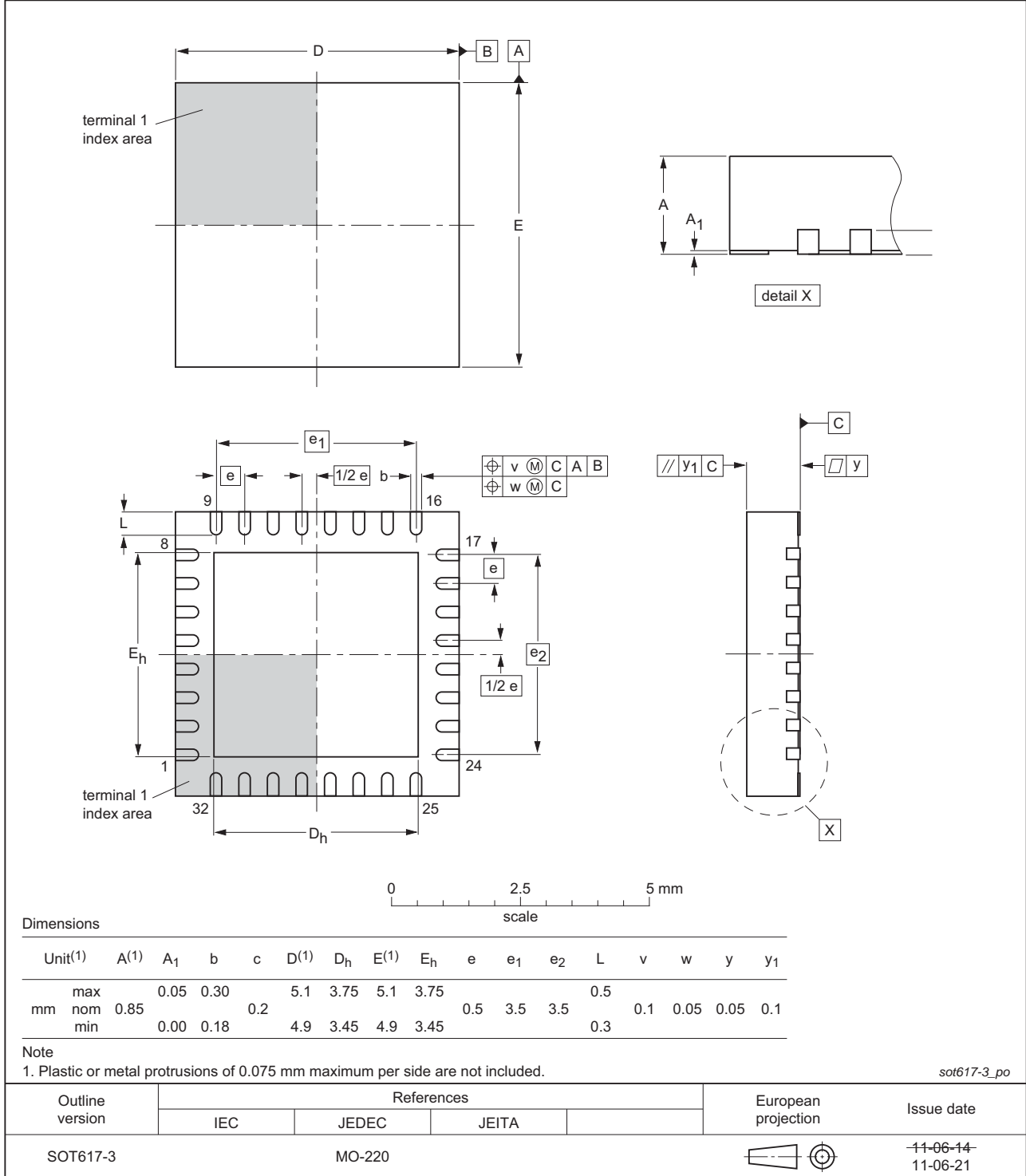


Fig 54. Package outline SOT617-3 (HVQFN32)

14. Abbreviations

Table 131. Abbreviations

Acronym	Description
AM	Amplitude Modulation
ASK	Amplitude-Shift Keying
ADC	Analog-to-Digital Converter
BER	Bit Error Rate
CW	Continuous Wave
DAC	Digital-to-Analog Converter
EOF	End Of File
FM	Frequency Modulation
FRMP	FSK RaMP
FSK	Frequency Shift Keying
GFSK	Gaussian Frequency Shift Keying
ICP	Input Compression Point
IF	Intermediate Frequency
ISM	Industrial, Scientific and Medical
LC	inductor Capacitor
LNA	Low-Noise Amplifier
LO	Local Oscillator
LSB	Least Significant Bit
MISO	Master In Slave Out
MOSI	Master Out Slave In
MSB	Most Significant Bit
NRZ	Not Return to Zero
OSR	OverSampling Ratio
PA	Power Amplifier
PAM	Power Amplifier Mode
PFD	Phase Frequency Detector
PLL	Phase-Locked Loop
POR	Power-On Reset
PRDA	PRreamble detection followed by DAta reception
PREA	PREAmble
PRNG	Pseudo-Random Number Generator
RC	Resistor Capacitor
RF	Radio Frequency
RFU	Reserved for Future Use
RSSI	Residual Signal Strength Indicator
RT	Room Temperature
RX	Receiver
SAW	Surface Acoustic Wave
SFR	Special Function Register

Table 131. Abbreviations ...continued

Acronym	Description
SPI	Serial Peripheral Interface
SRD	Short-Range Device
TX	Transmitter
VCO	Voltage-Controlled Oscillator
WUP	Wake UP
WUPS	Wake UP Search
XO	Crystal Oscillator

15. Revision history

Table 132. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
OL2381 v.1	20111130	Product data sheet	-	-

16. Legal information

16.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

16.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

Product specification — The information and data provided in a Product data sheet shall define the specification of the product as agreed between NXP Semiconductors and its customer, unless NXP Semiconductors and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the NXP Semiconductors product is deemed to offer functions and qualities beyond those described in the Product data sheet.

16.3 Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or

malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

NXP Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

Terms and conditions of commercial sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nxp.com/profile/terms>, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NXP Semiconductors hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of NXP Semiconductors products by customer.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Quick reference data — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

Non-automotive qualified products — Unless this data sheet expressly states that this specific NXP Semiconductors product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. NXP Semiconductors accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without NXP Semiconductors' warranty of the

product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond NXP Semiconductors' specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies NXP Semiconductors for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond NXP Semiconductors' standard warranty and NXP Semiconductors' product specifications.

16.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

17. Contact information

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

18. Tables

Table 1. Ordering information	2	(address 10h) bit description	96
Table 2. Pin description	4	Table 36. P10C port control data functions	96
Table 3. Blocks with regulated supplies	19	Table 37. P11C port control data functions	96
Table 4. TX command bits	35	Table 38. Test signal I	97
Table 5. TX command packet	36	Table 39. Test signal II	97
Table 6. Control of TX data (bits TC, TE)	36	Table 40. Port control register PORTCON1 - (address 11h) bit description	97
Table 7. Power amplifier control and synchronization (bits TC, TD)	36	Table 41. P12C port control data functions	98
Table 8. Summary of combined TC, TD and TE bits	36	Table 42. Test signal III	98
Table 9. Amplitude selection (bit TF)	36	Table 43. Test signal IIII	98
Table 10. Frequency band selection (bits TA, TB)	37	Table 44. P13C port control data functions	99
Table 11. Phase 1: data transmission	38	Table 45. Port control register PORTCON2 - (address 12h) bit description	99
Table 12. Phase 2: end data transmission	38	Table 46. SEP_RX_OUT data functions	99
Table 13. Channel filter gain settings	49	Table 47. SEP_TX_LINES data functions	100
Table 14. RX gain control	49	Table 48. P14C port control data functions	100
Table 15. Receive command packet	55	Table 49. General power mode register PWRMODE - (address 13h) bit description	100
Table 16. Frequency selection (bits RA, RB)	56	Table 50. POLLTIM_EN data functions	100
Table 17. Sub-command selection bits RC, RD	56	Table 51. Polling timer status after master reset	101
Table 18. Gain switch selection (bits RE, RF)	57	Table 52. DEV_MODE[1:0] device mode control functions	101
Table 19. RXDCON registers	60	Table 53. Interrupt enable register IEN - (address 14h) bit description	101
Table 20. RX operating mode transitions	61	Table 54. Interrupt flag register IFLAG - (address 15h) bit description	102
Table 21. Overview of the signal signature recognition unit	62	Table 55. Polling timer control register POLLWUPTIME - (address 16h) bit description	102
Table 22. Overview of signal monitoring methods	77	Table 56. Polling action register POLLACTION - (address 17h) bit description	102
Table 23. Example 1: Using single byte reads	79	Table 57. POLL_MODE[1:0] device mode control functions	103
Table 24. Example 2: Using read command auto-increment address	80	Table 58. Clock connection register CLOCKCON - (address 18h) bit description	103
Table 25. FM demodulator configurations	83	Table 59. EXTPOLLTIMRNG bit functions	103
Table 26. BASEBAND_FILTER_FC definition	85	Table 60. CLKSOURCESEL bit functions	103
Table 27. Available RX debug signal vectors	86	Table 61. EXT_CLK_BUF_EN / XODIS bit functions	104
Table 28. Register map table	89	Table 62. Device status register DEVSTATUS - (address 19h) bit description	104
Table 29. Frequency control register FC0L - (address 00h) bit description	93	Table 63. FSK frequency deviation register FDEV - (address 1Ah) bit description	104
Table 30. Frequency control register FC0M - (address 01h) bit description	93	Table 64. FSK ramp adjustment register FRMP - (address 1Bh) bit description	105
Table 31. Frequency control register FC0H - (address 02h) bit description	93	Table 65. Register ACON0 - (address 1Ch) bit description	105
Table 32. VCO control register VCOCON - (address 0Ch) bit description	94	Table 66. Register ACON1 - (address 1Dh)	
Table 33. Local oscillator control register LOCON - (address 0Dh) bit description	95		
Table 34. Timing register TIMING1 - (address 0Fh) bit description	95		
Table 35. Port control register PORTCON0 -			

continued >>

bit description	105	Table 97. WUPSTIMEOUTPRESC bit functions	116
Table 67. Register ACON2 - (address 1Eh) bit description	106	Table 98. Register TIMINGCHK - (address 34h) bit description	117
Table 68. Register ARMP - (address 1Fh) bit description	106	Table 99. BROBSLENGTH bit functions	117
Table 69. Transmitter control register TXCON - (address 20h) bit description	107	Table 100. SUMBITTMGERRTH bit functions	117
Table 70. RX frequency offset	107	Table 101. SGLBITTMGERRTH bit functions	117
Table 71. Clock output selection for the TX command, TXCLKOUTSEL	107	Table 102. Receive mode control register RXCON - (address 35h) bit description	118
Table 72. PAM definition	107	Table 103. CLOCK_RECOV_TC bit functions	118
Table 73. Receiver gain control register RXGAIN - (address 21h) bit description	108	Table 104. Receive mode follow-up control register RXFOLLOWUP - (address 36h) bit description	119
Table 74. Channel filter bandwidth and RSSI filter settings register RXBW - (address 22h) bit description	108	Table 105. Status register SIGMONSTATUS - (address 37h) bit description	121
Table 75. CF_BW bit functions	108	Table 106. Status register SIGMONERROR - (address 38h) bit description	121
Table 76. Register GAINSTEP - (address 23h) bit description	109	Table 107. Signal monitor states set by registers SIGMONSTATUS and SIGMONERROR	121
Table 77. Register HIGAINLIM - (address 24h) bit description	109	Table 108. Register RSSI - (address 39h) bit description	122
Table 78. Register RXBBCON - (address 27h) bit description	109	Table 109. Preamble detection control register PREACON - (address 3Ah) bit description	122
Table 79. DEGLITCHER_WINDOW_LEN bit functions	110	Table 110. PREA_TOL bit functions	122
Table 80. Register UMODAMPTH - (address 28h) bit description	110	Table 111. Register EXTRXSTATUS - (address 2Eh) bit description	123
Table 81. Register EMODAMPTH - (address 2Ah) bit description	111	Table 112. Register CFRCCAL - (address 2Fh) bit description	123
Table 82. Register RXDCON0 - (address 2Bh)	112	Table 113. IQ calibration register CFIQCAL - (address 30h) bit description	123
Table 83. Register RXDCON0 - (address 2Bh) bit description	112	Table 114. Register EXPERT0 - (address 31h) bit description	124
Table 84. SLICERSEL_W bit functions	112	Table 115. Register EXPERT1 - (address 32h) bit description	124
Table 85. SLICERINITSEL_W bit functions	112	Table 116. XOSTARTUPDELAY bit functions	124
Table 86. INIT_ACQ_BITS_x bit functions	113	Table 117. Register EXPERT2 - (address 33h) bit description	125
Table 87. Dynamic RX mode control register RXDCON1 - (address 2Ch) bit description	113	Table 118. FM demodulator configurations	125
Table 88. Dynamic RX mode control register RXDCON2 - (address 2Dh) bit description	113	Table 119. CAPRSSI bit functions	125
Table 89. CODINGRESTR_W bit function	114	Table 120. Register EXPERT3 - (address 34h) bit description	126
Table 90. Signal monitoring registers SIGMON0, SIGMON1 and SIGMON2	114	Table 121. Register TEST0 - (address 35h) bit description	126
Table 91. Signal monitoring control register SIGMON0 - (address 2Eh) bit description	114	Table 122. Register TEST1 - (address 36h) bit description	127
Table 92. WUPSMODE bit functions	115	Table 123. Register TEST2 - (address 37h) bit description	127
Table 93. SIGMON_EN_W bit functions	115	Table 124. Register TEST3 - (address 38h) bit description	127
Table 94. Signal monitoring control register SIGMON1 - (address 2Fh) bit description	115	Table 125. Register TEST4 - (address 39h) bit description	128
Table 95. Signal monitoring control register SIGMON2 - (address 30h) bit description	116	Table 126. Time-constant reference settings for RC	
Table 96. Wakeup search timeout control register WUPSTO - (address 31h) bit description	116		

continued >>

auto-calibration	128
Table 127. Register TEST5 - (address 3Ah)	
bit description	128
Table 128. Limiting values	129
Table 129. Static characteristics	129
Table 130. Dynamic characteristics	131
Table 131. Abbreviations	141
Table 132. Revision history	143

19. Figures

Fig 1.	Block diagram	3	Fig 43.	Code checker state diagram	74
Fig 2.	Pin configuration	4	Fig 44.	Wakeup search timeout timer schematic	76
Fig 3.	TX block diagram	7	Fig 45.	Creation of PASS/FAIL information from one signal monitor	78
Fig 4.	RX block diagram	8	Fig 46.	Block diagram of wakeup search	78
Fig 5.	Minimum port connections for TX and RX mode	10	Fig 47.	Wakeup search registers	79
Fig 6.	Full port connections between host controller and the OL2381	10	Fig 48.	XOR FM demodulator	82
Fig 7.	Write serial interface timing diagram	13	Fig 49.	Baseband filter signal flow	83
Fig 8.	Read serial interface timing diagram	13	Fig 50.	Step response of the baseband filter	84
Fig 9.	Read serial interface timing diagram (SEP_SDO = 1)	14	Fig 51.	Frequency response of the baseband filter	84
Fig 10.	Write serial interface auto-increment timing diagram	15	Fig 52.	Data transmission on the RX digital debug interface	85
Fig 11.	Read serial interface auto-increment timing diagram (SEP_SDO = 0)	15	Fig 53.	Application diagram	139
Fig 12.	Simplified state diagram	17	Fig 54.	Package outline SOT617-3 (HVQFN32)	140
Fig 13.	Crystal oscillator circuit	21			
Fig 14.	Diagram for crystal oscillator with clock selection circuitry	23			
Fig 15.	Polling timer block diagram	26			
Fig 16.	Baud-rate generator	28			
Fig 17.	PLL block diagram	29			
Fig 18.	Computing the frequency divider control word	31			
Fig 19.	TX data timing diagram (SEP_TX_LINES = 0)	37			
Fig 20.	TX data timing diagram (SEP_TX_LINES = 1)	38			
Fig 21.	TX data example	39			
Fig 22.	Power amplifier control	40			
Fig 23.	ASK modulation timing	41			
Fig 24.	Soft FSK parameters	44			
Fig 25.	RX signal diagram	46			
Fig 26.	Simulation examples for I/Q calibration with different channel filter bandwidth settings	49			
Fig 27.	20 dB difference between Hi-gain and Lo-gain setting	50			
Fig 28.	40 dB difference between Hi-gain and Lo-gain setting	51			
Fig 29.	Signal level plan	52			
Fig 30.	Block diagram of RSSI	53			
Fig 31.	Preparation for RX mode	55			
Fig 32.	Example of a RX command (SEP_SDO = 0, SEP_RX_OUT = 0)	58			
Fig 33.	Example of a RX command (SEP_SDO = 0, SEP_RX_OUT = 1)	59			
Fig 34.	RSSI wakeup recognition	63			
Fig 35.	RSSI threshold	63			
Fig 36.	Block diagram of the modulation amplitude classification	64			
Fig 37.	Modulation amplitude measurement of a Manchester coded signal	64			
Fig 38.	Modulation amplitude measurement (zoomed)	65			
Fig 39.	Slicer block diagram	67			
Fig 40.	Working principle of the edge slicer	67			
Fig 41.	Block schematic of chip timing verification block	72			
Fig 42.	State diagram of chip timing verification block	73			

20. Contents

1	General description	1	7.7.6	Write access to SFR with auto-increment function	15
2	Features and benefits	1	7.7.7	Read access to SFR with auto-increment function	15
3	Applications	2	7.8	Device mode description	16
4	Ordering information	2	7.8.1	Automatic start-up procedures	16
5	Block diagram	3	7.8.2	General description	16
6	Pinning information	4	7.8.3	Reset and power mode register	16
6.1	Pinning	4	7.8.3.1	First power-on reset	16
6.2	Pin description	4	7.8.3.2	Power-down	16
7	Functional description	5	7.8.3.3	Device mode states	16
7.1	General architecture description	5	7.8.4	Flow description	17
7.1.1	Power management	6	7.8.4.1	Digital regulator start-up	17
7.1.2	XTAL oscillator	6	7.8.4.2	XTAL oscillator start-up	18
7.1.3	Polling timer	6	7.8.4.3	PLL start-up	18
7.1.4	TX block	6	7.8.4.4	Turn on VCO	18
7.1.5	VCO calibration	7	7.8.4.5	Perform VCO calibration	18
7.1.6	TX command	7	7.8.4.6	Preparation for TX mode	18
7.1.7	RX block	8	7.8.4.7	Preparation for RX mode	18
7.1.8	Channel filter auto-calibration	8	7.8.4.8	Perform channel filter calibration	18
7.1.9	I/Q calibration	8	7.8.5	Changing device modes	18
7.1.10	Receive command	9	7.8.6	Interrupts	19
7.1.11	Signal signature recognition unit	9	7.9	Power supply and reset	19
7.1.12	Preamble detection	9	7.9.1	Voltage regulators operation	19
7.2	General operation	9	7.9.2	Digital regulator	19
7.3	Interface description	9	7.9.3	PLL regulator	19
7.3.1	Port connections	9	7.9.4	VCO regulator	20
7.4	Special ports	10	7.9.5	PA regulator	20
7.4.1	TEN	10	7.9.6	Device reset	20
7.4.2	TEST1, TEST2 and TEST3	10	7.10	Main control and timing blocks	20
7.4.3	RSTDIS	10	7.10.1	Crystal oscillator	20
7.5	General purpose ports	10	7.10.1.1	Circuit description	20
7.5.1	P10/DATA	11	7.10.2	Oscillator control and control bits	23
7.5.2	P11 and P12	11	7.11	Watchdog	25
7.5.3	P14	11	7.12	Polling and wakeup timer	26
7.6	Serial configuration interface description	11	7.12.1	Actions at polling timer wakeup	27
7.6.1	General SPI information	11	7.13	RX and TX baud-rate generator	27
7.6.2	SEN	12	7.13.1	Clock recovery for RX mode	29
7.6.3	SCLK	12	7.14	Phase-locked loop	29
7.6.4	SDIO	12	7.14.1	PLL building blocks	29
7.6.5	General SFR access information	12	7.14.2	PLL and VCO regulators	29
7.7	Write and read access to SFR	13	7.14.3	General PLL operation	30
7.7.1	Write access to SFR	13	7.14.4	Charge pump	30
7.7.2	Read access to SFR	13	7.14.5	RF VCO	30
7.7.3	Separation of SDI and SDO line	13	7.14.6	PLL loop bandwidth setting	30
7.7.4	Read access to SFR with separate SDO line	14	7.14.7	Delta-sigma modulator for fractional-N synthesis	30
7.7.5	Read and write access to SFR with auto-increment function	14	7.14.7.1	PLL operating frequency f ₀	31

continued >>

7.14.8	RX frequency offset	34	7.34	Data classification	66
7.14.9	PLL lock detection	35	7.34.1	Data slicer	66
7.15	VCO auto-calibration	35	7.34.1.1	Number of corrupted bits in RX mode	66
7.16	TX operation	35	7.34.1.2	Slicer description	66
7.16.1	TX mode	35	7.34.2	Edge slicer	67
7.16.1.1	Preparation for TX mode	35	7.34.2.1	Edge slicer signal monitor setting	69
7.16.2	TX command	35	7.34.3	Level-sensitive slicer	69
7.16.3	Example of synchronized data transmission	38	7.34.3.1	Level-sensitive slicer initial acquisition	70
7.16.4	Clock output selection for the TX command	39	7.34.4	Deglitcher and edge detector	71
7.17	Power amplifier	40	7.35	Timing classification block	71
7.18	Soft ASK, ramp control	41	7.35.1	Chip timing verification	71
7.19	Power mode control	41	7.35.2	Code checker	73
7.20	PLL frequency deviation (FSK)	42	7.35.3	Baud-rate checker	75
7.20.1	Frequency modulation	42	7.35.4	Timeout timer for the wakeup search	76
7.20.2	Soft FSK	43	7.36	Wakeup search logic	76
7.21	Oscillator and divider settings	44	7.36.1	Sampling the signal monitoring status	79
7.22	Modulation data generation	45	7.36.2	Evaluating the wakeup search result	80
7.23	TX operating mode	45	7.37	Data reception	80
7.23.1	Power-down	45	7.37.1	Preamble detection	80
7.23.2	Idle mode	45	7.38	RX data decoding	81
7.23.3	Active mode	45	7.39	RX clock generation	81
7.23.3.1	PLL active TX mode	46	7.40	RX digital signal processing	82
7.23.4	Baud-rate generation	46	7.40.1	AM demodulator	82
7.23.5	TX mode clock selection	46	7.40.2	FM demodulator	82
7.24	RX operation	46	7.40.3	Baseband filter	83
7.24.1	General operation	47	7.40.3.1	RX baseband configuration	83
7.25	LNA	47	7.41	RX debug interface	85
7.26	Mixer	47	8	Special function registers	88
7.27	Channel filter	47	8.1	Overview	88
7.27.1	Channel filter auto-calibration	48	8.2	Register descriptions	93
7.27.2	Channel I/Q calibration	48	8.2.1	Registers visible in both bank 0 and bank 1	93
7.28	LNA and channel filter gain settings	49	8.2.1.1	Frequency control registers	93
7.29	Limiter	51	8.2.1.2	VCO control register VCOCON	94
7.30	Limiter block filter cut-off frequency	51	8.2.1.3	Local oscillator control register LOCON	95
7.31	RSSI	52	8.2.1.4	Timing register TIMING0	95
7.31.1	Dynamic range and operation	52	8.2.1.5	Timing register TIMING1	95
7.31.2	Resolution	52	8.2.1.6	Port control registers PORTCON0 to PORTCON2	96
7.31.2.1	RSSI low-pass filtering	53	8.2.1.7	Port control register PORTCON0	96
7.31.2.2	RSSI digital filtering	53	8.2.1.8	Port control register PORTCON1	97
7.31.2.3	Low-level signal detection	53	8.2.1.9	Port control register PORTCON2	99
7.31.3	RSSI gain control	53	8.2.1.10	General power mode register PWRMODE	100
7.32	Receive mode	54	8.2.1.11	Interrupt enable register IEN	101
7.32.1	Preparation for RX mode	54	8.2.1.12	Interrupt flag register IFLAG	101
7.32.2	Receive command	55	8.2.1.13	Polling timer control register POLLWUPTIME	102
7.32.2.1	Dynamic receiver configuration	60	8.2.1.14	Polling action register POLLACTION	102
7.33	Signal signature recognition unit	61	8.2.1.15	Clock connection register CLOCKCON	103
7.33.1	RSSI level classification	62	8.2.1.16	Device status register DEVSTATUS	104
7.33.1.1	Functional block diagram	63	8.2.1.17	Register FDEV	104
7.33.2	Modulation amplitude classification	63			
7.33.2.1	Method to determine the modulation amplitude	64			

continued >>

8.2.1.18	FSK ramp adjustment register FRMP	105	8.2.5.4	Register TEST3	127
8.2.1.19	Register ACON0	105	8.2.5.5	Register TEST4	128
8.2.1.20	Register ACON1	105	8.2.5.6	Register TEST5	128
8.2.1.21	Register ACON2	106	9	Limiting values	129
8.2.1.22	Register ARMP	106	10	Static characteristics	129
8.2.1.23	Transmitter control register TXCON	107	11	Dynamic characteristics	131
8.2.1.24	Receiver gain control register RXGAIN	108	12	Application information	139
8.2.1.25	Channel filter bandwidth and RSSI filter settings register RXBW	108	13	Package outline	140
8.2.1.26	Register GAINSTEP	109	14	Abbreviations	141
8.2.1.27	Register HIGAINLIM	109	15	Revision history	143
8.2.1.28	Registers UPPERRSSITH and LOWERSSITH	109	16	Legal information	144
8.2.1.29	Register RXBBCON	109	16.1	Data sheet status	144
8.2.1.30	Register UMODAMPTH	110	16.2	Definitions	144
8.2.1.31	Register LMODAMPTH	111	16.3	Disclaimers	144
8.2.1.32	Register EMODAMPTH	111	16.4	Trademarks	145
8.2.1.33	Register RXDCON0	112	17	Contact information	145
8.2.1.34	Register RXDCON1	113	18	Tables	146
8.2.1.35	Register RXDCON2	113	19	Figures	149
8.2.2	Registers only visible in bank 0	114	20	Contents	150
8.2.2.1	Signal monitoring register SIGMON0	114			
8.2.2.2	Signal monitoring control register SIGMON1	115			
8.2.2.3	Signal monitoring control register SIGMON2	116			
8.2.2.4	Register WUPSTO	116			
8.2.2.5	Register SLICERINITL	116			
8.2.2.6	Register SLICERINITH	116			
8.2.2.7	Register TIMINGCHK	117			
8.2.2.8	Register RXCON	118			
8.2.2.9	Register RXFOLLOWUP	119			
8.2.2.10	Register SIGMONSTATUS	121			
8.2.2.11	Register SIGMONERROR	121			
8.2.2.12	Register RSSILEVEL	122			
8.2.2.13	Register PREACON	122			
8.2.2.14	Register PREA0	122			
8.2.2.15	Register PREA1	122			
8.2.2.16	Register PREA2	122			
8.2.2.17	Register PREA3	123			
8.2.3	Registers only visible in bank 1	123			
8.2.3.1	Register EXTRXSTATUS	123			
8.2.3.2	Register CFRCCAL	123			
8.2.3.3	Register CFIQCAL	123			
8.2.4	Expert registers	124			
8.2.4.1	Register EXPERT0	124			
8.2.4.2	Register EXPERT1	124			
8.2.4.3	Register EXPERT2	125			
8.2.4.4	Register EXPERT3	126			
8.2.5	Test registers	126			
8.2.5.1	Register TEST0	126			
8.2.5.2	Register TEST1	127			
8.2.5.3	Register TEST2	127			

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

© NXP B.V. 2011.

All rights reserved.

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 30 November 2011

Document identifier: OL2381

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[NXP:](#)

[OL2381AHN/C0B,515](#)

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)

Email: org@lifeelectronics.ru